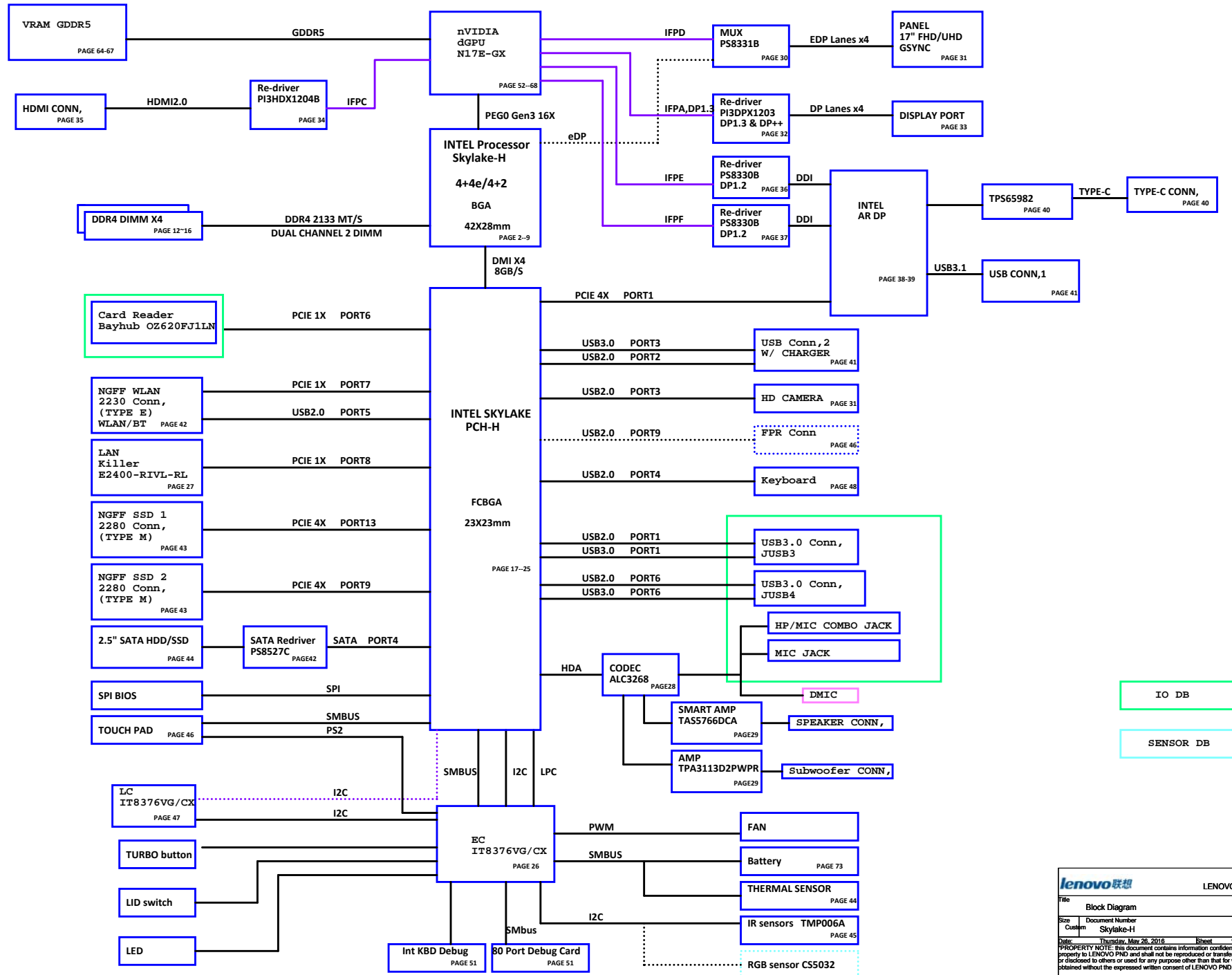


Schematic Block Diagram



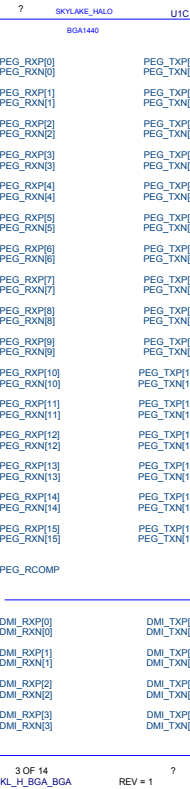
BRD Note:
W=12mils;S=15mils;L<=400mils

dGPU PEG

+VCCIO

18 DMI_IT_MR_0_DP >>> D8 DMI_RXP[0]
18 DMI_IT_MR_0_ON >>> E8 DMI_RXN[0]
18 DMI_IT_MR_1_DP >>> E6 DMI_RXP[1]
18 DMI_IT_MR_1_ON >>> F6 DMI_RXN[1]
18 DMI_IT_MR_2_DP >>> D5 DMI_RXP[2]
18 DMI_IT_MR_2_ON >>> E5 DMI_RXN[2]
18 DMI_IT_MR_3_DP >>> J8 DMI_RXP[3]
18 DMI_IT_MR_3_ON >>> J9 DMI_RXN[3]

PCIE Reversed



PCIE Reversed

B8 DMI_IT_MR_0_DP >>> DMI_TXP[0]
A8 DMI_IT_MR_0_ON >>> DMI_TXN[0]
C6 DMI_IT_MR_1_DP >>> DMI_TXP[1]
B6 DMI_IT_MR_1_ON >>> DMI_TXN[1]
B5 DMI_IT_MR_2_DP >>> DMI_TXP[2]
A5 DMI_IT_MR_2_ON >>> DMI_TXN[2]
D4 DMI_IT_MR_3_DP >>> DMI_TXP[3]
B4 DMI_IT_MR_3_ON >>> DMI_TXN[3]

dGPU PEG

<<>> PEG_PRX_GTX_N[0..15] 52
<<>> PEG_PRX_GTX_P[0..15] 52
<<>> PEG_PTX_C_GRX_N[0..15] 52
<<>> PEG_PTX_C_GRX_P[0..15] 52

lenovo 联想

LENOVO.CRDN

File
PROCESSOR-PEG/DMI

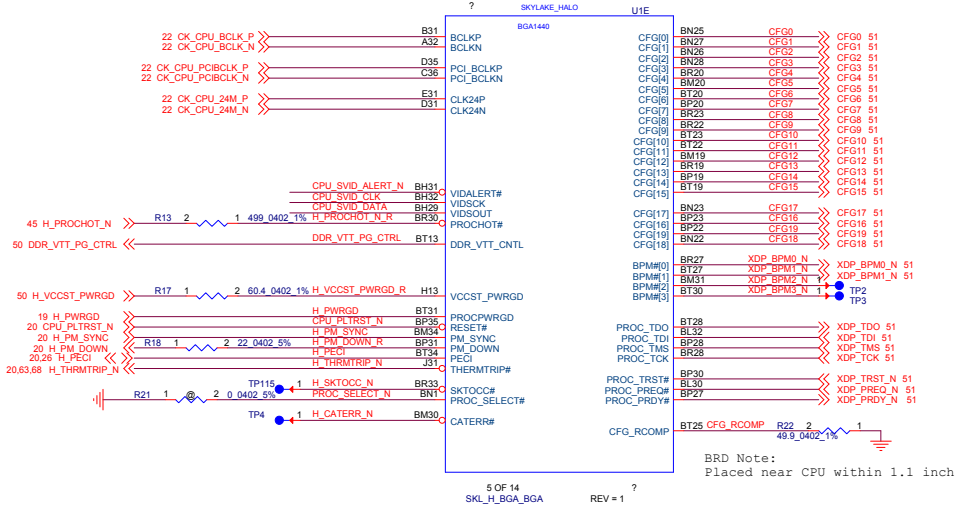
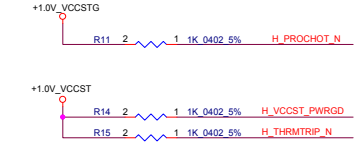
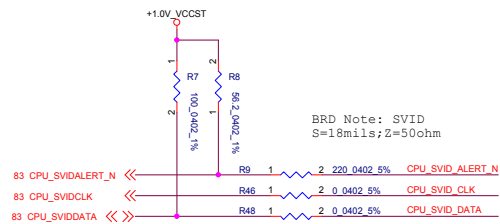
Size
C Document Number
Skylake-H

Rev V0.3

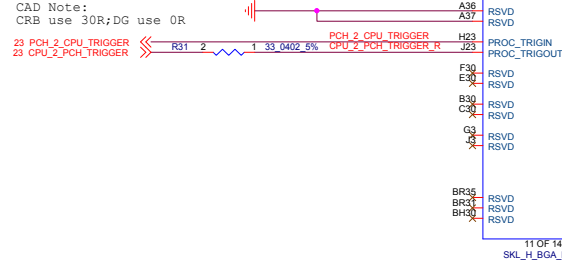
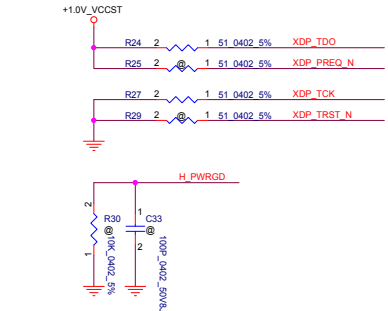
Date: Thursday, May 26, 2016 Sheet 2 of 99

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		SKYLAKE_HALO		U1A	
		BGA1440			
12 M_A_DIM0_CK_DDR0_DP	AG0	DDR0_CK[0]	DDR0_DQ[0]	BR6	M_A_DQ0
12 M_A_DIM0_CK_DDR0_DN	AG2	DDR0_CK[0]	DDR0_DQ[1]	BR6	M_A_DQ1
12 M_A_DIM0_CK_DDR1_DN	AK1	DDR0_CK[1]	DDR0_DQ[2]	BR3	M_A_DQ2
12 M_A_DIM0_CK_DDR1_DP	AK2	DDR0_CK[1]	DDR0_DQ[3]	BR3	M_A_DQ3
12 M_A_DIM1_CK_DDR2_DP	AK3	DDR0_CLKP[2]	DDR0_DQ[4]	BR6	M_A_DQ5
13 M_A_DIM1_CK_DDR2_DN	AL2	DDR0_CLKN[2]	DDR0_DQ[5]	BR2	M_A_DQ5
13 M_A_DIM1_CK_DDR3_DP	ALT	DDR0_CLKP[3]	DDR0_DQ[6]	BR3	M_A_DQ7
13 M_A_DIM1_CK_DDR3_DN	ALT	DDR0_CLKN[3]	DDR0_DQ[7]	BR4	M_A_DQ8
			DDR0_DQ[8]	BR5	M_A_DQ9
12 M_A_DIM0_CKE0	AT1	DDR0_CKE[0]	DDR0_DQ[9]	BR2	M_A_DQ10
12 M_A_DIM0_CKE1	AT2	DDR0_CKE[1]	DDR0_DQ[10]	BR1	M_A_DQ11
13 M_A_DIM1_CKE2	AT3	DDR0_CKE[2]	DDR0_DQ[11]	BR4	M_A_DQ12
13 M_A_DIM1_CKE3	AT5	DDR0_CKE[3]	DDR0_DQ[12]	BR5	M_A_DQ13
			DDR0_DQ[13]	BR1	M_A_DQ14
12 M_A_DIM0_CS0_N	AE3	DDR0_CS[0]	DDR0_DQ[14]	BR2	M_A_DQ15
12 M_A_DIM0_CS1_N	AE2	DDR0_CS[1]	DDR0_DQ[15]	BR4	M_A_DQ16
13 M_A_DIM1_CS2_N	AE3	DDR0_CS[2]	DDR0_DQ[16]	BR5	M_A_DQ17
13 M_A_DIM1_CS3_N	AE3	DDR0_CS[3]	DDR0_DQ[17]	BR5	M_A_DQ18
			DDR0_DQ[18]	BR5	M_A_DQ19
12 M_A_DIM0_ODT0	AD3	DDR0_ODT[0]	DDR0_DQ[19]	BR5	M_A_DQ20
12 M_A_DIM0_ODT1	AE4	DDR0_ODT[1]	DDR0_DQ[20]	BR5	M_A_DQ21
13 M_A_DIM1_ODT2	AD4	DDR0_ODT[2]	DDR0_DQ[21]	BR5	M_A_DQ22
13 M_A_DIM1_ODT3	AD4	DDR0_ODT[3]	DDR0_DQ[22]	BR5	M_A_DQ23
			DDR0_DQ[23]	BR5	M_A_DQ24
12.13 M_A_BA0	AH5	DDR0_BA[0]	DDR0_DQ[24]	BD1	M_A_DQ25
12.13 M_A_BA1	AH1	DDR0_BA[1]	DDR0_DQ[25]	BD1	M_A_DQ26
12.13 M_A_B00	AUT	DDR0_BA[2]	DDR0_DQ[26]	BD5	M_A_DQ27
			DDR0_DQ[27]	BD5	M_A_DQ28
12.13 M_A_A16_RAS_N	AH4	DDR0_RAS#	DDR0_DQ[28]	BD4	M_A_DQ29
12.13 M_A_A14_WE_N	ADT	DDR0_WE#	DDR0_DQ[29]	BD1	M_A_DQ30
12.13 M_A_A15_CAS_N	ADT	DDR0_CAS#	DDR0_DQ[30]	BD2	M_A_DQ31
			DDR0_DQ[31]	AB1	M_A_DQ32
12.13 M_A_A0	AH0	DDR0_MA[0]	DDR0_DQ[32]	AB2	M_A_DQ33
12.13 M_A_A1	AP4	DDR0_MA[1]	DDR0_DQ[33]	AA4	M_A_DQ34
12.13 M_A_A2	AP5	DDR0_MA[2]	DDR0_DQ[34]	AA5	M_A_DQ35
12.13 M_A_A3	AP2	DDR0_MA[3]	DDR0_DQ[35]	AB5	M_A_DQ36
12.13 M_A_A4	AP1	DDR0_MA[4]	DDR0_DQ[36]	AB4	M_A_DQ37
12.13 M_A_A5	AP3	DDR0_MA[5]	DDR0_DQ[37]	AA2	M_A_DQ38
12.13 M_A_A6	AN1	DDR0_MA[6]	DDR0_DQ[38]	AA1	M_A_DQ39
12.13 M_A_A7	AN2	DDR0_MA[7]	DDR0_DQ[39]	V5	M_A_DQ40
12.13 M_A_A8	AN3	DDR0_MA[8]	DDR0_DQ[40]	V2	M_A_DQ41
12.13 M_A_A9	ATA	DDR0_MA[9]	DDR0_DQ[41]	U1	M_A_DQ42
12.13 M_A_A10_AP	AH2	DDR0_MA[10]	DDR0_DQ[42]	U2	M_A_DQ43
12.13 M_A_A11	AN2	DDR0_MA[11]	DDR0_DQ[43]	V4	M_A_DQ44
12.13 M_A_A12	AE5	DDR0_MA[12]	DDR0_DQ[44]	U5	M_A_DQ45
12.13 M_A_A13	AU2	DDR0_MA[13]	DDR0_DQ[45]	U4	M_A_DQ46
12.13 M_A_B01	AU3	DDR0_MA[14]	DDR0_DQ[46]	R2	M_A_DQ47
12.13 M_A_ACT_N	AU3	DDR0_MA[15]	DDR0_DQ[47]	P5	M_A_DQ48
			DDR0_DQ[48]	R4	M_A_DQ49
12.13 DDR0_PARITY	AG3	DDR0_PAR	DDR0_DQ[49]	P4	M_A_DQ50
12.13 DDR0_ALERT_N	ALF	DDR0_ALERT#	DDR0_DQ[50]	R5	M_A_DQ51
			DDR0_DQ[51]	P2	M_A_DQ52
12.13 M_A_DQS_DN0	BR5	DDR0_DQSN[0]	DDR0_DQ[52]	R1	M_A_DQ53
12.13 M_A_DQS_DN1	BR3	DDR0_DQSN[1]	DDR0_DQ[53]	P1	M_A_DQ54
12.13 M_A_DQS_DN2	BR3	DDR0_DQSN[2]	DDR0_DQ[54]	M4	M_A_DQ55
12.13 M_A_DQS_DN3	AB3	DDR0_DQSN[3]	DDR0_DQ[55]	M1	M_A_DQ56
12.13 M_A_DQS_DN4	V5	DDR0_DQSP[4]	DDR0_DQ[56]	L4	M_A_DQ57
12.13 M_A_DQS_DN5	RS	DDR0_DQSP[5]	DDR0_DQ[57]	L2	M_A_DQ58
12.13 M_A_DQS_DN6	M3	DDR0_DQSP[6]	DDR0_DQ[58]	M5	M_A_DQ59
12.13 M_A_DQS_DN7	M3	DDR0_DQSP[7]	DDR0_DQ[59]	M2	M_A_DQ60
			DDR0_DQ[60]	L5	M_A_DQ61
12.13 M_A_DQS_DP0	BPS	DDR0_DQSP[8]	DDR0_DQ[61]	L1	M_A_DQ62
12.13 M_A_DQS_DP1	BK3	DDR0_DQSP[9]	DDR0_DQ[62]		M_A_DQ63
12.13 M_A_DQS_DP2	BFS	DDR0_DQSP[10]	DDR0_DQ[63]		
12.13 M_A_DQS_DP3	BC3	DDR0_DQSP[11]	DDR0_DQ[64]		
12.13 M_A_DQS_DP4	AA3	DDR0_DQSP[12]	DDR0_DQ[65]		
12.13 M_A_DQS_DP5	UB	DDR0_DQSN[4]	DDR0_DQ[66]		
12.13 M_A_DQS_DP6	PS	DDR0_DQSN[5]	DDR0_DQ[67]		
12.13 M_A_DQS_DP7	L3	DDR0_DQSN[6]	DDR0_DQ[68]		
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BRD Note:
Placed within 1.1 inch of CPU pins



PROCESSOR CFG STRAPS

Stall reset sequence after PCU PLL lock until de-asserted

CFG0	1:Normal(Default) *
	0:Stall

PEG16x Static Lane Reversal Strap

CFG2	1:Normal
	0:Reversed(Default) *

Embedded Display Port Presence Strap

CFG4	1:Disable
	0:Enable(Default) *

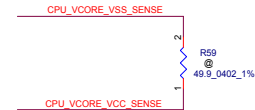
PEG CONFIG Straps

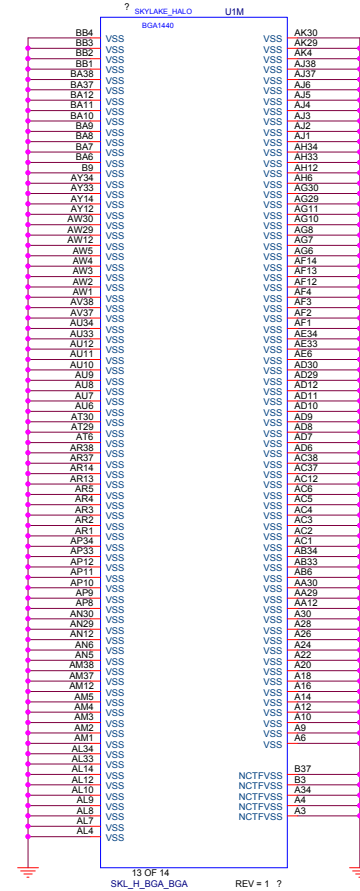
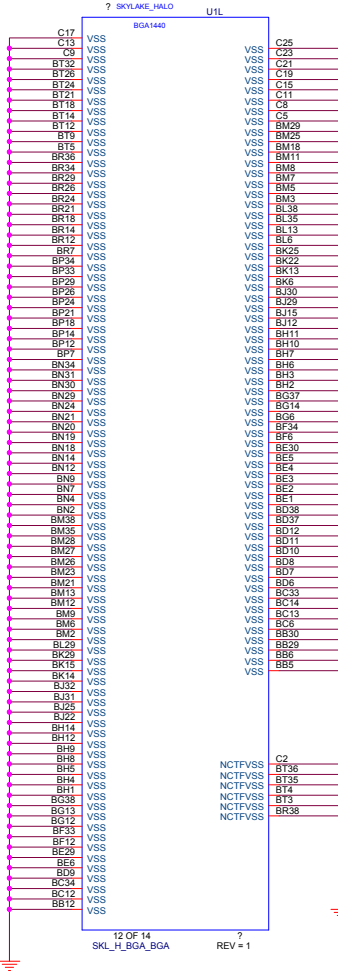
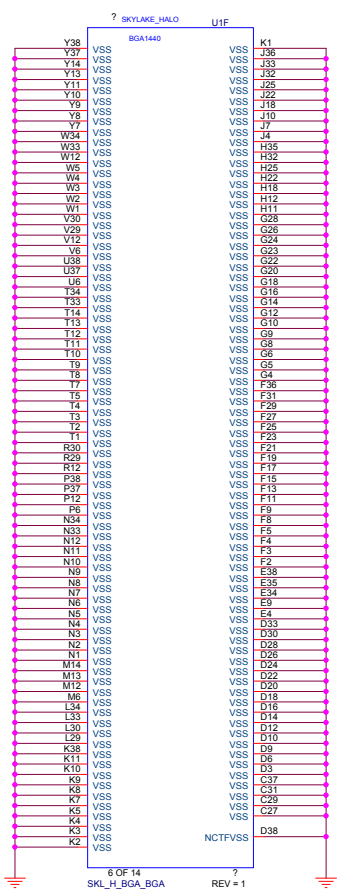
CFG[6:5]	11: x16 (Default) *
	10: x8, x8
	01: Reserved
	00: x8,x4,x4

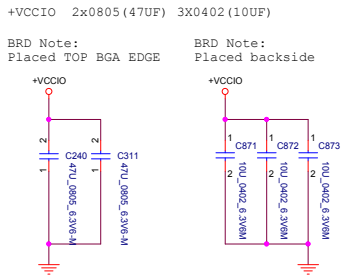
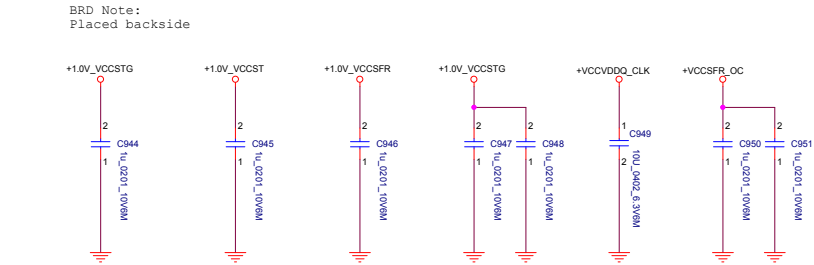
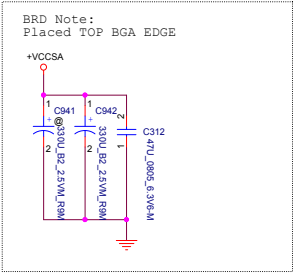
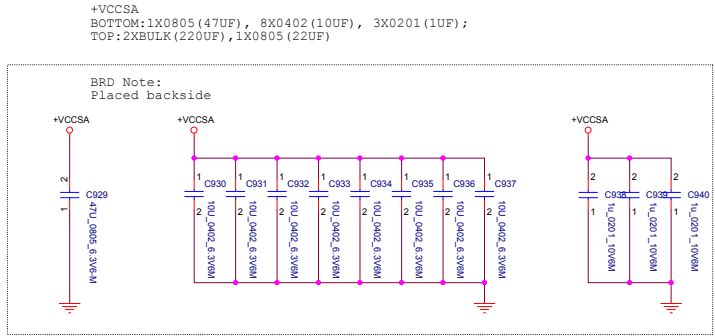
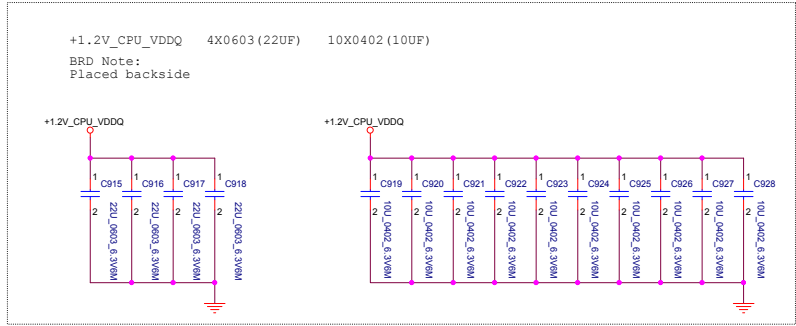
PEG TRAINNING

CFG7	1: follow RESET# deassertion *
	0: Wait for BIOS for training

FOR H4+4e	
	SKYLAKE_HALO U1J
	7
	BGA1442
BJ17	VCCOPC
BJ19	VCCOPC
BJ20	VCCOPC
BK17	VCCOPC
BK19	VCCOPC
BK20	VCCOPC
BL19	VCCOPC
BL17	VCCOPC
BL18	VCCOPC
BL19	VCCOPC
BL20	VCCOPC
BL21	VCCOPC
BM17	VCCOPC
BN17	VCCOPC
BJ23	RSVD
BJ27	RSVD
BK23	RSVD
BK27	RSVD
BL23	RSVD
BL27	RSVD
BL28	RSVD
BL29	RSVD
BL20	RSVD
BL27	RSVD
BL28	RSVD
BL29	RSVD
BM27	RSVD
BL15	VCCOPC_SENSE
BM16	VSSOPC_SENSE
BL22	RSVD
BM22	RSVD
BP15	VCCEOPIO
BR16	VCCEOPIO
BT16	VCCEOPIO
BP16	RSVD
BR16	RSVD
BT16	RSVD
BN15	VCCEOPIO_SENSE
BM16	VSSOPIO_SENSE
BP17	RSVD
BN16	RSVD
BM14	VCC_OPC_1P8
BL14	VCC_OPC_1P8
BJ36	RSVD
BJ38	RSVD
AT13	ZVM#
AW14	MSN#
AU13	ZVM2#
AY13	MSN2#
BT20	OPC_RCOMP
BR25	OPCE_RCOMP
BT25	OPCE_RCOMP2
	10 OF 14
	SKL_H_BGA_BGA
	REV = 1







BRD Note:
Placed TOP BGA EDGE

1 1178 3300 uF 2.5V 10% 2

1 1179 3300 uF 2.5V 10% 2


1 1180 470 uF 6.3V 10% 1

1 1181 470 uF 6.3V 10% 1

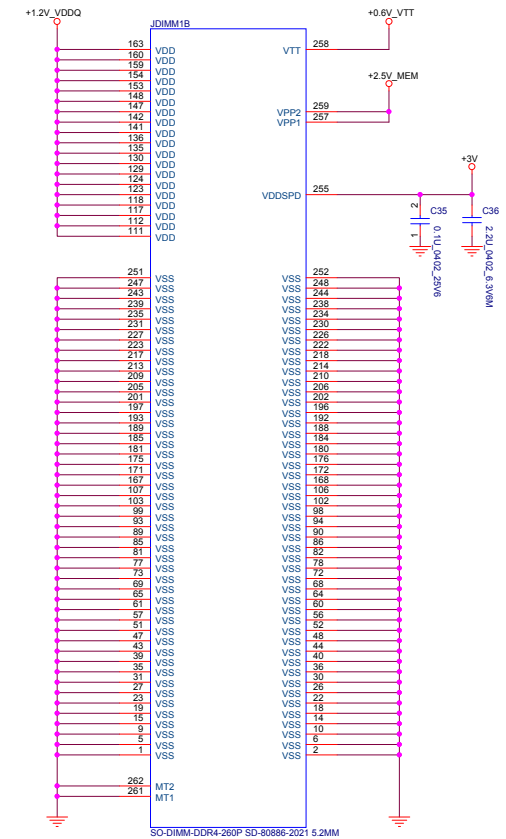
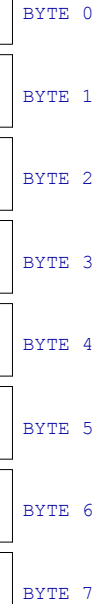
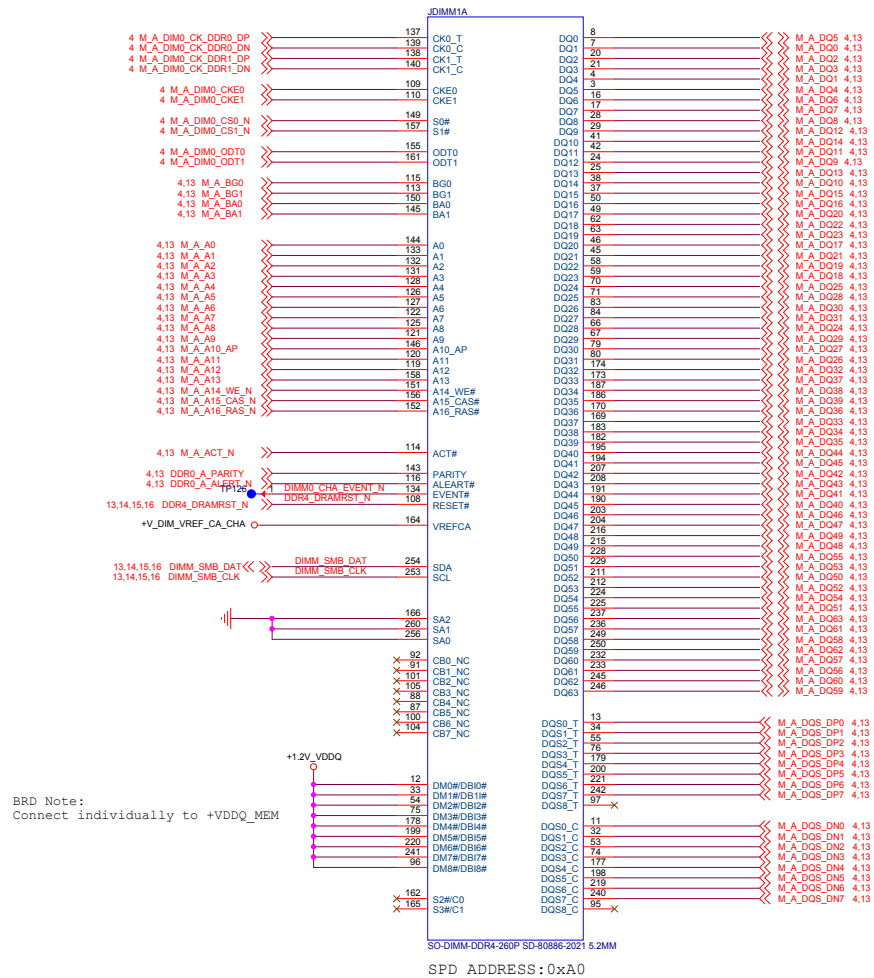
1 1182 470 uF 6.3V 10% 1

1 1183 470 uF 6.3V 10% 1

1 1184 470 uF 6.3V 10% 1

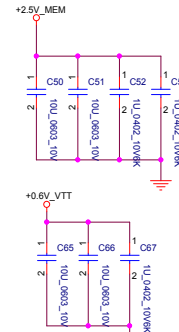
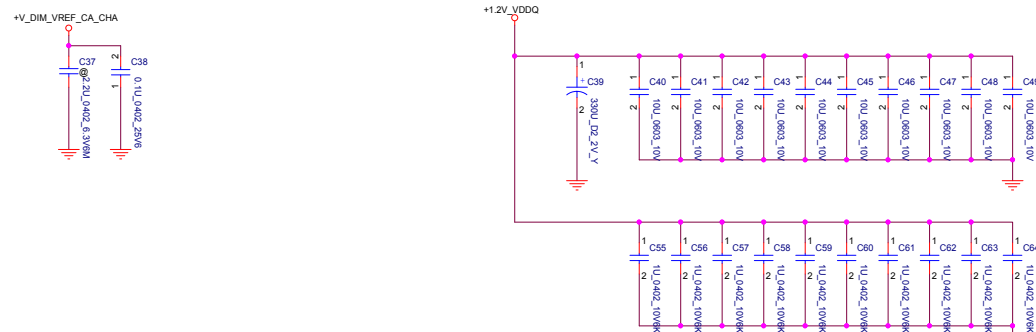
		LENOVO.CRDN	
Title PROCESSOR Decoupling 2/2			
Size C	Document Number Skylake-H		Rev v0.3
Date: Thursday, May 26, 2016		Sheet 11 of 99	
<p>PROPERTY NOTICE: this document contains information confidential and property of Lenovo and shall not be reproduced or transferred to other documents or disclosed to others without the express written consent of LENOVO PND. *</p>			

DDR4 SODIMM CHANNEL - A BOTTOM REV DIMM0 (5.2 MM HEIGHT CONNECTOR)

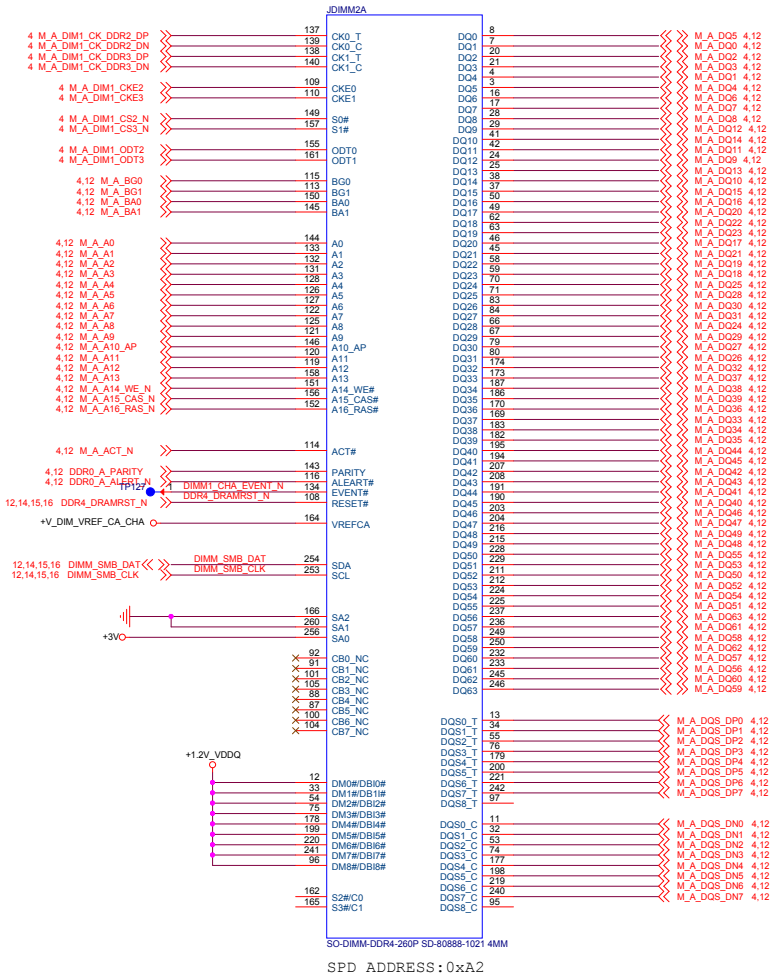


Decoupling Caps

BRD Note:
placed close to CHA DIMMO

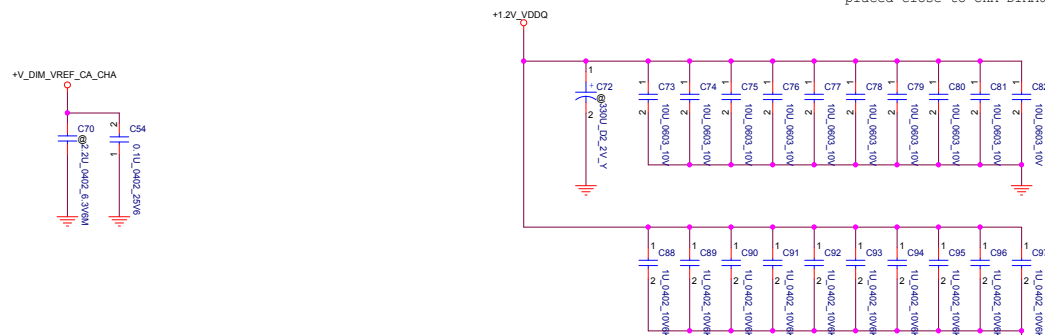


DDR4 SODIMM CHANNEL - A TOP STD DIMM1 (4 MM HEIGHT CONNECTOR)

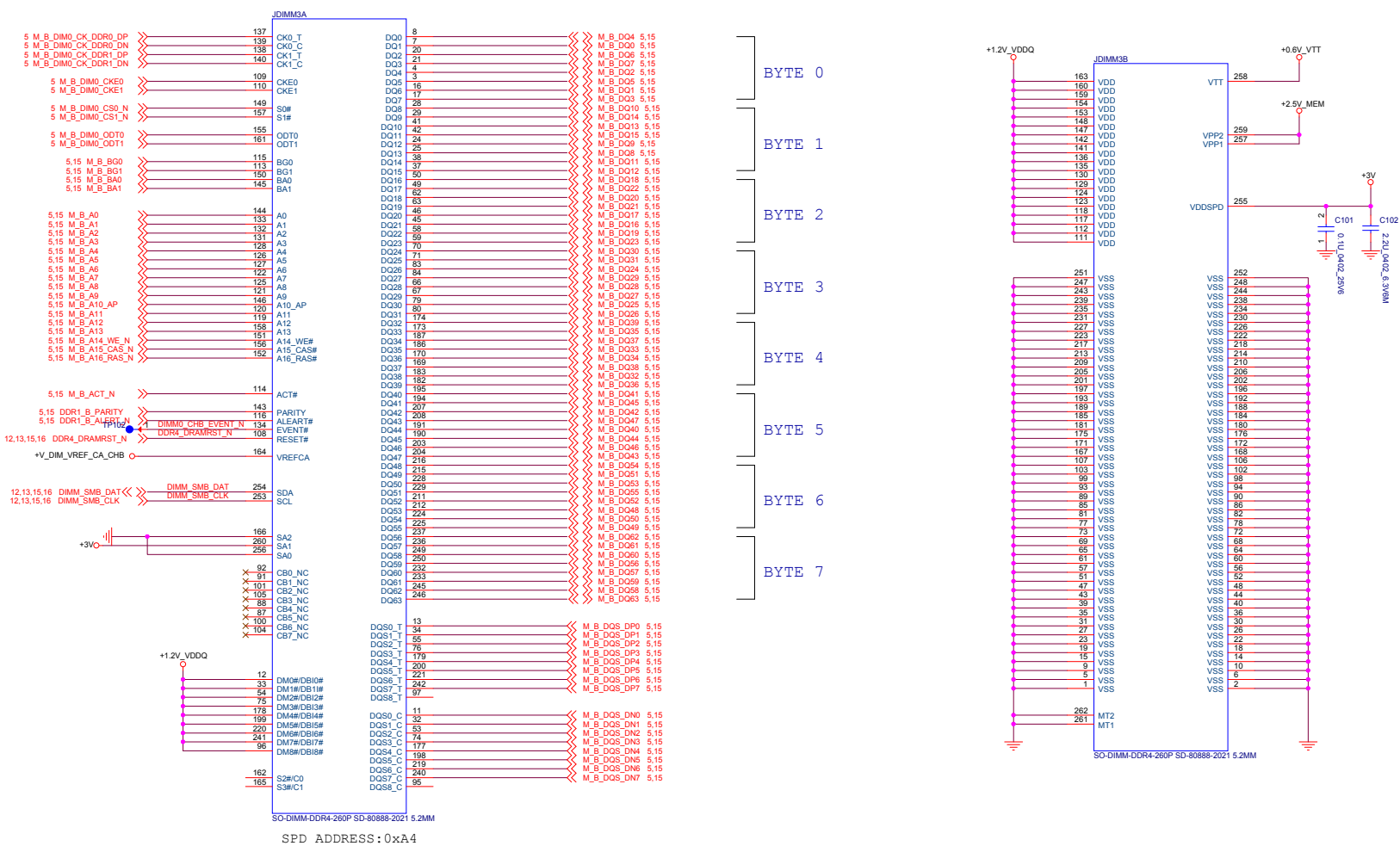


Decoupling Caps

BRD Note:
placed close to CHA DIMM0

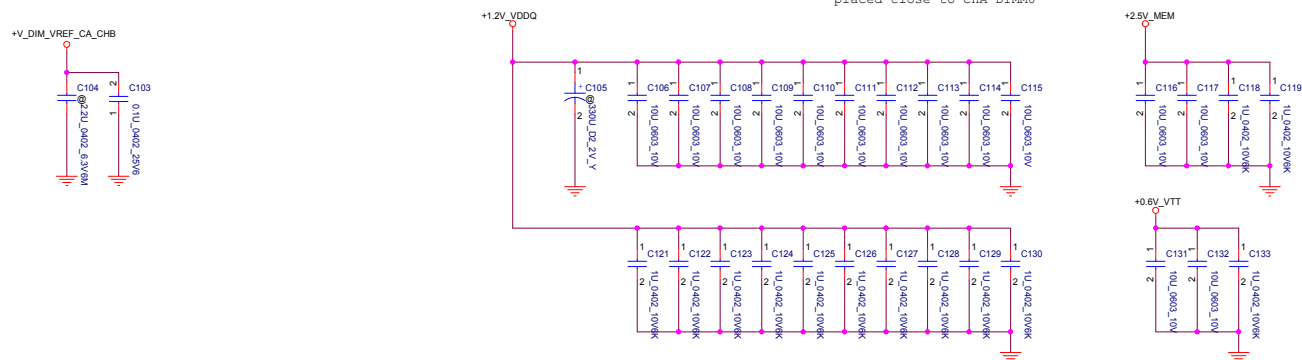


DDR4 SODIMM CHANNEL - B BOTTOM STD DIMM0 (5.2 MM HEIGHT CONNECTOR)

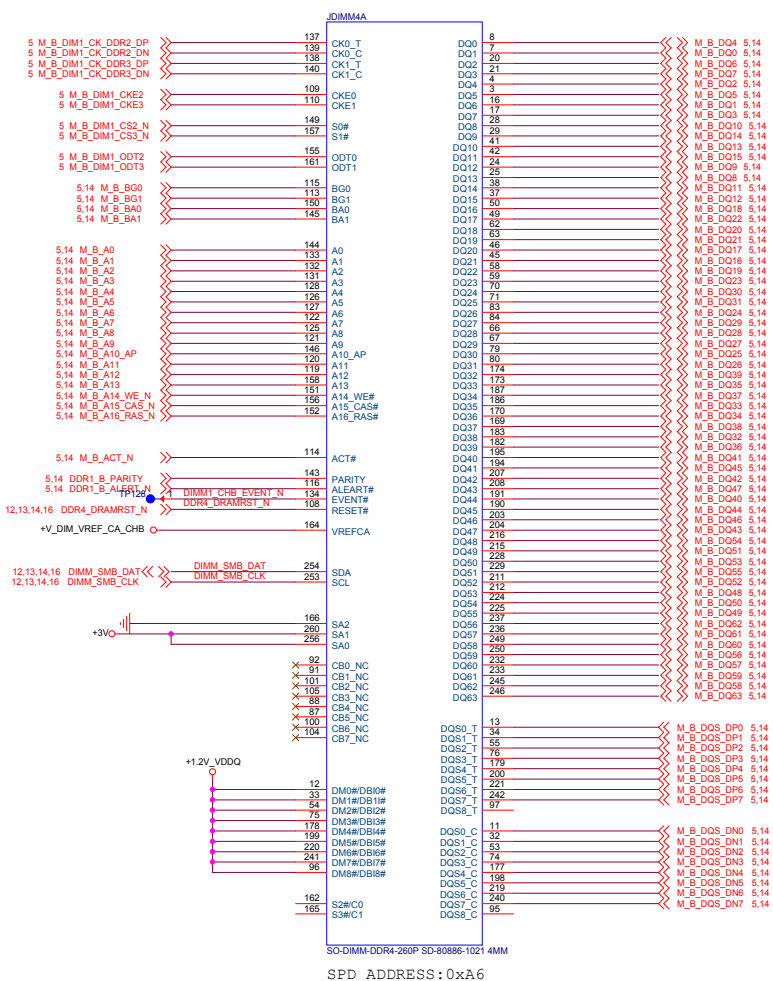


Decoupling Caps

BRD Note:
placed close to CHA DIMM0



DDR4 SODIMM CHANNEL - B TOP REV DIMM1 (4.0 MM HEIGHT CONNECTOR)

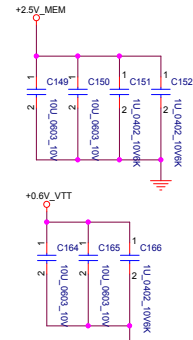
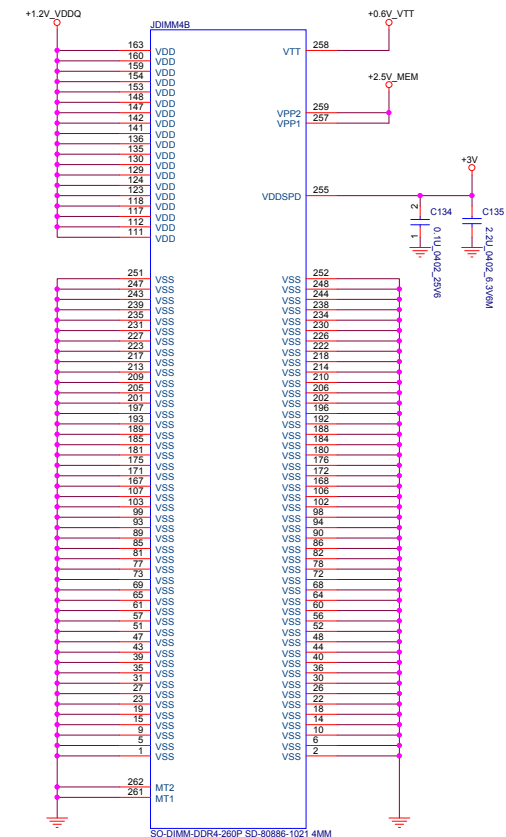
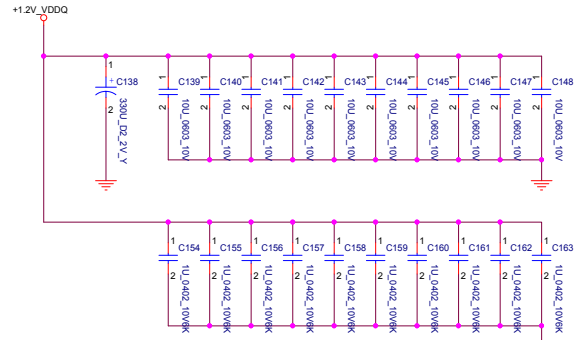
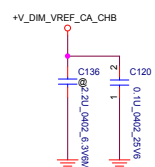


SPD ADDRESS: 0xA6

BYTE 7

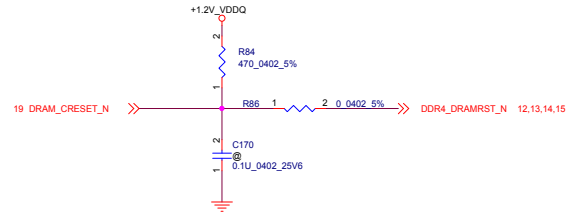
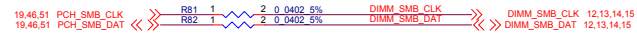
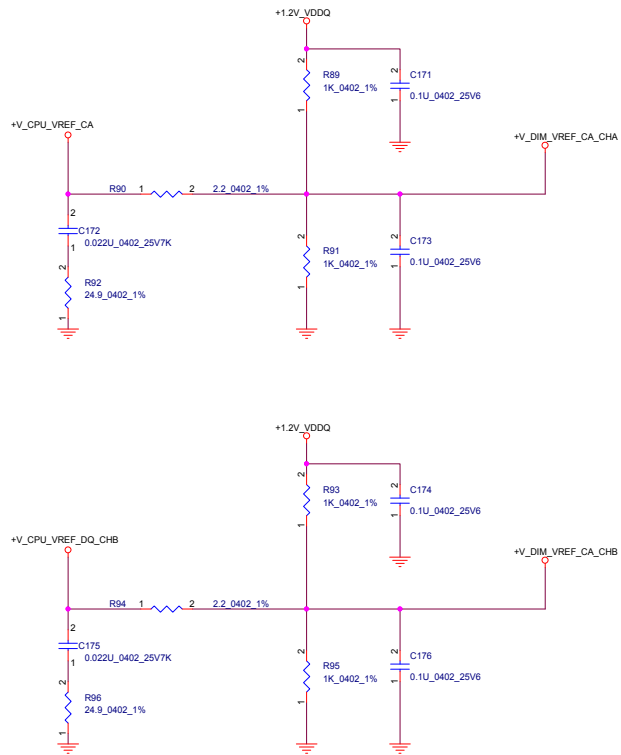
Decoupling Caps

BRD Note:
placed close to CHA DIMM0



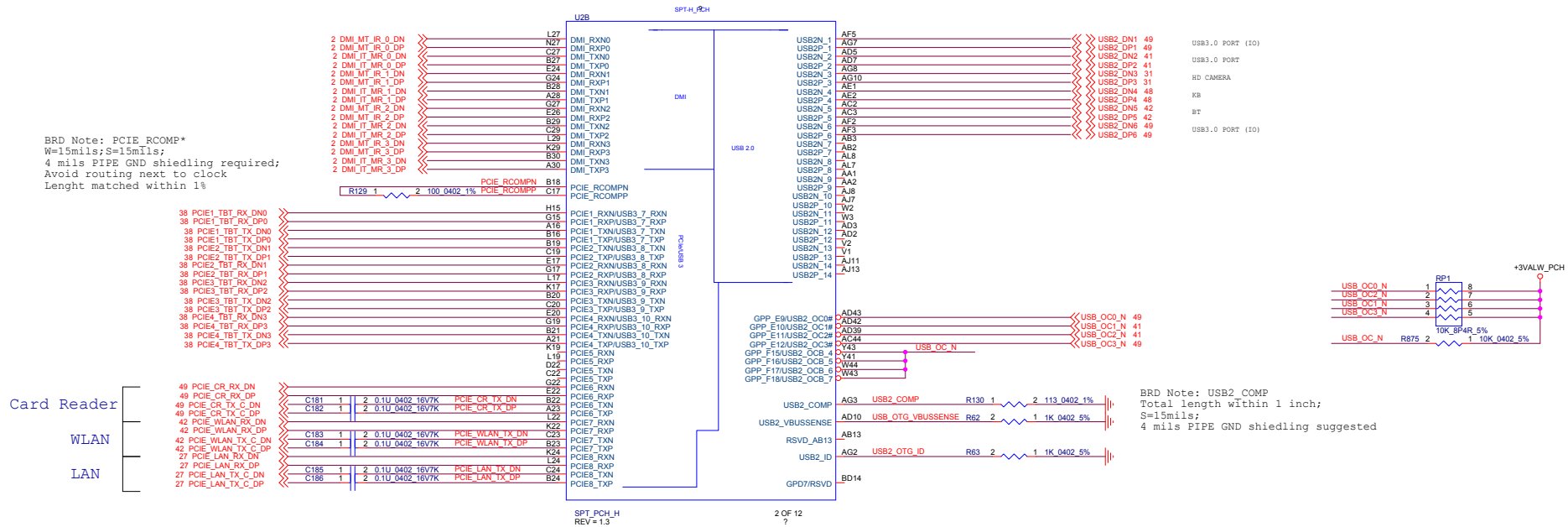
DDR VREF

BRD Note:
VREF trace width 20mils;spacing 20 mils to other signal/planes

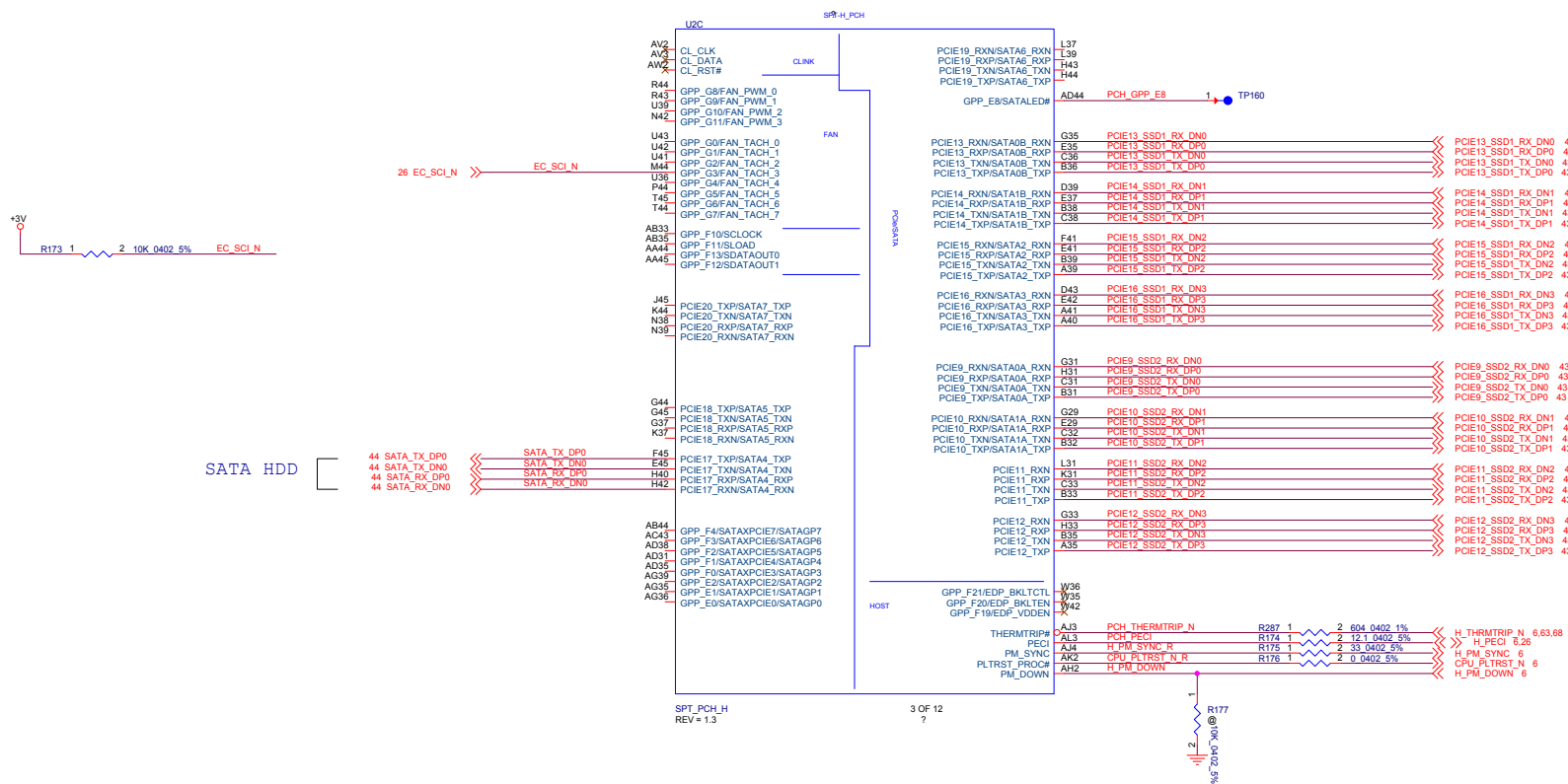


Flexible I/O Configuration				
I / O	High Speed Signals	Configuration	DEVICE	GEN
Port 7	USB3_7 / PCIE 1	AR (L0)	U2005 (Intel AR DP)	
Port 8	USB3_8 / PCIE 2	AR (L1)		
Port 9	USB3_9 / PCIE 3	AR (L2)		
Port 10	USB3_10 / PCIE 4	AR (L3)		
Port 11	PCIE 5	NC		
Port 12	PCIE 6	Card Reader	U3001	PCIE 1x Gen2
Port 13	PCIE 7	WLAN	JWLAN1	PCIE 1x Gen2
Port 14	PCIE 8	LAN	U6	PCIE1x Gen1

USB2.0 Configuration		
USB2 #	Assignment	OCx #
USB2 1	JUSB3(IO DB)	USB_OC0_N
USB2 2	JUSB2	USB_OC1_N
USB2 3	HD camera	
USB2 4	KB	
USB2 5	BT	
USB2 6	JUSB4(IO DB)	USB_OC3_N
USB2 7	NC	
USB2 8	NC	
USB2 9	NC	
USB2 10	NC	
USB2 11	NC	
USB2 12	NC	
USB2 13	NC	
USB2 14	NC	

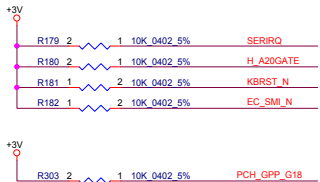


Flexible I/O Configuration				
I/O	High Speed Signals	Configuration	DEVICE	GEN
Port 15	SATA 0A / PCIE 9	M.2 SSD2 (L0) / SATA0	JSSD2	PCIE 4x Gen 3 /SATA Gen 3
Port 16	SATA 1A / PCIE 10	M.2 SSD2 (L1)		
Port 17	/ PCIE 11	M.2 SSD2 (L2)		
Port 18	/ PCIE 12	M.2 SSD2 (L3)		
Port 19	SATA 0B / PCIE 13	M.2 SSD12(L0)	JSSD1	PCIE 4 x Gen 3
Port 20	SATA 1B / PCIE 14	M.2 SSD1 (L1)		
Port 21	SATA 2 / PCIE 15	M.2 SSD1 (L2)		
Port 22	SATA 3 / PCIE 16	M.2 SSD1 (L3)		
Port 23	SATA 4 / PCIE 17	SATA HDD	U14	SATA Gen 3
Port 24	SATA 5 / PCIE 18	NC		
Port 25	SATA6 / PCIE 19	NC		
Port 26	SATA7 / PCIE 20	NC		

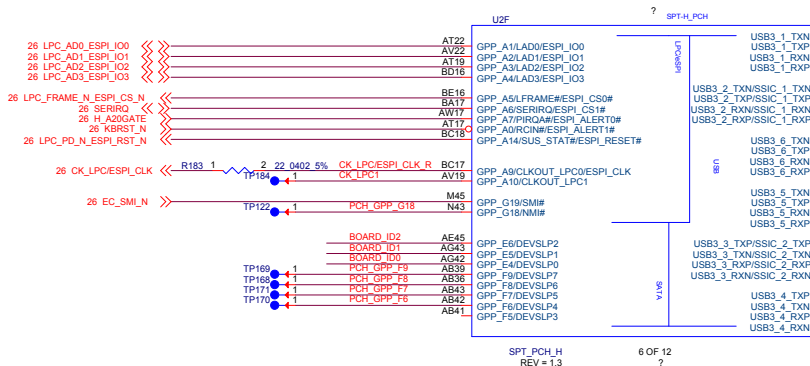


Gen3
PCIE SSD1

Gen3
PCIE SSD2

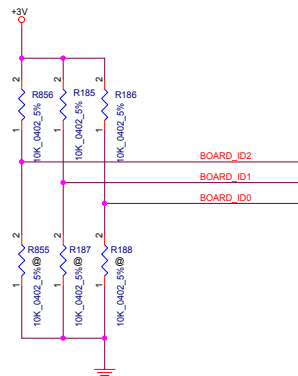


CAD Note:
LPC:24M Hz
eSPI:20/30/60M Hz



Flexible I/O Configuration				
I / O	High Speed Signals	Configuration	DEVICE	OCx #
Port 1	USB3 1 Capable of OTG	USB3.0	JUSB3(IO DB)	USB_OC0_N
Port 2	USB2 3 / SSIC 1	NC		
Port 3	USB3 3 / SSIC 2	USB3.0	JUSB2	USB_OC1_N
Port 4	USB3 4	NC		
Port 5	USB3 5	NC		
Port 6	USB3 6	USB3.0	JUSB4(IO DB)	USB_OC3_N

BRD Note:USB3.0
Non-interleaved breakout is required



BOARD_ID2	BOARD_ID1	BOARD_ID0	Description
0	0	0	
0	0	1	
0	1	0	
0	1	1	
1	0	0	
1	0	1	
1	1	0	
1	1	1	

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File

PCH-USB3.0/LPC

Size

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Document Number

Skylake-H

Date

Thursday, May 26, 2016

Sheet

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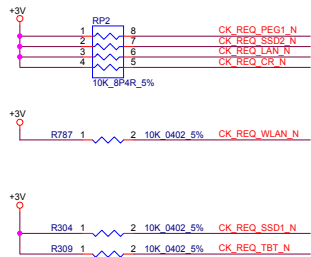
of

99

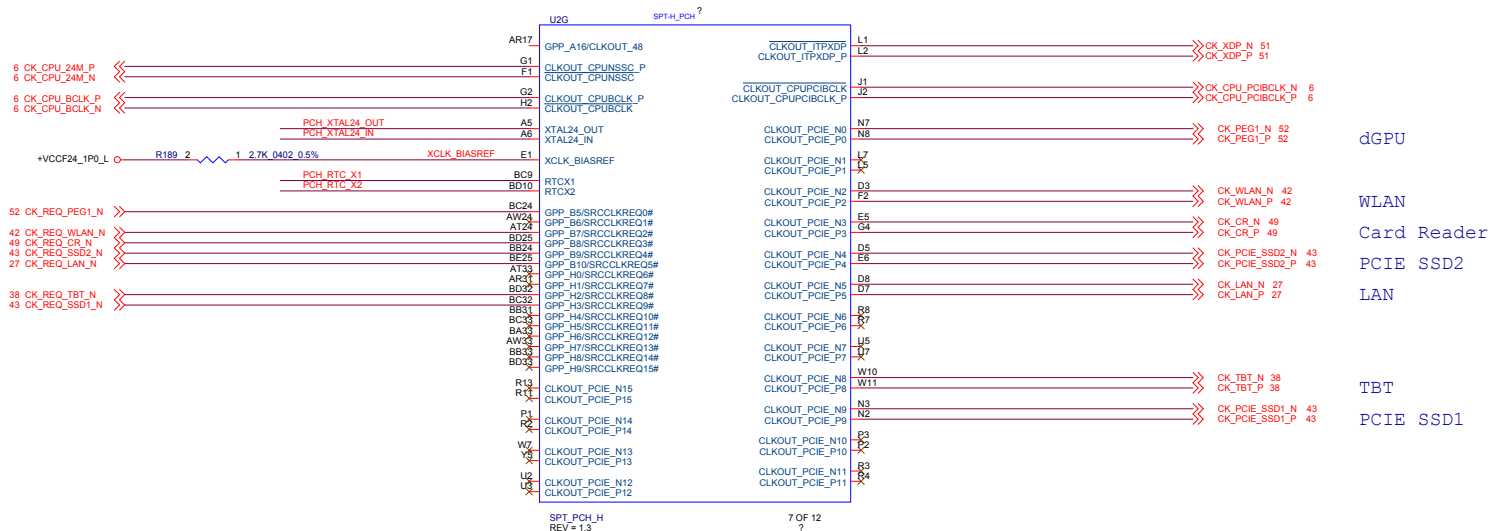
Rev

V0.3

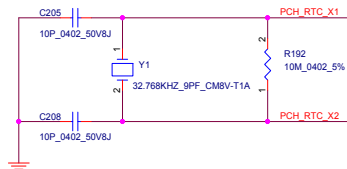
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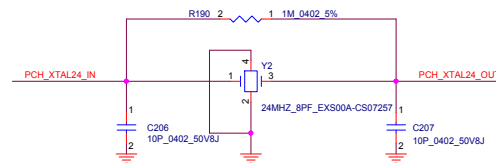
BRD Note: XCLK_BIASREF
Ground reference;Max via:2
Isolation spacing:20mils
Segment Length:100mils;Total length:1000mils
VSS shield recommended;S:W:S=6:4:6

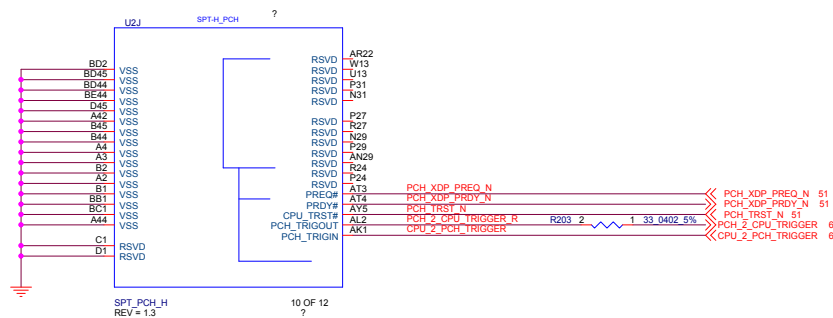
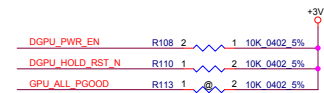
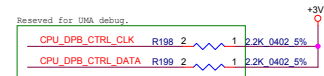
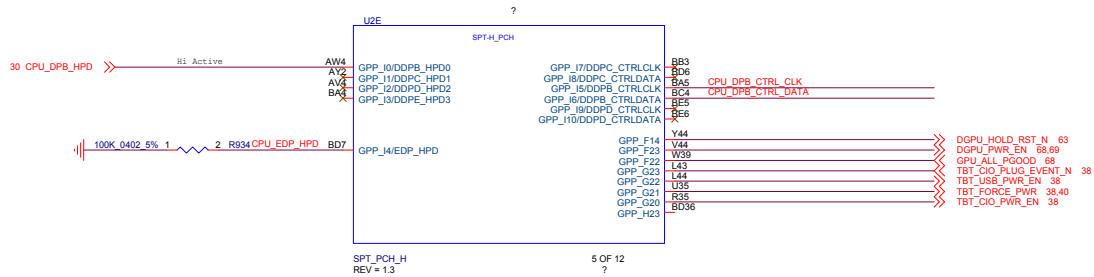


CAD Note:
Max crystal ESR 50K ohm

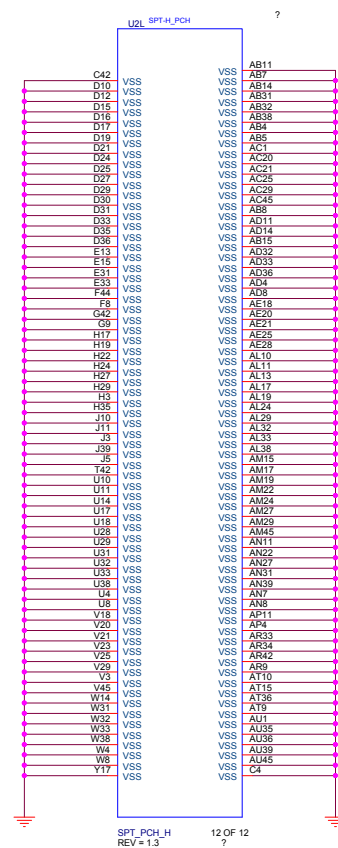
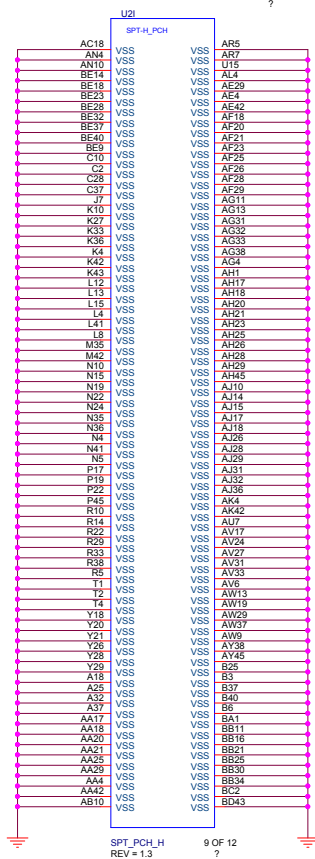


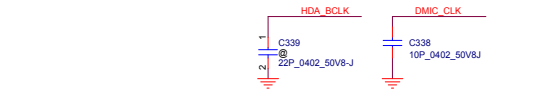
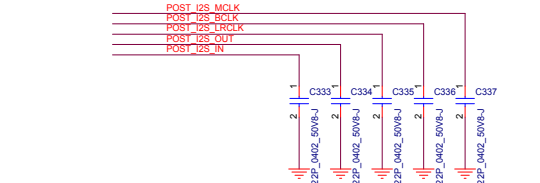
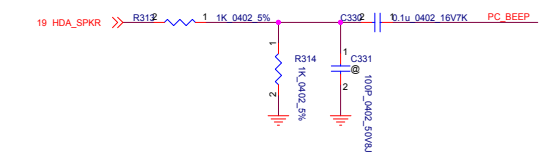
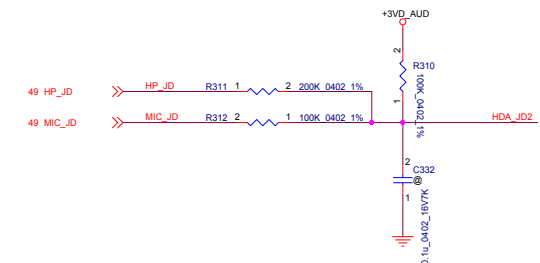
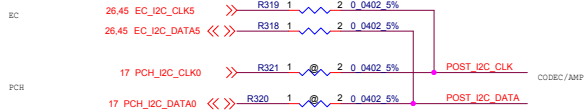
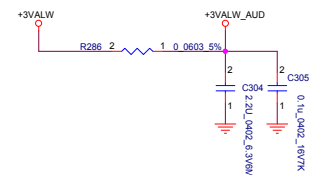
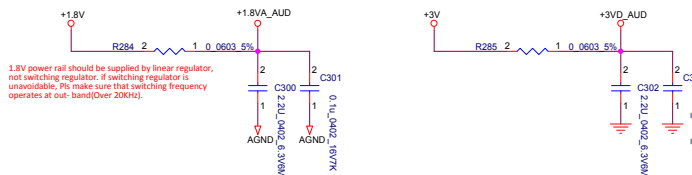
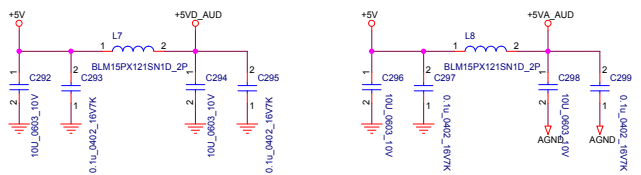
BRD Note:
Z0=50 ohm +/-15%;Ground reference;Max via:2
Group spacing:15mils;Isolation spacing:20mils
Segment Length:100mils;Total length:1000mils;Length match:100mils
VSS shield recommended;S:W:S=6:4:6



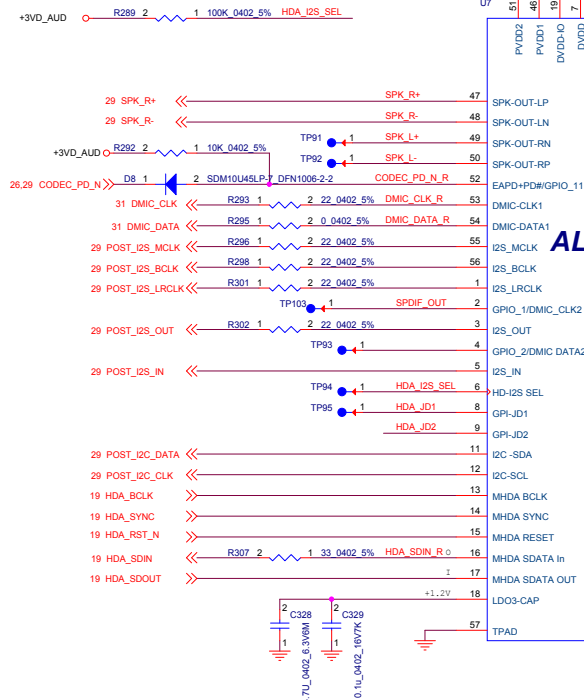


CAD Note:
CRB use 30R;DG use 0R

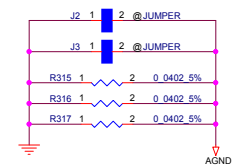
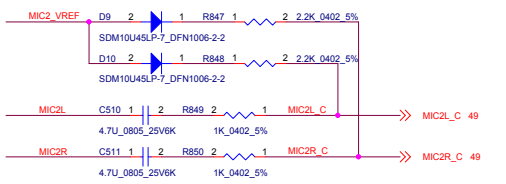
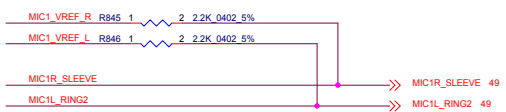




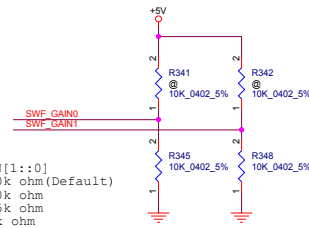
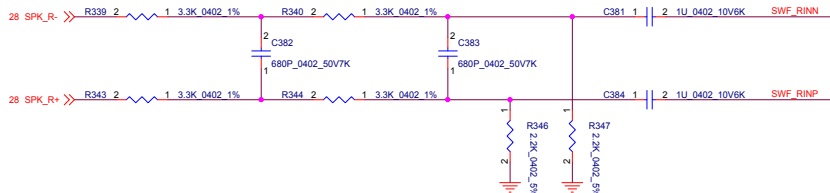
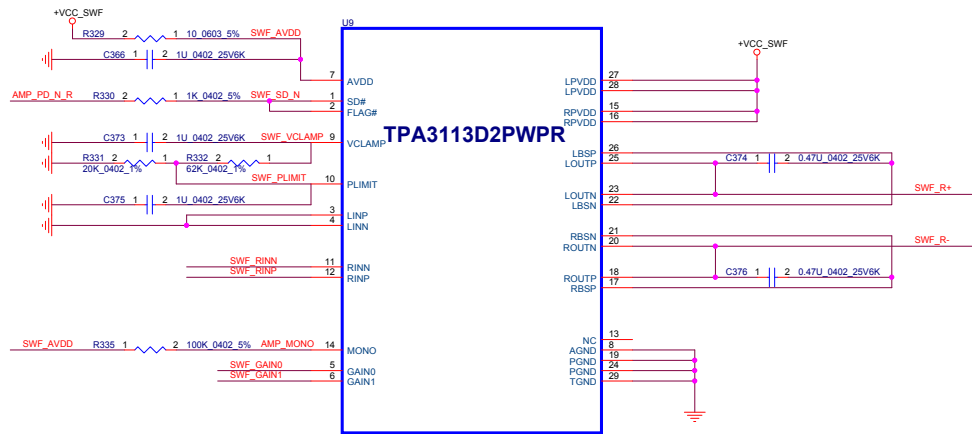
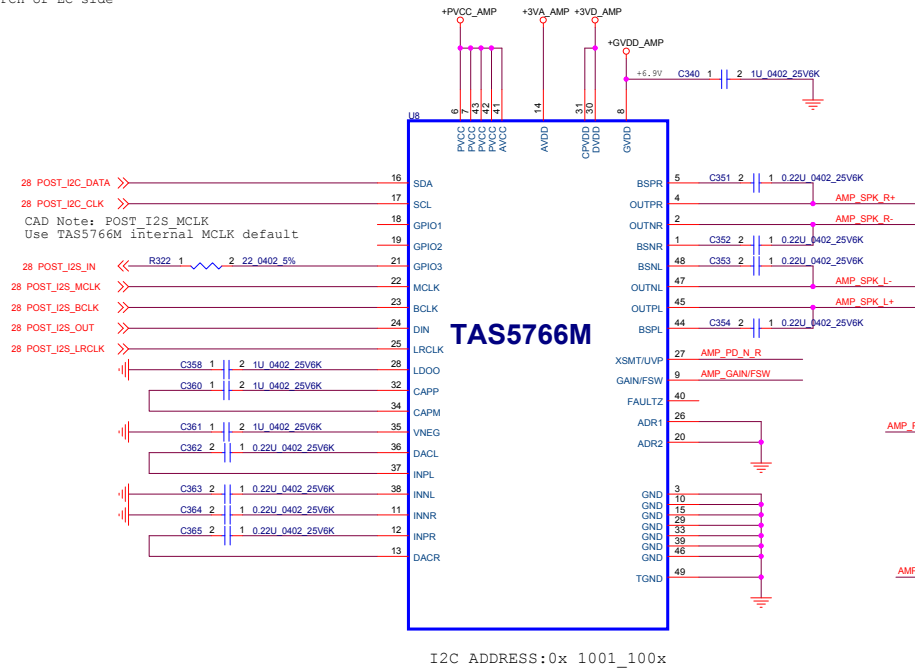
CAD Note: HD_I2C_SEL
Hi: HDA mode? POR strap

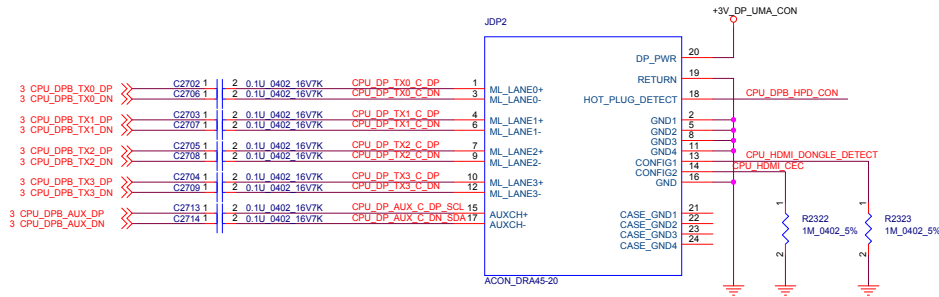
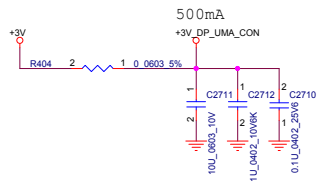


ALC3268-CG

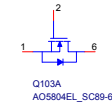
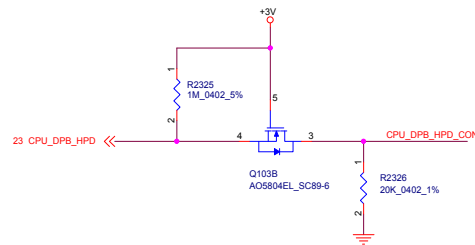
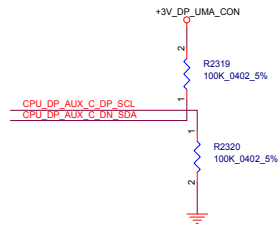


CAD Note: POST I2C*
connect to PCH default and reserve to EC
PU at PCH or EC side

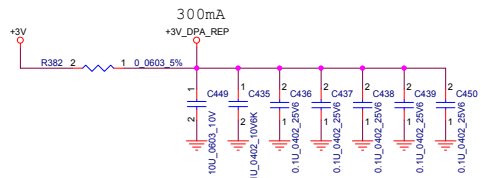




CAD Note: HDMI DONGLE_DETECT
LOW:DP PORT ENABLED(Default) *
Hi:HDMI ENABLED







CAD Note:
Internal pull up at ~100kΩ, 3.3V I/O.

DPC SW[1:0]=11, output swing=1000mv
Inputs with internal 100 kΩ pull-up.
This pin sets the output Voltage Level in all channel when EN12C is LOW.

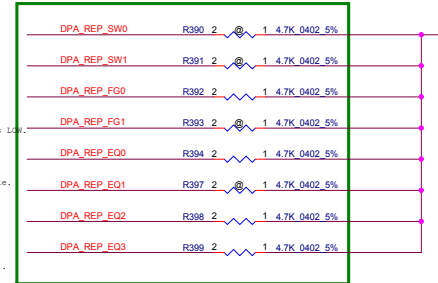
DPC FG[1:0]=10, gain=0.5db
Inputs with internal 100 kΩ pull up resistor.
Sets the output flat gain level on all channels when EN12C is low.

DPC EQ[3:0]=0010, about 10inch,
Inputs with internal 100 kΩ pull-up.
This pins set the amount of Equalizer Boost in all channel when EN12C is LOW.
I2C Address=0xF2

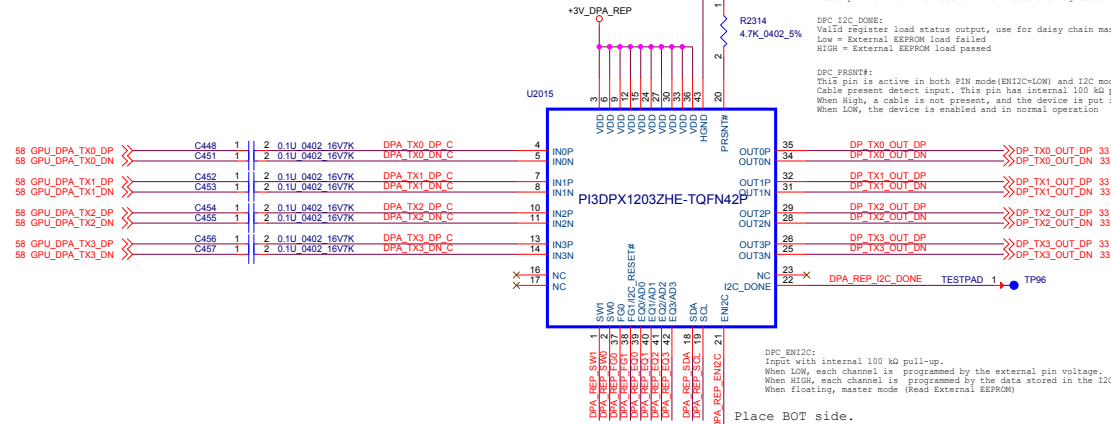
DPC I2C RESET#:
Inputs With internal 100 kΩ pull up resistor.
Reset pin for I2C. When set low with reset the registers to default state.

DPC I2C DONE:
Valid register load status output, use for daisy chain master
Low = External EEPROM load failed
HIGH = External EEPROM load passed

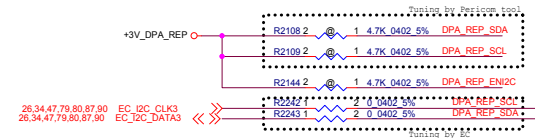
DPC PRSNT#:
This pin is active in both PIN mode (EN12C=LOW) and I2C mode (EN12C=HIGH).
Cable present detect input. This pin has internal 100 kΩ pull-up.
When High, a cable is not present, and the device is put in lower power mode.
When LOW, the device is enabled and in normal operation



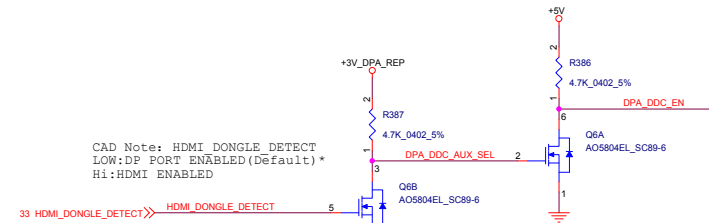
Place BOT side.



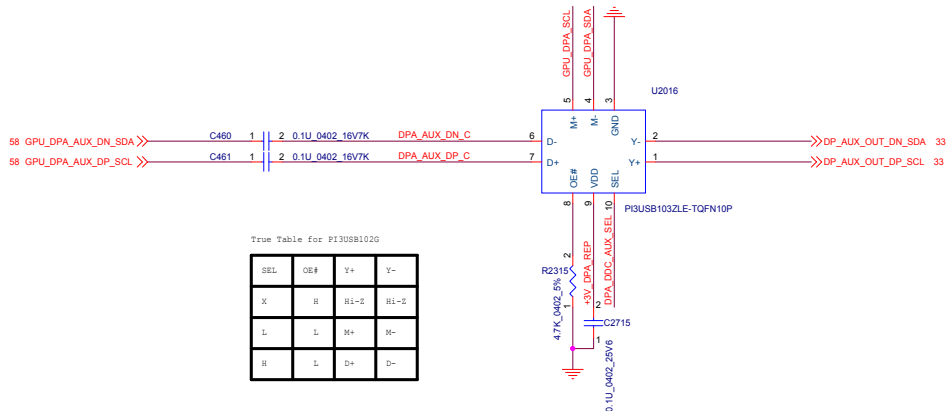
Place BOT side.



Place BOT side.



CAD Note: HDMI DONGLE DETECT
LOW:DP PORT ENABLED(Default)*
Hi:HDMI ENABLED



True Table for PI3USB1020

SEL	OE#	Y+	Y-
X	H	H1-E	H1-E
L	L	H+	H-
H	L	D+	D-

lenovo 联想

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DP1.3 REPEATER

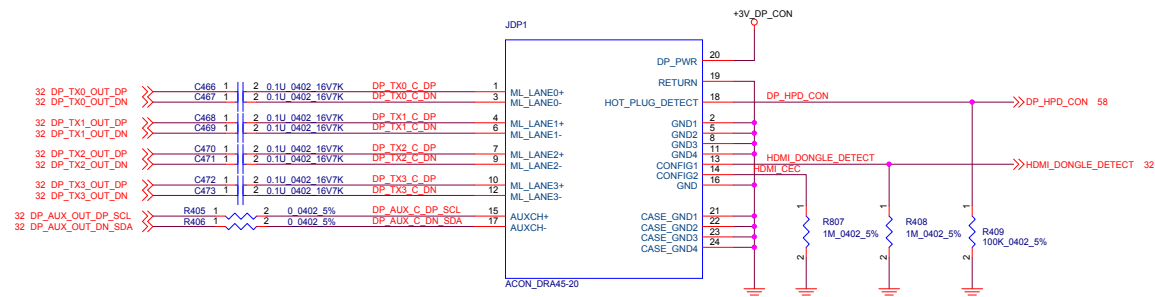
Document Number
Skylake-H

Date: Thursday, May 26, 2016

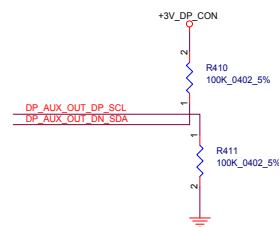
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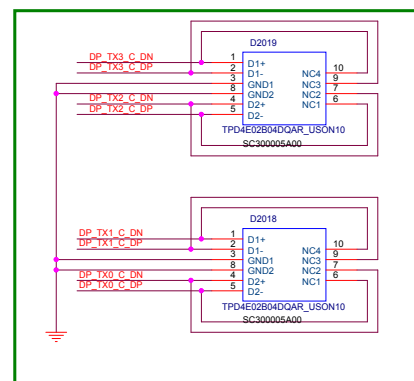
Rev V0.3



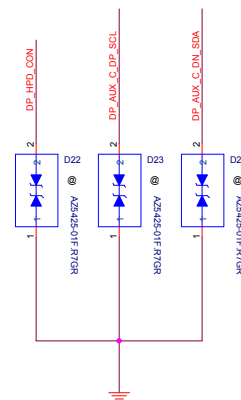
CAD Note: HDMI DONGLE DETECT
LOW:DP PORT ENABLED(Default)*
Hi:HDMI ENABLED

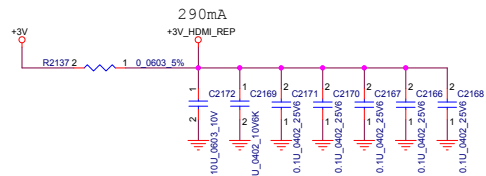


CAD Note: Reserve for ESD

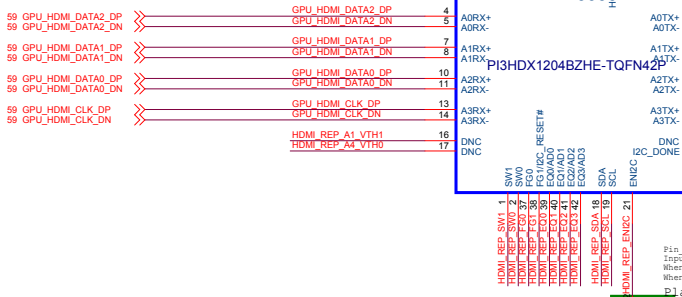


CAD Note: Reserve for ESD





AC coupling cap @ GPU side, and place close to U2019.



Pin Mode: (PI3HDX1204BZHE)
Input with internal 100k-Ohm Pull-Up.
When HIGH, each channel is programmed by the external pin voltage.
When LOW, each channel is programmed by the data stored in the I2C bus.
Place BOT side.



CAD Note:
Internal pull up at ~100kΩ, 3.3V I/O.

DE[1:0]=01, De-emphasis=3.5db
Inputs with internal 100k-Ohm Pull-Up.
This pins set the output De-emphasis Level in all channel when Pin_Mode is HIGH.

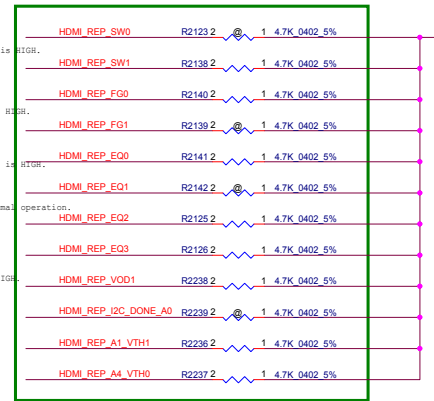
PS[1:0]=10, Pre-shoot=3.5db
Inputs with internal 100k-Ohm Pull-Up.
This pins set the output Pre-shoot Level in all channel when Pin_Mode is HIGH.

BST[3:0]:
Inputs with internal 100k-Ohm Pull-Up.
This pins set the amount of Equalizer Boost in all channel when Pin mode is HIGH.

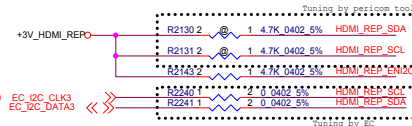
FEH: (PI3HDX1204B)
Power Enable with internal 100k-Ohm Pull-Up device is enabled and in normal operation.
Reserve 4.7k PD for PI3HDX1204D.

HDMI REP_VDD1:
Inputs with internal 100k-Ohm Pull-Up.
This pin sets the output Voltage Level in all channel when Pin mode is HIGH.

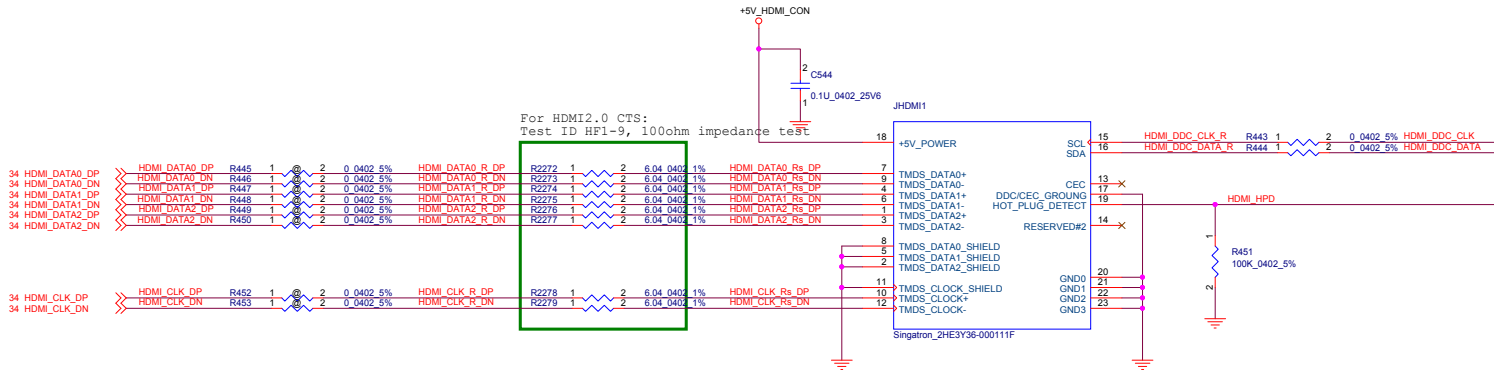
A4/A1/A0:
I2C programmable address bits, with internal 100k-Ohm Pull-Up.
I2C Address=0xC2



Place BOT side.



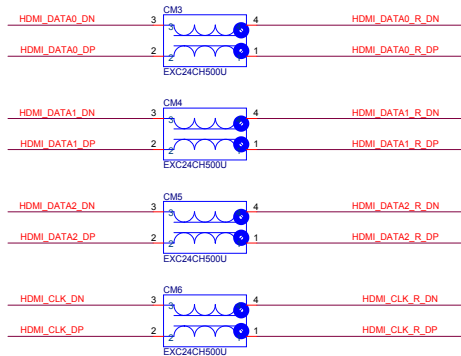
Place BOT side.



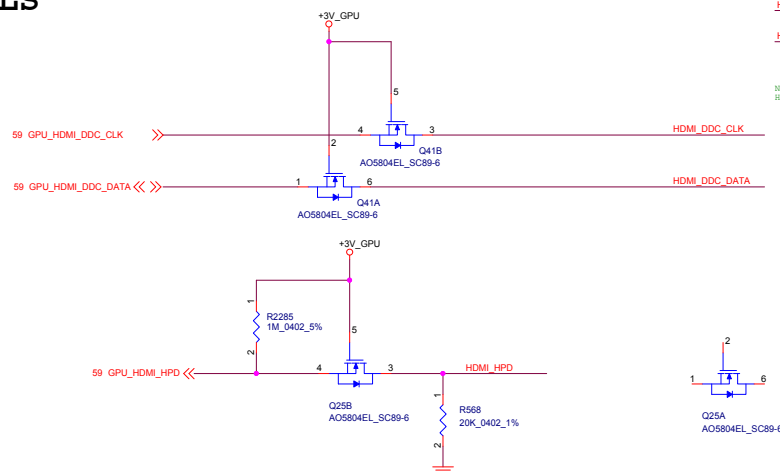
CM

BRD Note:
Co-layer with R

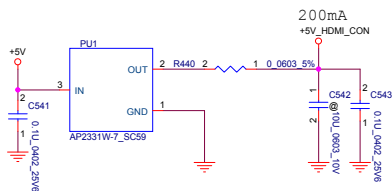
CAD Note:
Reserve for EMI



LS

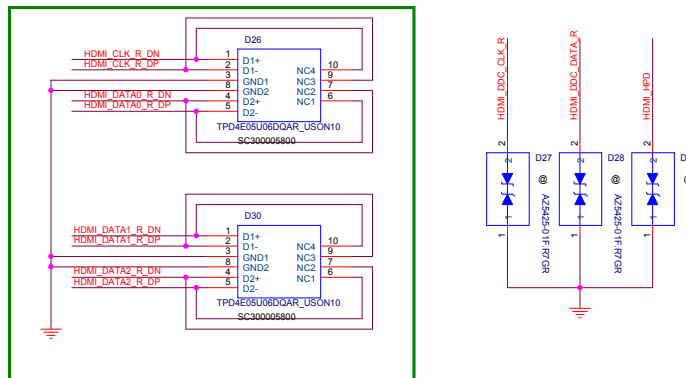


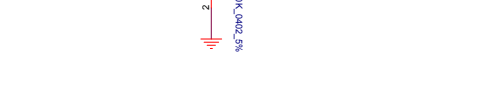
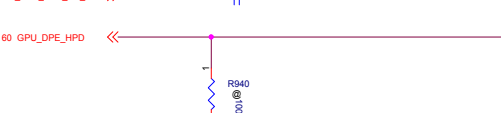
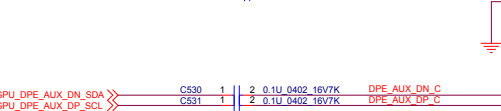
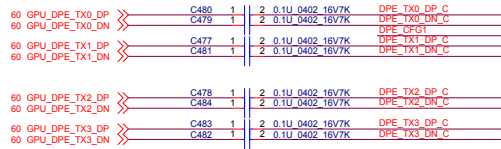
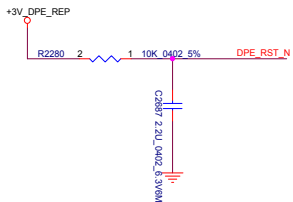
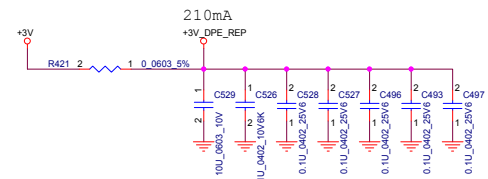
Power switch



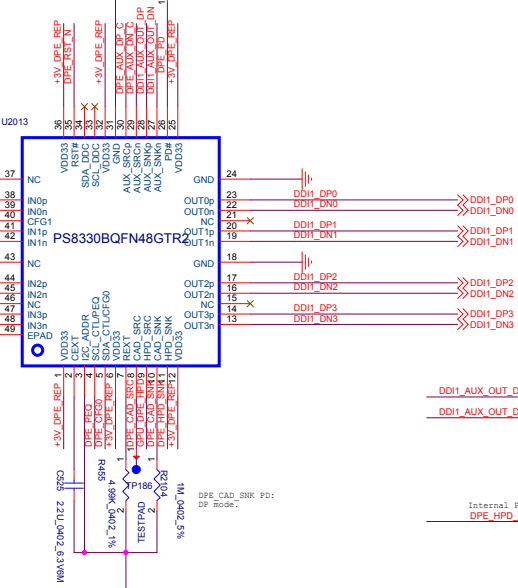
ESD

CAD Note: Reserve for ESD

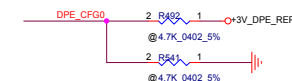




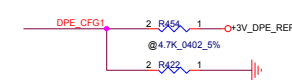
CAD Note: DPE REDRIVER PD
Chip power down, active LOW
Internal pull UP at ~150kΩ, 3.3V I/O.
H=Normal operation(default)
L=Chip power down



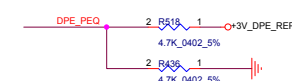
I2C ADDR:
LOW#pin control is selected.
High#I2C control is selected with default I2C address 42/437



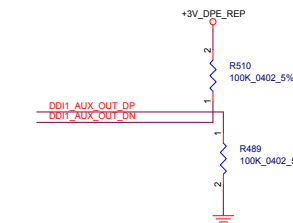
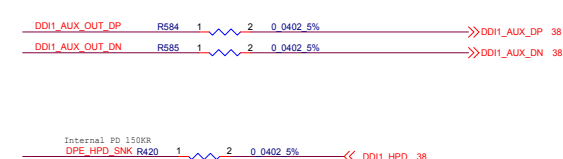
Configuration pin for automatic EQ and AUX interception; Internal pull down at ~150kΩ, 3.3V I/O.
L: default, automatic EQ enable & AUX interception enable
H: automatic EQ disable & AUX interception enable
M: automatic EQ disable & AUX interception disable, no pre-emphasis, 600mVpp swing



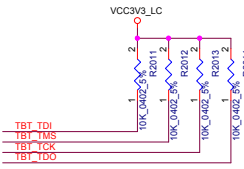
Configuration pin for auto test and input offset cancellation, 3.3V I/O, internal pull up at ~150K
H: default, auto test disable & input offset cancellation enable
L: auto test enable & input offset cancellation enable
M: auto test disable & input offset cancellation disable



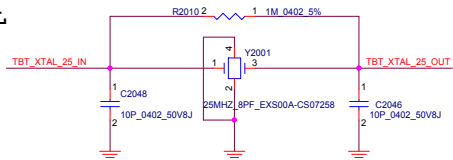
Programmable input equalization levels; Internal pull down at ~150kΩ, 3.3V I/O.
L: default, LEQ, compensate channel loss up to 12dB @ HBR2
H: HEQ, compensate channel loss up to 15dB @ HBR2
M: LEQ, compensate channel loss up to 5dB @ HBR2



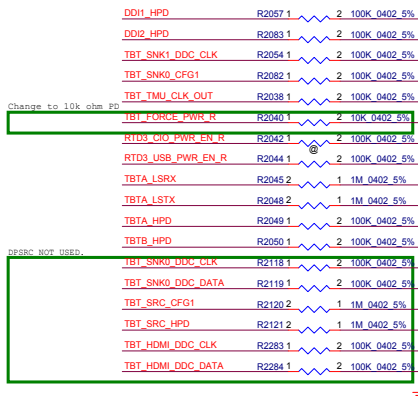
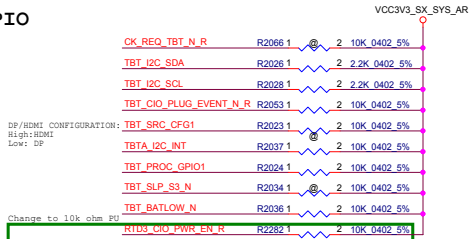
JTAG



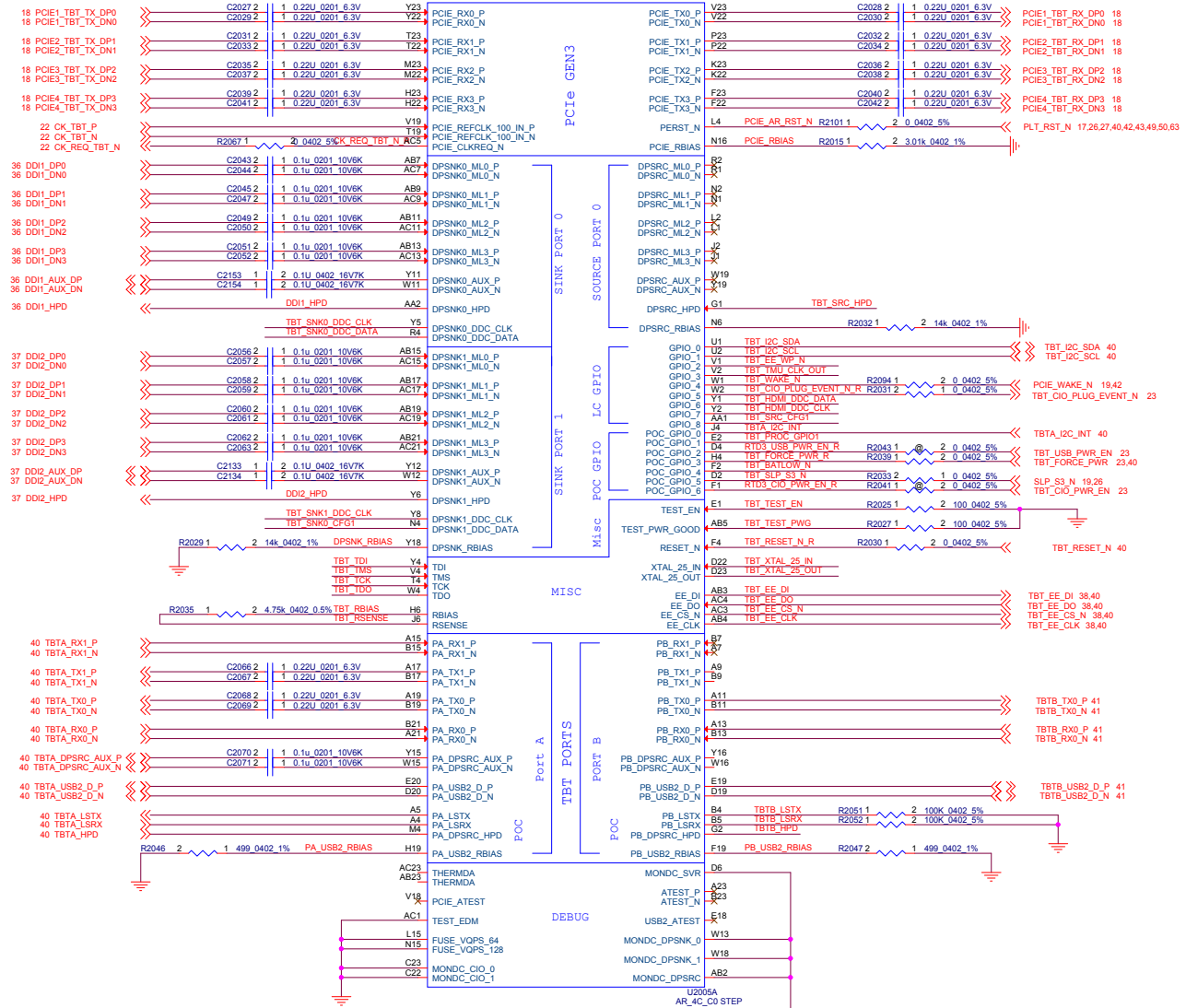
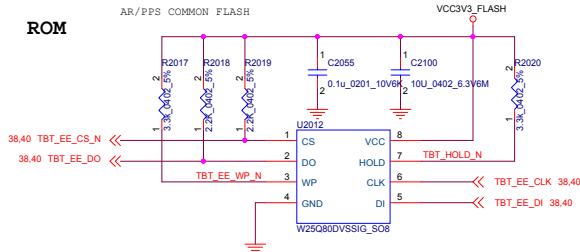
XTAL



GPIO



ROM



IF SOME OF GPIOs ARE NOT IN USE FOLLOW TABLE BELOW:

GPIO	TERMINATION	Power Rail
GPIO 0	10K PU	VCC3V3_LC
GPIO 1	10K PU	VCC3V3_LC
GPIO 2	10K PU	VCC3V3_LC
GPIO 3	100K PD	VCC3V3_LC
GPIO 4	10K PU	VCC3V3_LC
GPIO 5	10K PU	VCC3V3_LC
GPIO 6	100K PD	SRC NOT USED
GPIO 7	100K PD	SRC NOT USED
GPIO 8	1M PD	SRC NOT USED
POC_GPIO_0	10K PU	VCC3V3_TBT_SX
POC_GPIO_1	10K PU	VCC3V3_TBT_SX
POC_GPIO_2	100K PD	VCC3V3_TBT_SX
POC_GPIO_3	10K PD	VCC3V3_TBT_SX
POC_GPIO_4	10K PU	VCC3V3_TBT_SX
POC_GPIO_5	10K PU	VCC3V3_TBT_SX
POC_GPIO_6	100K PD	VCC3V3_TBT_SX

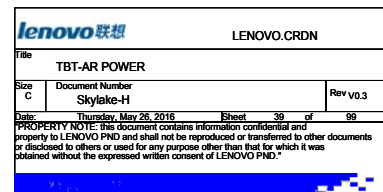
DEBUG PINS:

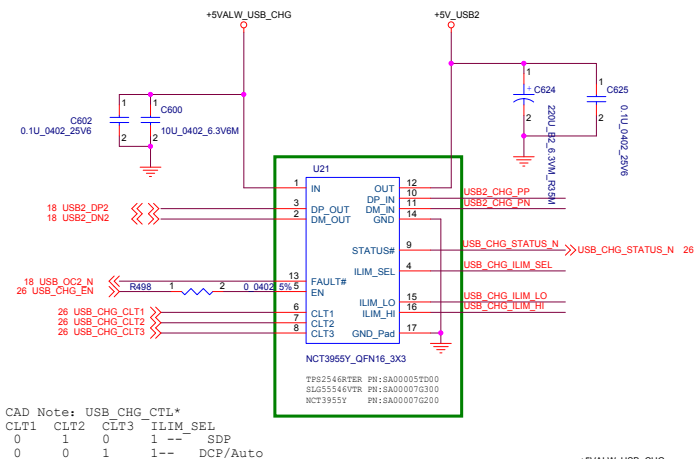
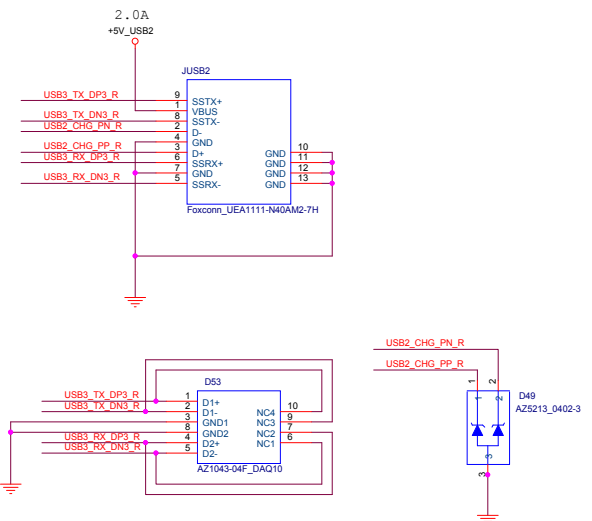
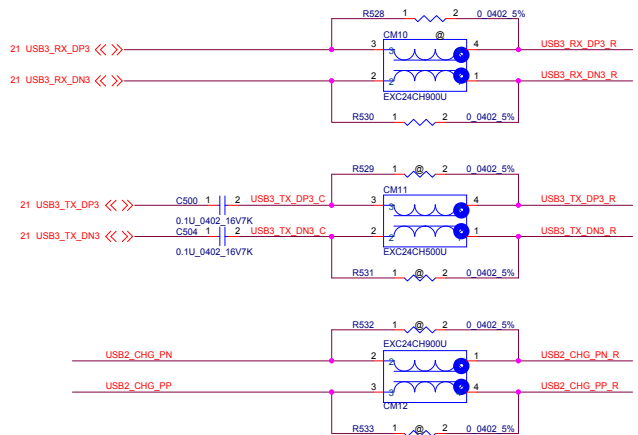
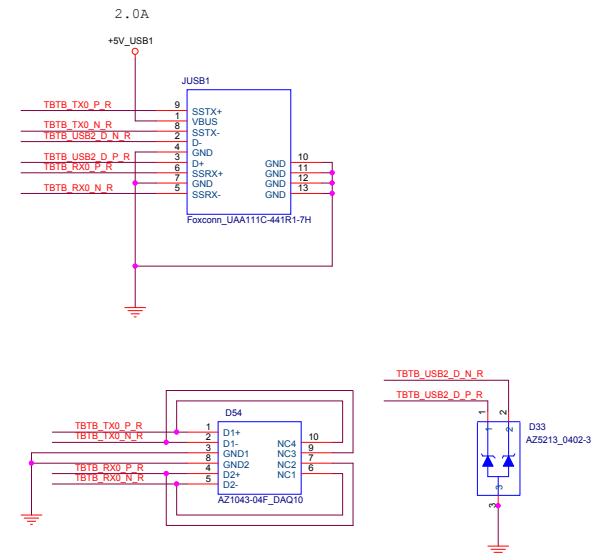
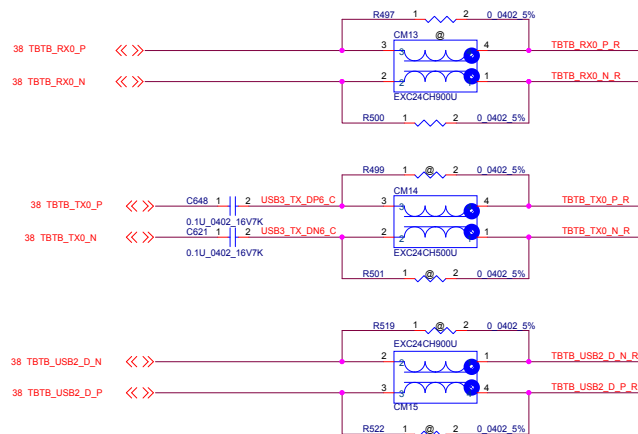
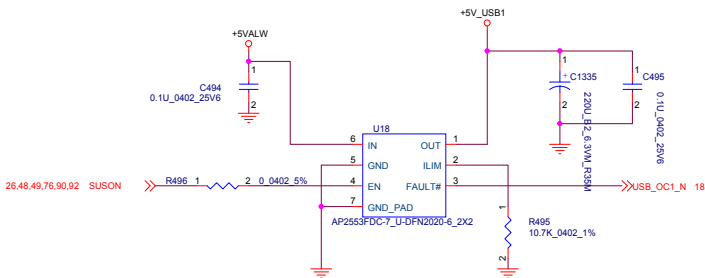
PIN	TERMINATION
MONDC_SVR	GND
MONDC_DPSNK_0	GND
MONDC_DPSNK_1	GND
MONDC_DPSRC	GND
MONDC_CIO_0	GND
MONDC_CIO_1	GND
TEST_EDM	GND
FUSE_VQPS_64	FLOATING
FUSE_VQPS_128	FLOATING
ATEST_P/N	FLOATING
PCIE_ATEST	FLOATING

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Size	Document Number	Sheet	Rev
C	DDI redriver PS8330	38	v0.3
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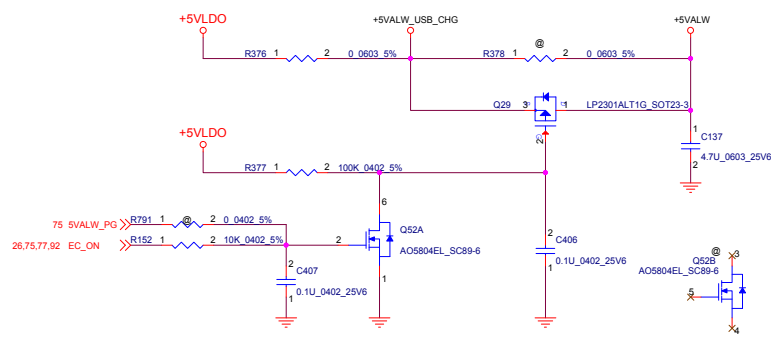


CAD Note: USB_CHG_CTL*
CLT1 CLT2 CLT3 ILIM_SEL
0 1 0 1 -- SDP
0 0 1 1-- DCP/Auto

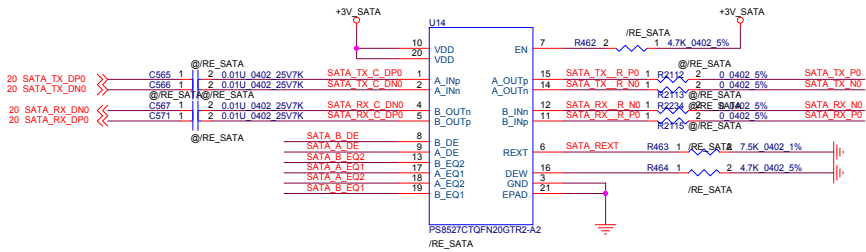
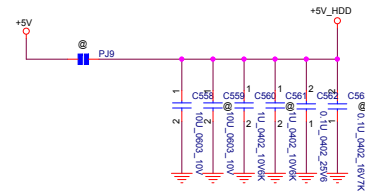
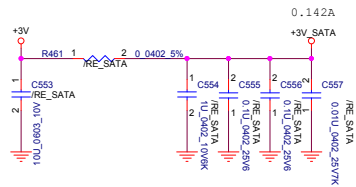
CAD Note:
ILIM_SEL=Vin, ILIM_HI=22.6KR:
output current limit=2.3A

Support Mouse/Keyboard wake up.
Support Power Wake

CAD Note: For Power consumption



CAD Note: PS8527A VDD
1.2V/1.35V/1.5V



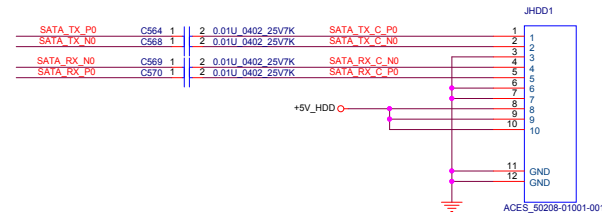
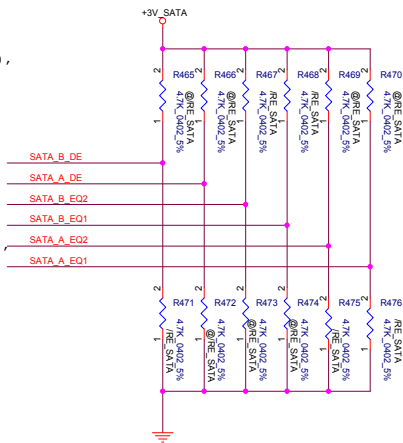
CAD Note:
SATA_REXT=7.5KR:
Vtx_diff=700 mV

CAD Note: SATA_DEW
L:For SATA Gen3
H:For SATA Gen2

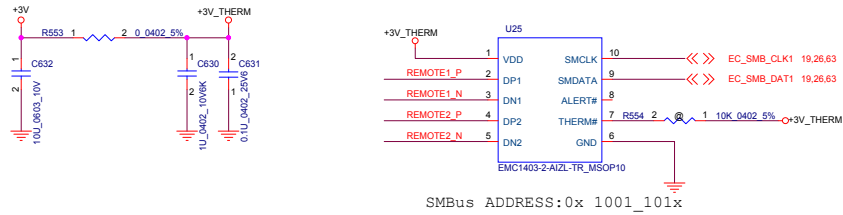
SATA_TX_DP0	R2229	1	/SATA	2	0.0402 5%	R2232	1	/SATA	2	0.0402 5%	SATA_TX_P0
SATA_TX_DN0	R2106	1	/SATA	2	0.0402 5%	R2107	1	/SATA	2	0.0402 5%	SATA_TX_N0
SATA_RX_DN0	R2233	1	/SATA	2	0.0402 5%	R2230	1	/SATA	2	0.0402 5%	SATA_RX_N0
SATA_RX_DP0	R2110	1	/SATA	2	0.0402 5%	R2231	1	/SATA	2	0.0402 5%	SATA_RX_P0

CAD Note: SATA_x_DE
De-emphasis level setting for channel x(x=A,B),
internally tied to VDD/2
[A_DE, B_DE]=M,L
M: -3.5dB
L: 0dB
H: -6dB

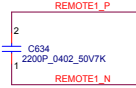
CAD Note: SATA_x_EQ
Equalization level setting for channel x(x=A,B),
internally tied to VDD/2
[x_EQ2, x_EQ1]=
L/M: for channel loss up to 2.4dB
L/L: for channel loss up to 7.4dB (CH A)
L/H: for channel loss up to 14.4dB
M/M: for channel loss up to 12.2dB
M/L: for channel loss up to 9.4dB
M/H: for channel loss up to 13.3dB
H/M: for channel loss up to 6.2dB
H/L: for channel loss up to 11.2dB
H/H: for channel loss up to 5dB (CH B)



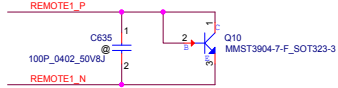
Theamal Sensor



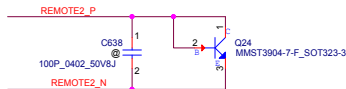
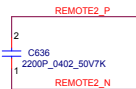
BRD Note:
Placed close to EMC1403



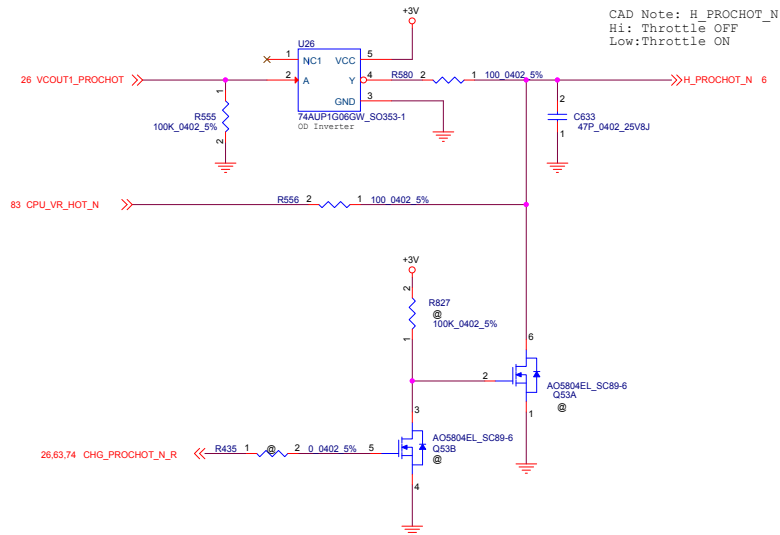
BRD Note:
Placed close to DDR
W/S=10:10



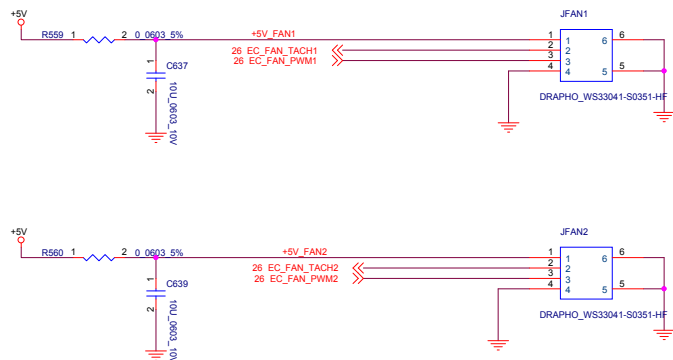
BRD Note:
Placed close to FAN



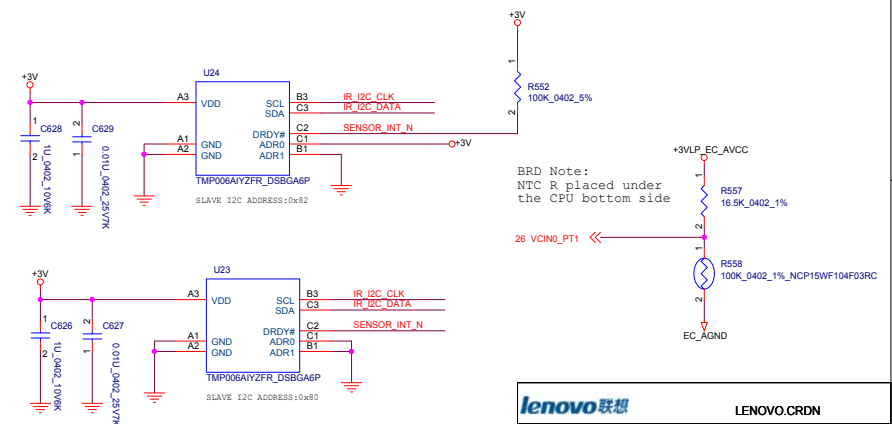
PROCHOT_N Logic



FAN CONN.



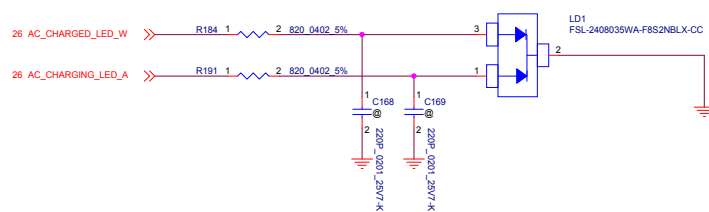
IR Sensor



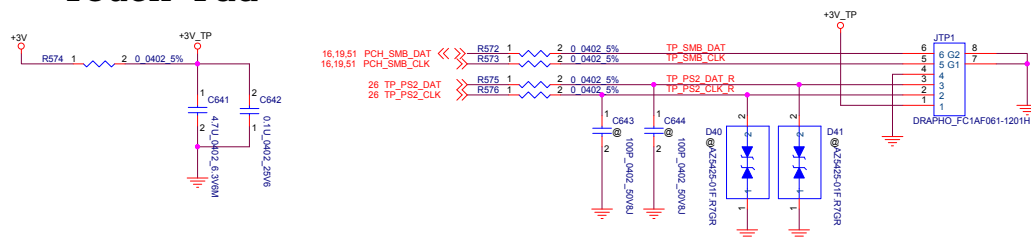
26.28 EC_I2C_CLKS <<< R550 1 2 0 0402 5% IR_I2C_CLK
26.28 EC_I2C_DATA5 <<< R551 1 2 0 0402 5% IR_I2C_DATA

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Title Thermal/IR Sensor/FAN			
Size C	Document Number Skylake-H	Rev V0.3	
Date: Thursday, May 26, 2016	Sheet 45	of 99	
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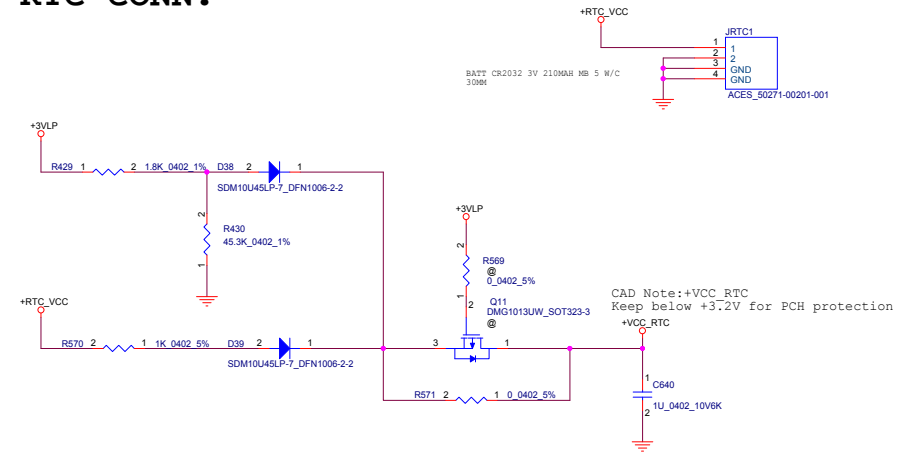
AC Charge LED



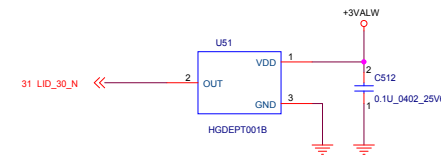
Touch Pad

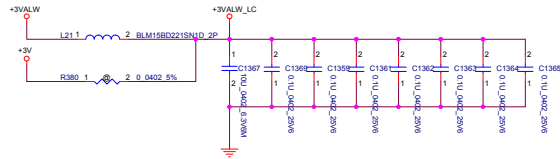


RTC CONN.

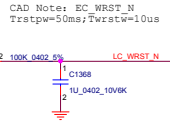


LID

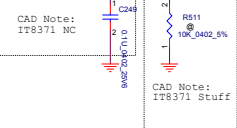
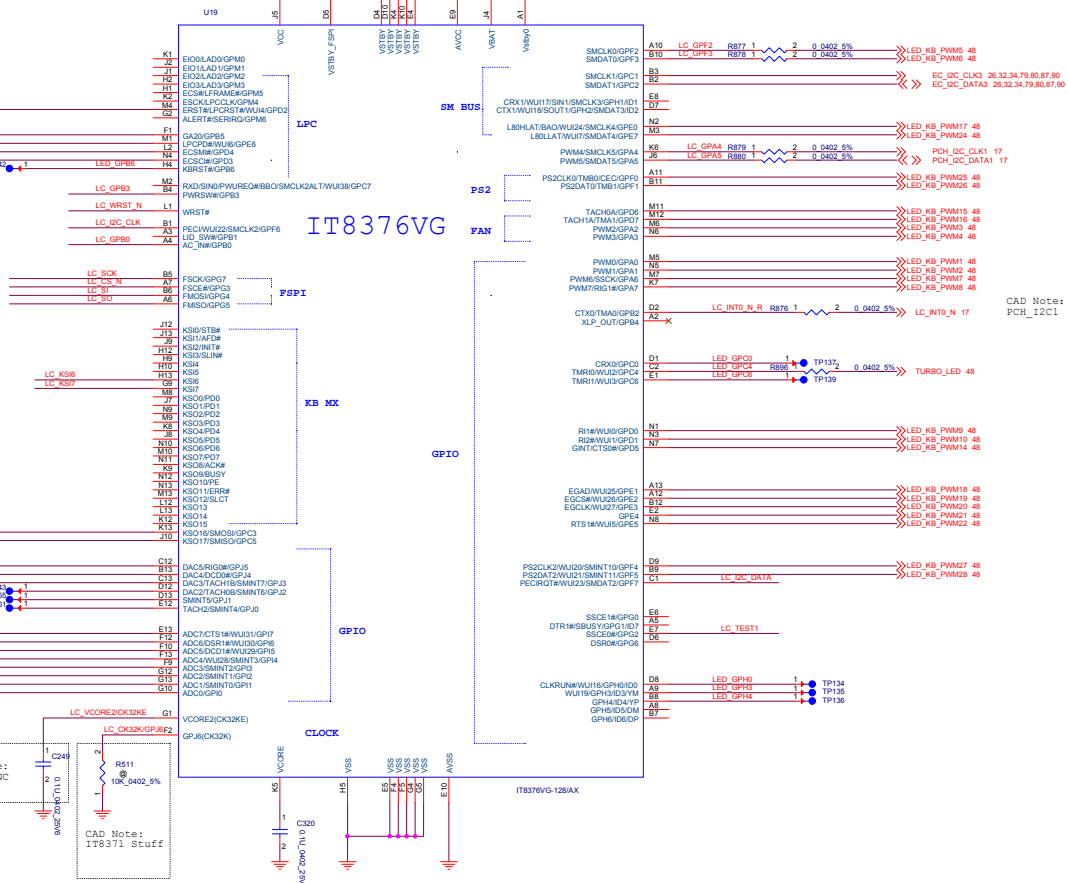




CAD Note:
FOR EC_I2C



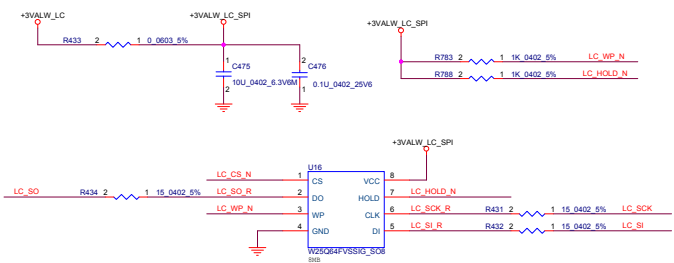
CAD Note: EC_WRST_N
Trstpw=50ms;Ttrstw=10us



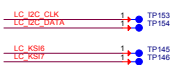
CAD Note:
IT8371 NC

CAD Note:
IT8371 Stuff

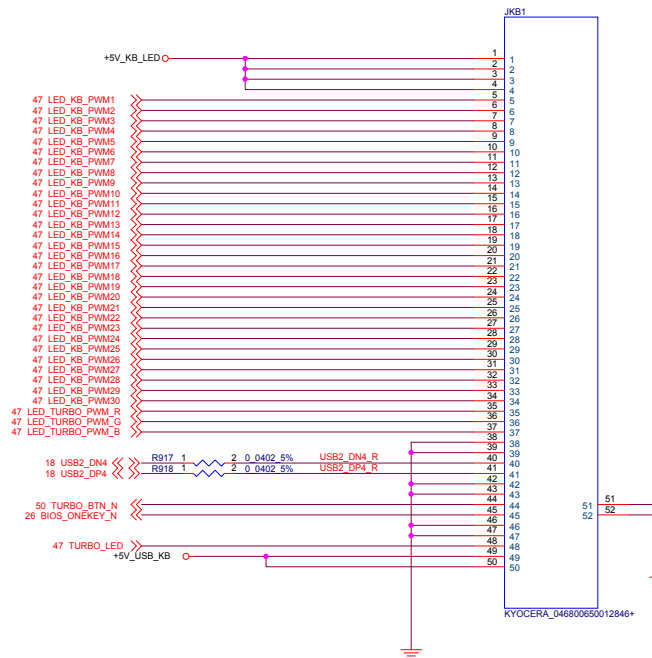
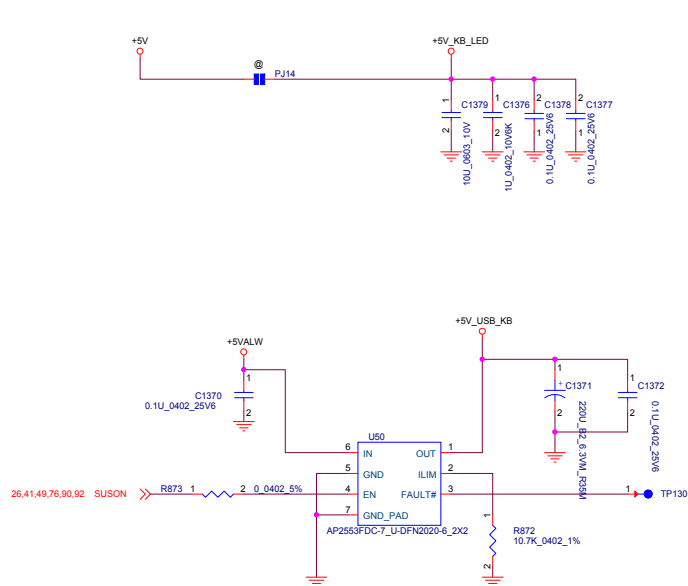
SPI ROM



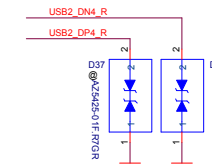
LC debug



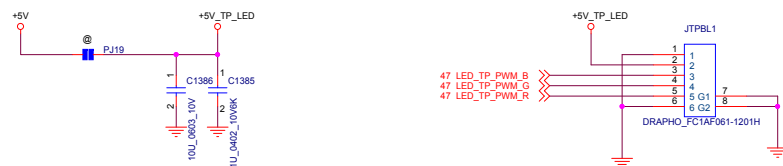
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LENOVO.CRDN			
File	LED Controller		
Size	Document Number	Rev	0.3
Custom	SkyLake-H		
Date	Thursday, May 26, 2016	Printed	27 of 69
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KB CONN.

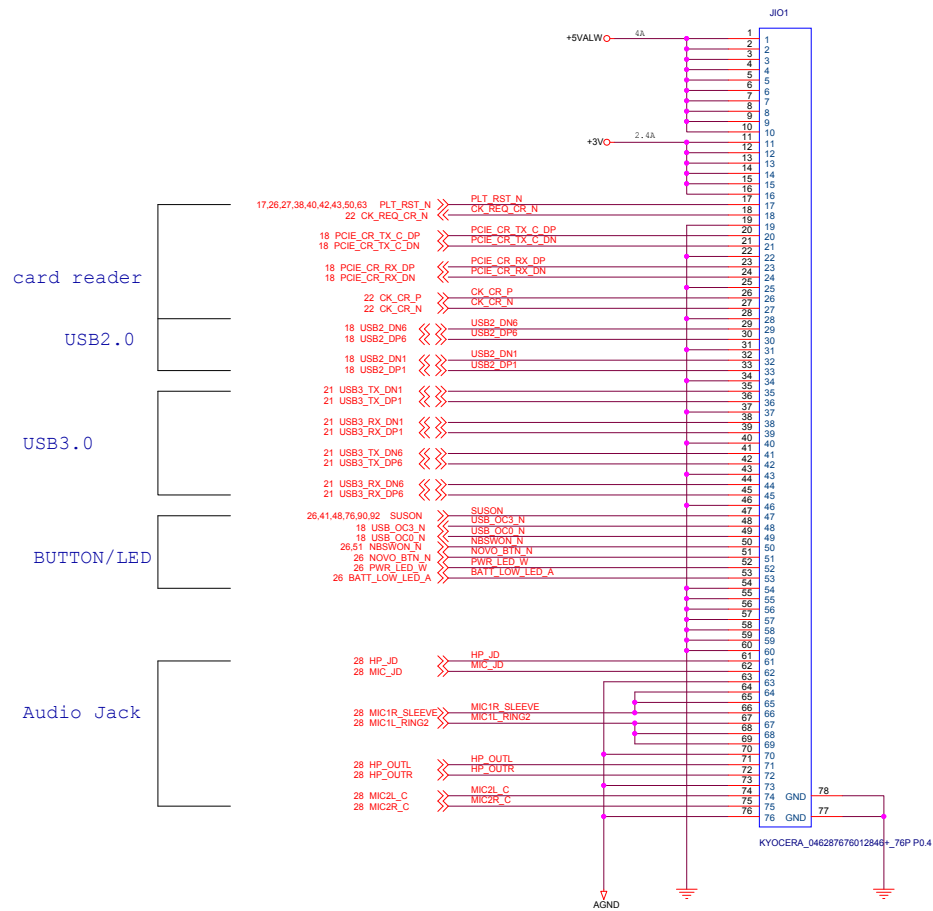


TP LED CONN.

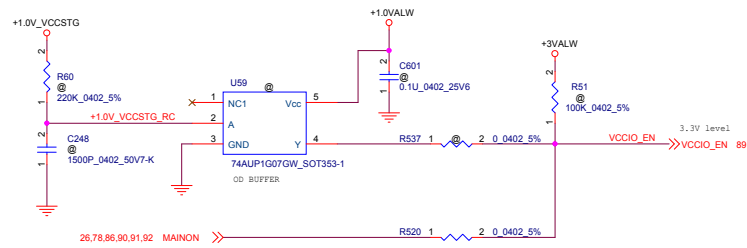


SPKR LED CONN.

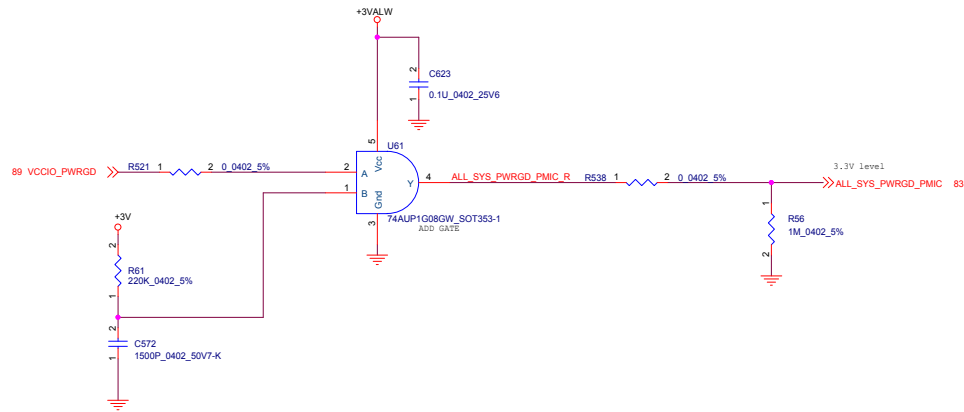




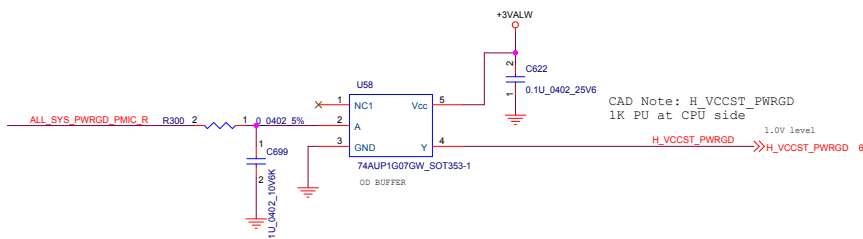
VCCIO_EN



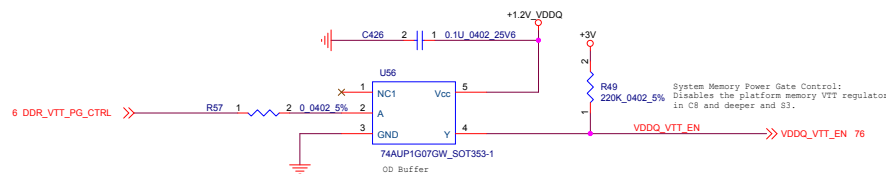
ALL_SYS_PWRGD_PMIC



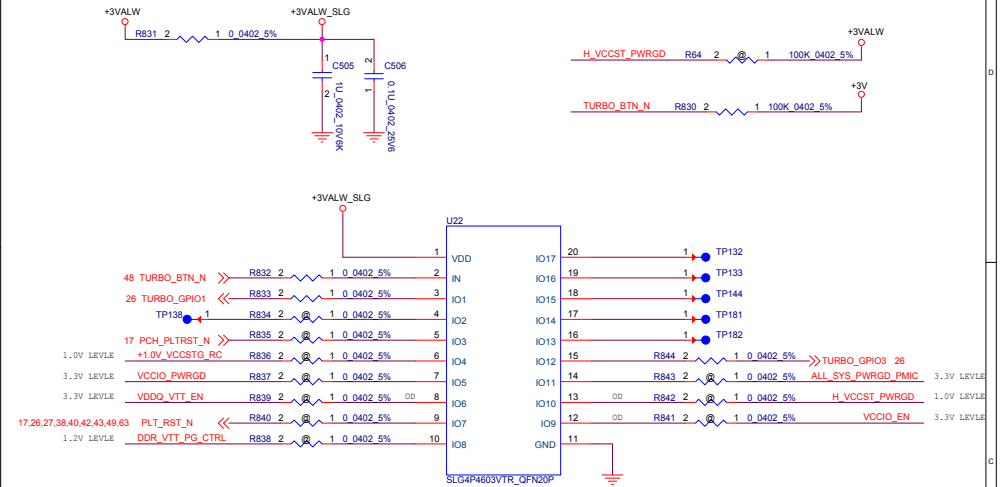
H_VCCST_PWRGD



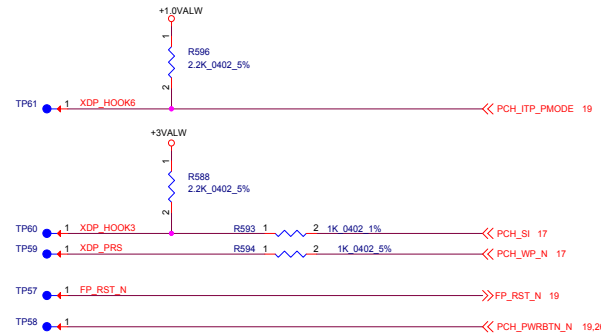
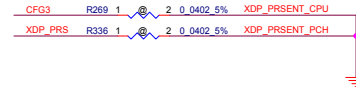
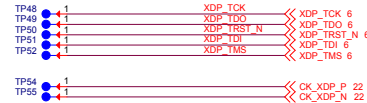
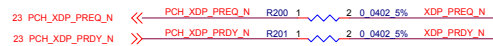
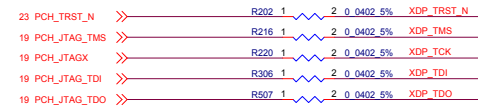
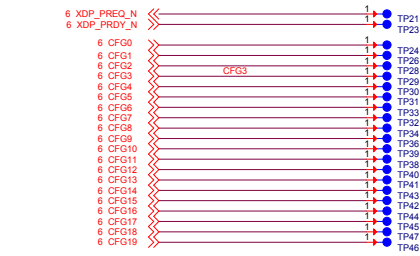
VDDQ_VTT_EN



SLG4P4603VTR

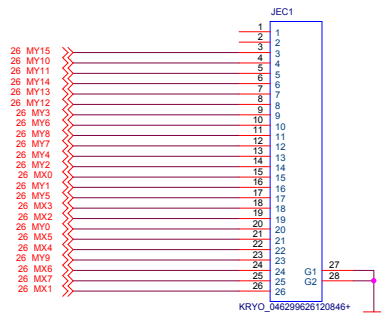


XDP CONN.



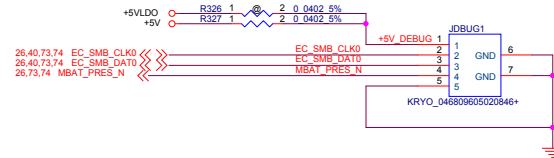
EC Debug CONN.

CAD Note:
For EC flash and debug



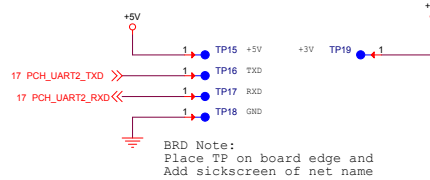
80 Port Debug CONN.

CAD Note:
For 80 port debug

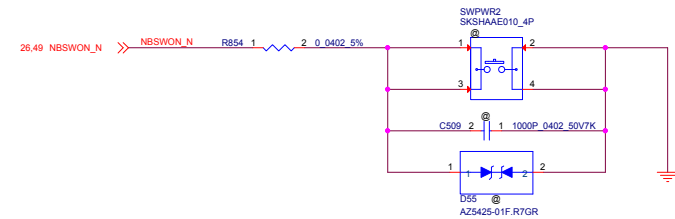


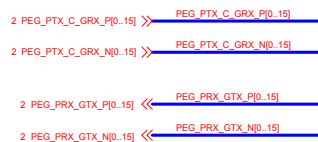
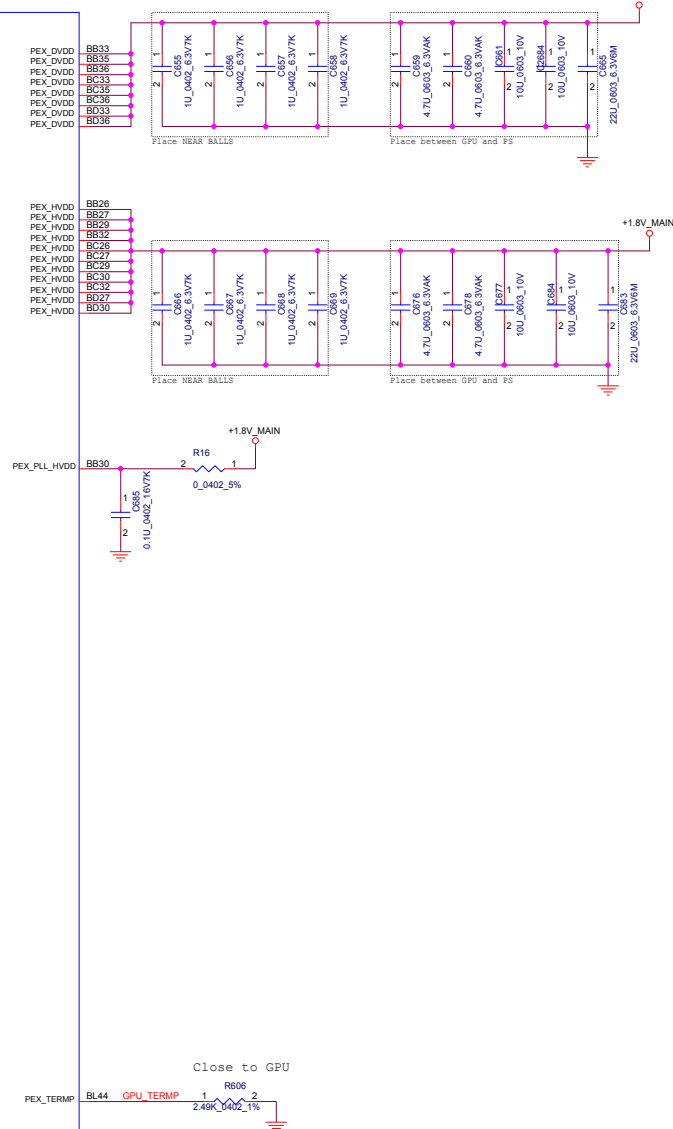
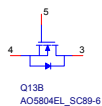
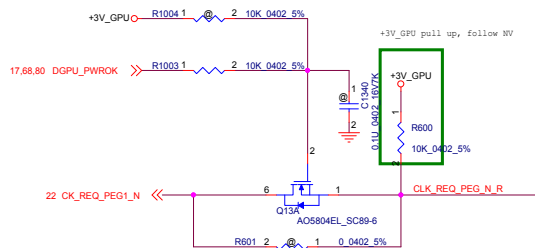
PCH UART Debug CONN.

CAD Note:
For PCH UART port debug



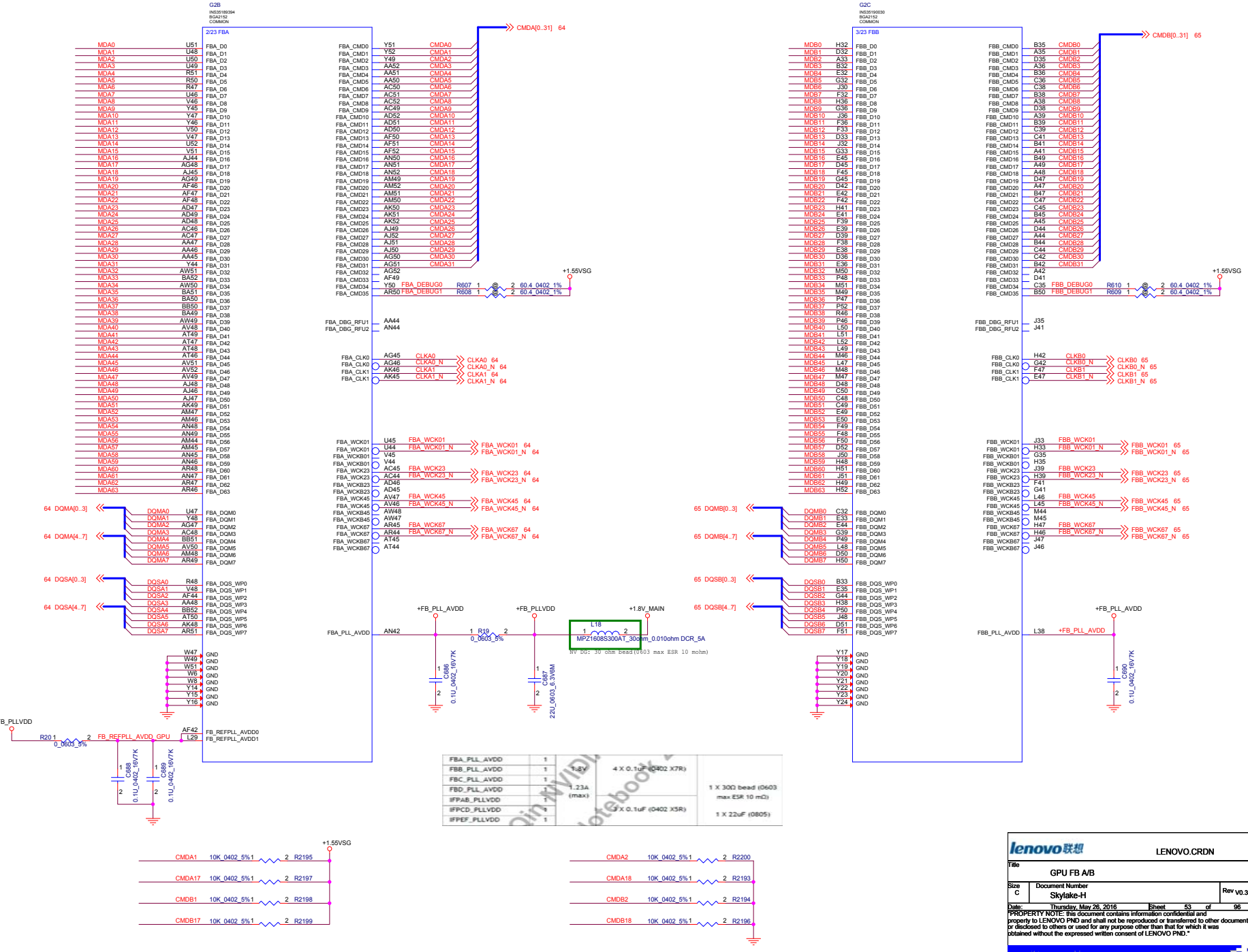
MB PWRBTN

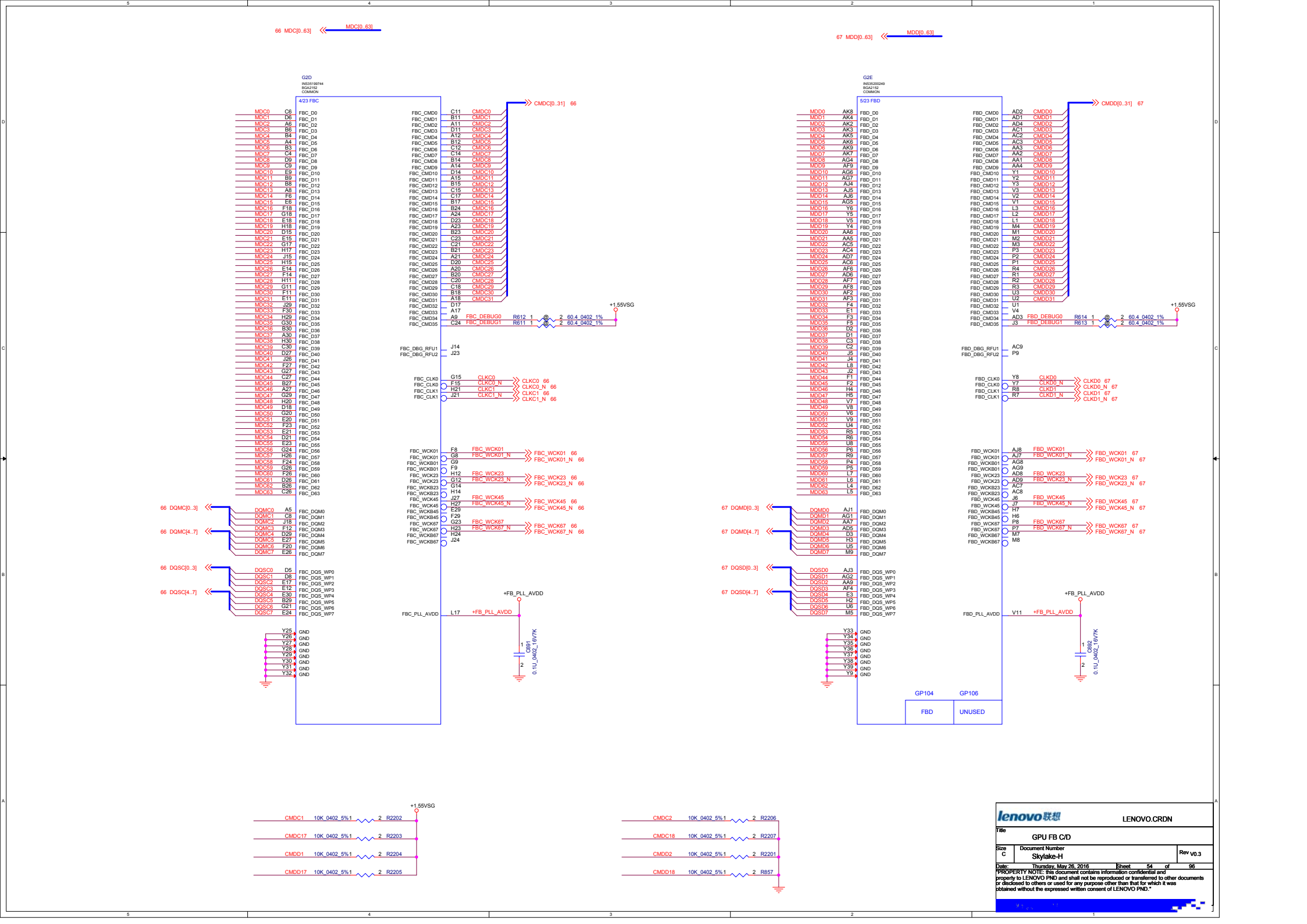


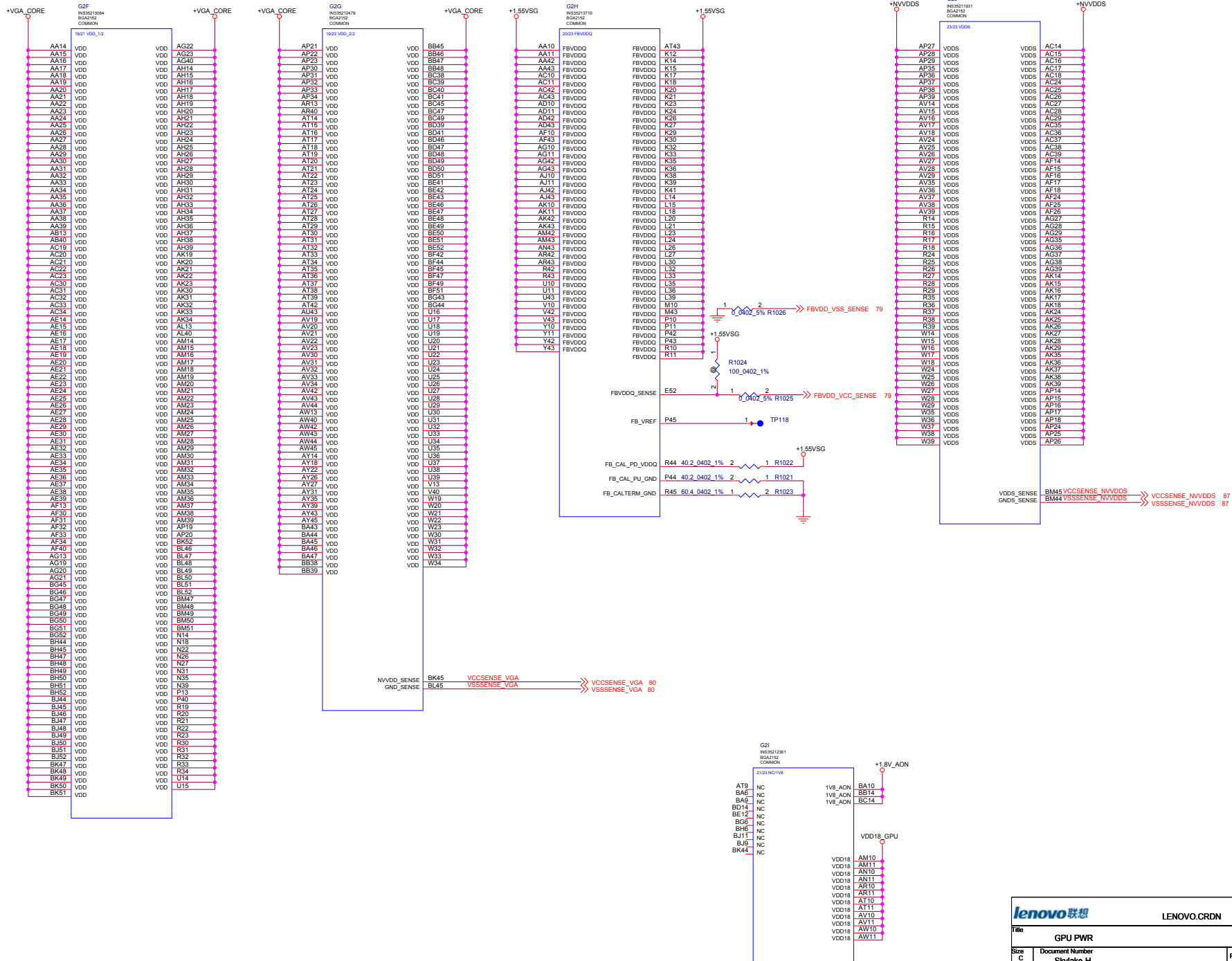


64 MDA[0..63] << MDA[0..63]

65 MDB[0..63] << MDB[0..63]

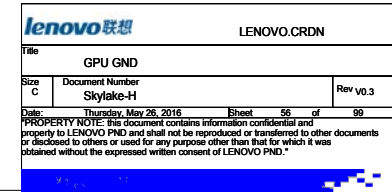


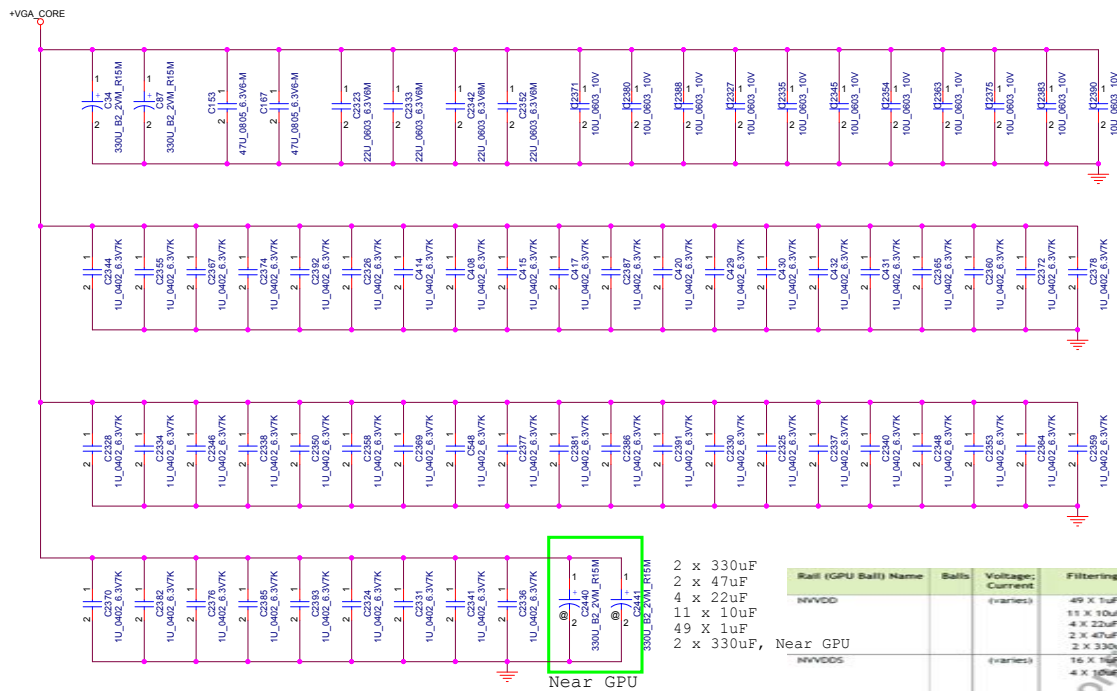




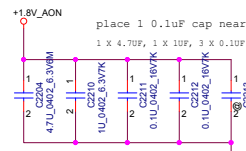
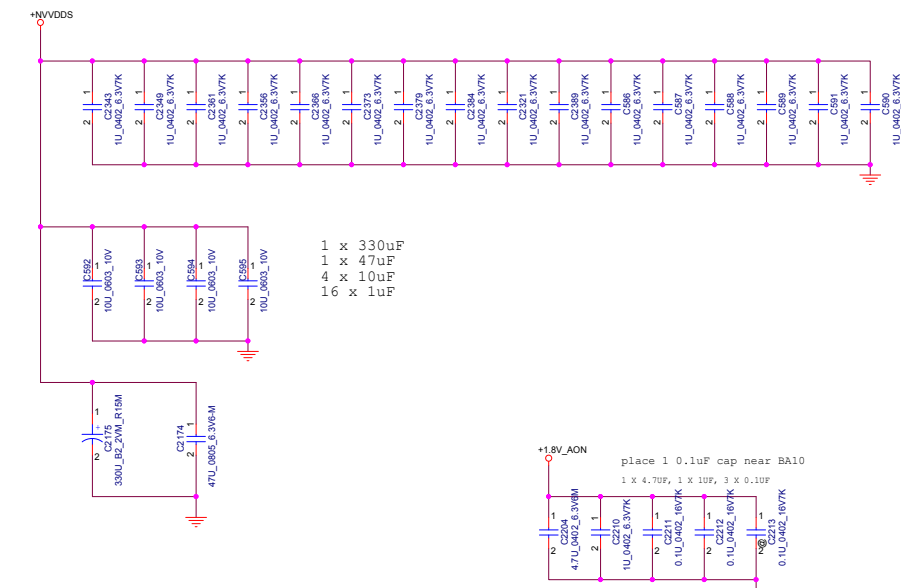
LENOVO.CRDN

File		GPU PWR	
Size		Document Number	
C		Skylake-H	
Date:		Thursday, May 26, 2016	Sheet 55 of 96
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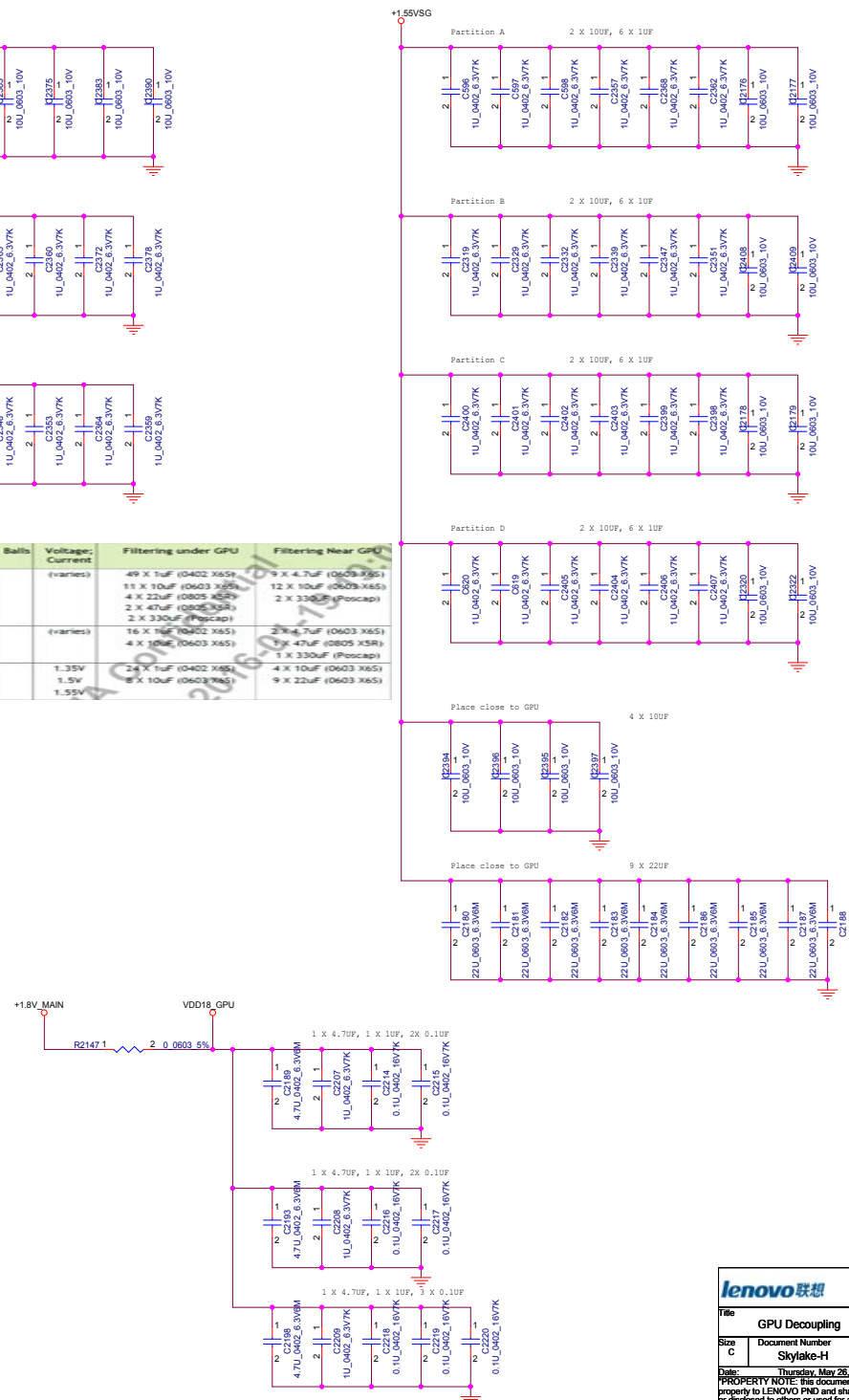


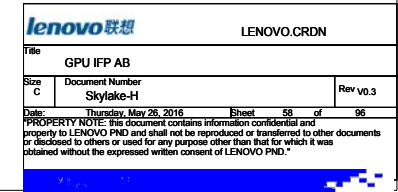
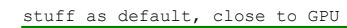


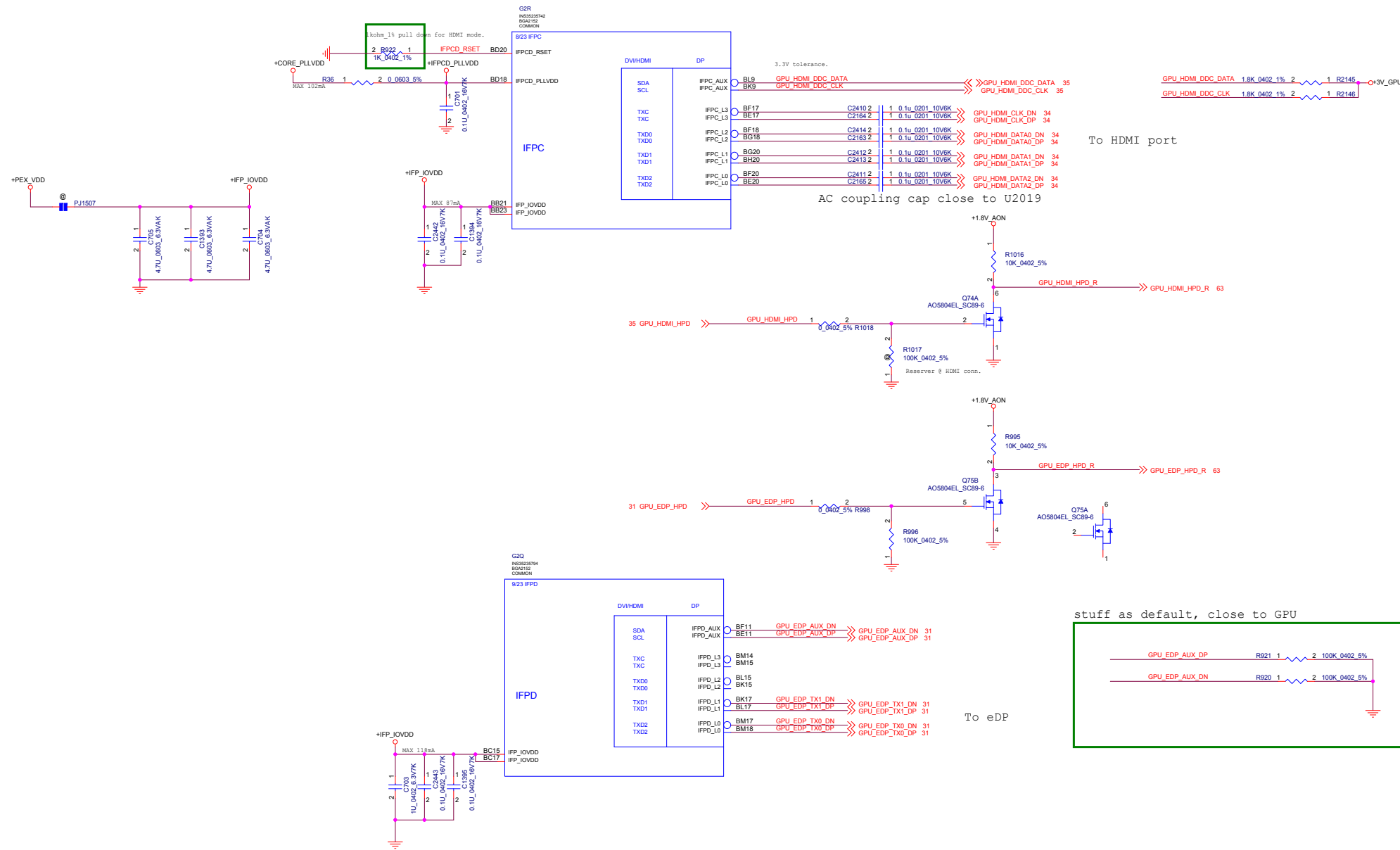
Rail (GPU Ball) Name	Balls	Voltage; Current	Filtering under GPU	Filtering Near GPU
Near GPU	INVIDO	(varies)	49 X 1uF (0402 X65) 18 X 10uF (0603 X85) 4 X 22uF (0805 X52) 2 X 47uF (0805 X38) 2 X 330uF (Pospac)	9 X 4.7uF (0805 X58) 12 X 10uF (0603 X85) 2 X 330uF (Pospac)
	INVIDS	(varies)	16 X 1uF (0402 X65) 4 X 10uF (0603 X65)	2 X 4.7uF (0603 X65) 1 X 47uF (0805 X58) 1 X 330uF (Pospac)
	FBIQDO (GPU side) ³	1.35V 1.5V 1.55V	24 X 1uF (0402 X65) 5 X 10uF (0603 X65)	4 X 10uF (0603 X65) 9 X 22uF (0603 X65)

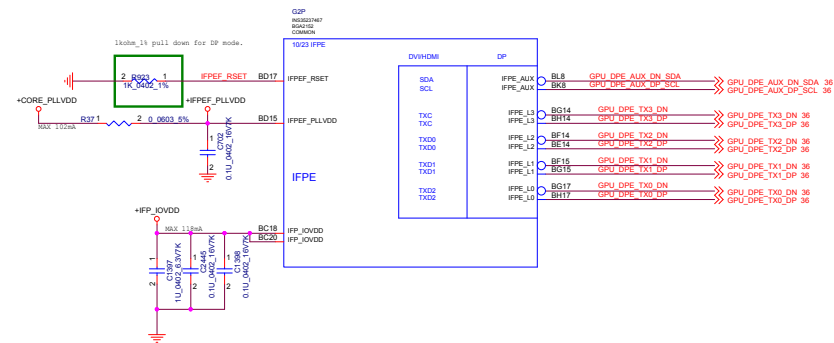


place 1 0.1uf cap for BB14 and BC14 to share



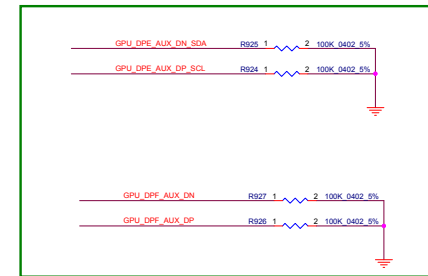




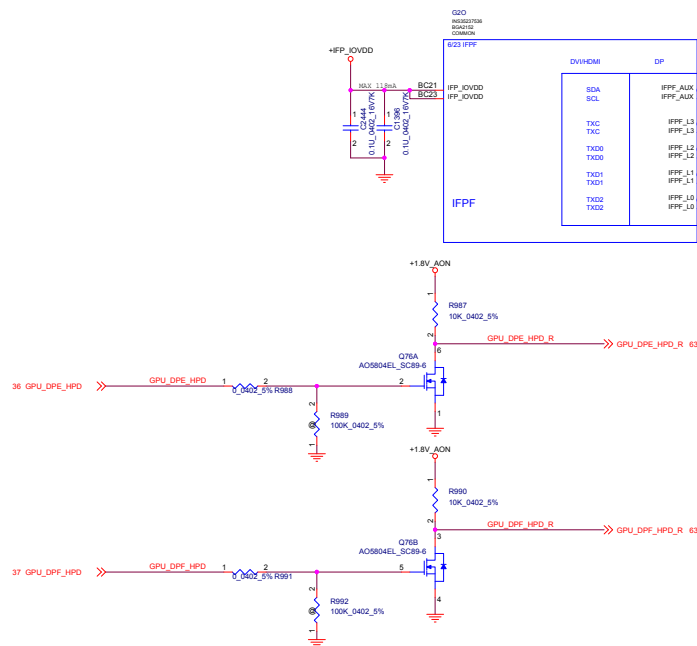


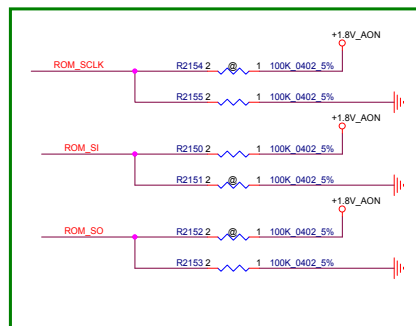
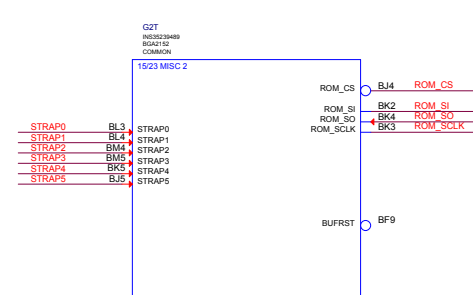
AR DP1


stuff as default, close to GPU

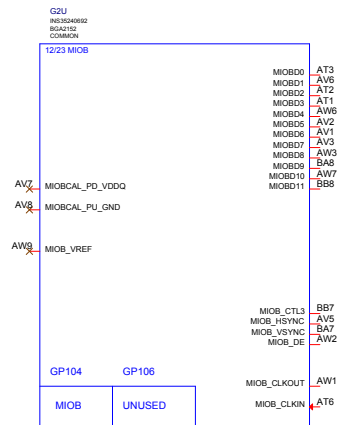
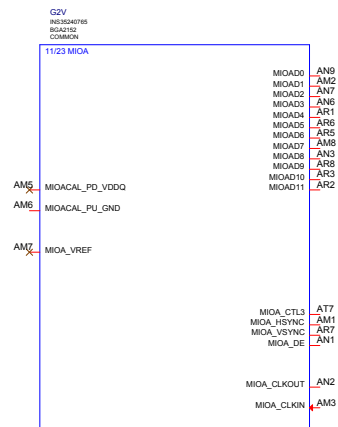


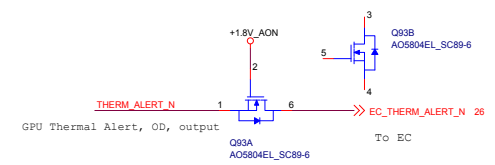
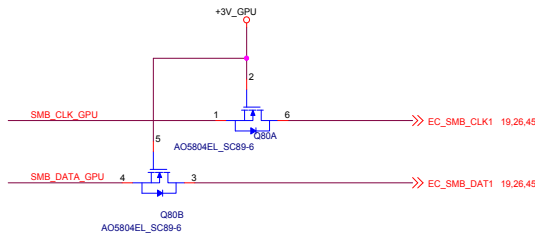
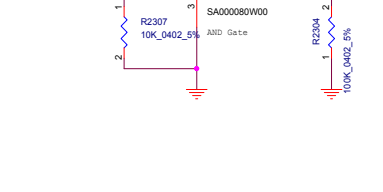
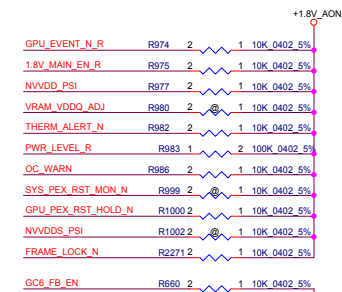
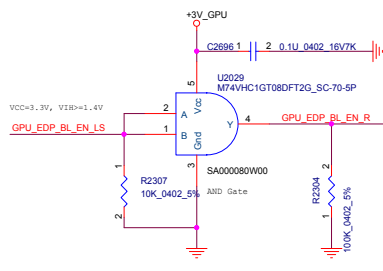
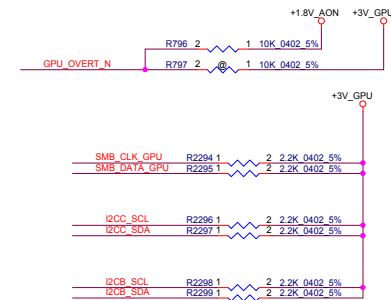
AR DP2



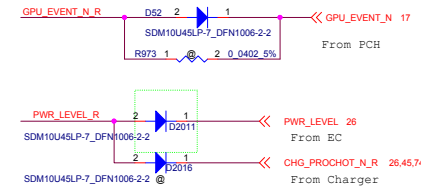
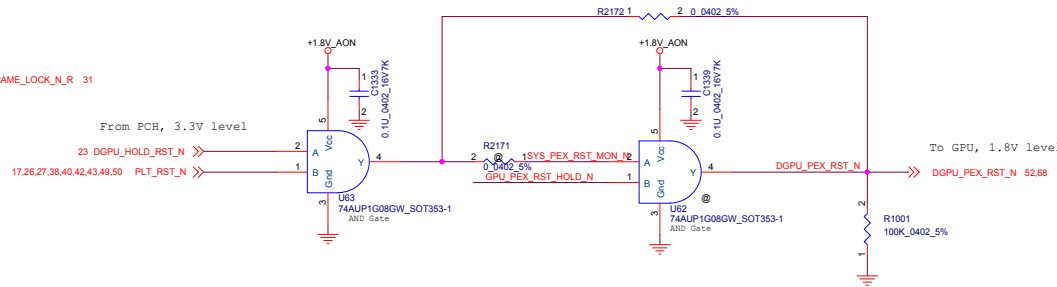
ROM SCLK (LSB) / ROM SI / ROM SO (MSB) :

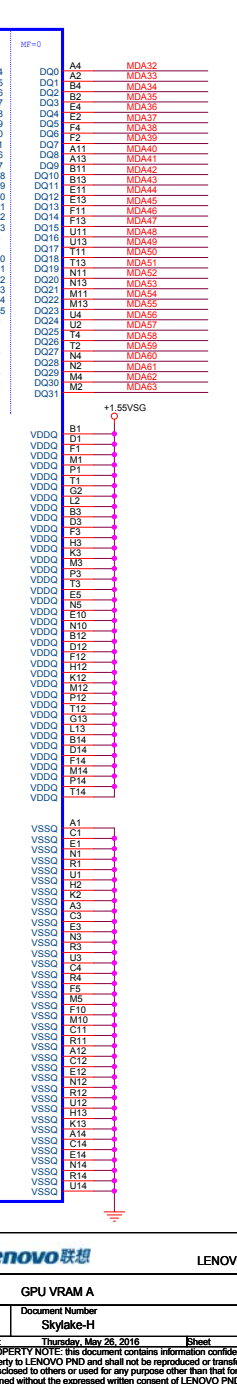
 联想		LENOVO.CRDN	
Title			
GPU PLL/KTAL			
Size	Document Number	Rev	
C	Skylake-H	v0.3	
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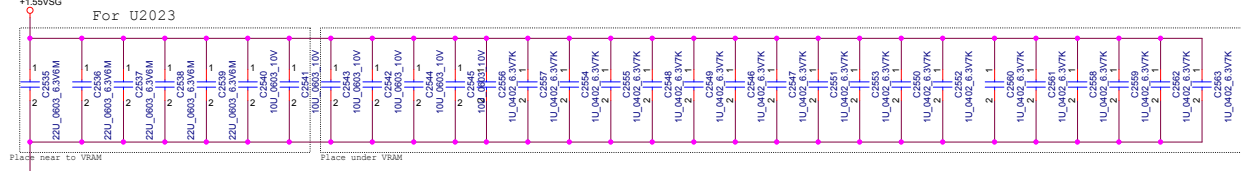


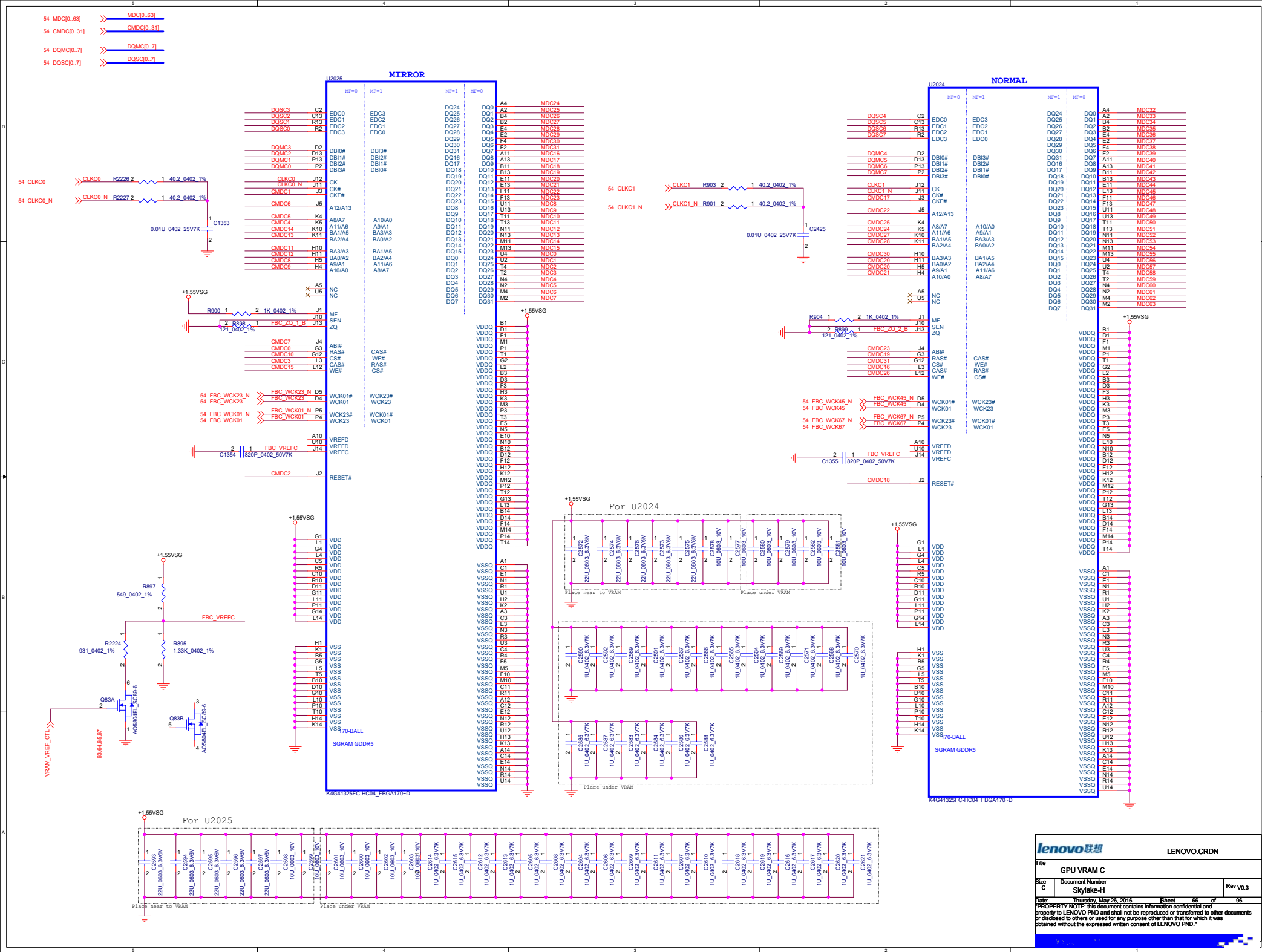
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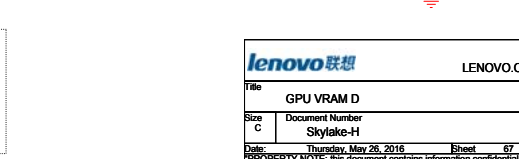
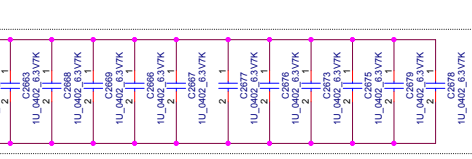
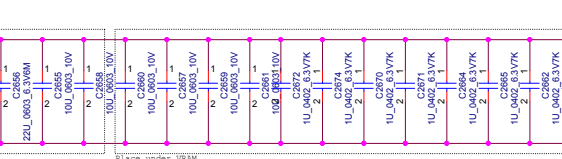
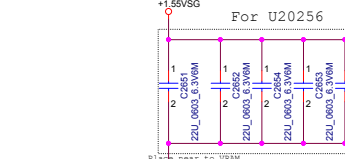
The schematic diagram shows the internal circuitry of the AO5804EL_SC89-6 driver. It features a +3V_EDP supply connected to a 10K pull-up resistor R784. The input signal, FRAME_LOCK_N (active low), is connected to the gate of MOSFET Q48A through a 10K resistor R780. MOSFET Q48A is an AO5804EL_SC89-6 device. The output of Q48A is connected to the gate of MOSFET Q48B, which is also an AO5804EL_SC89-6 device. The output of Q48B is connected to the GPU_EDP_VDD_EN_LS signal line. A 0.1µF capacitor C885 is connected between the output of Q48A and ground. The circuit is powered by +3V_EDP and ground.

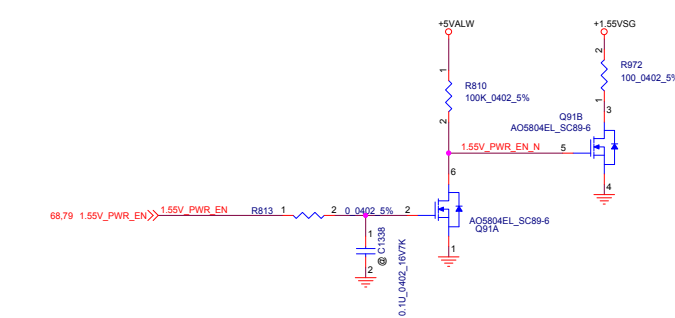
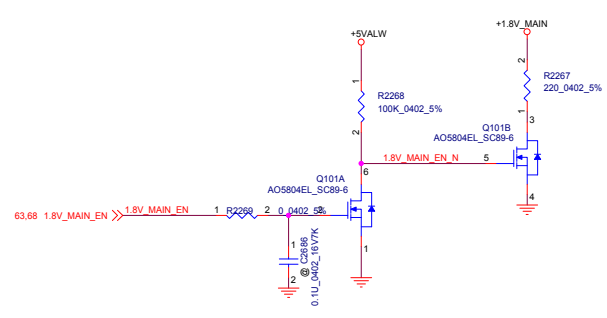
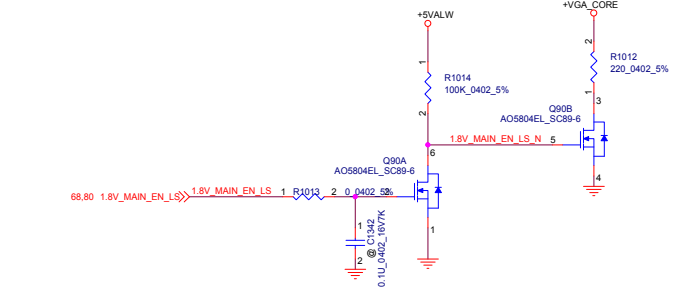
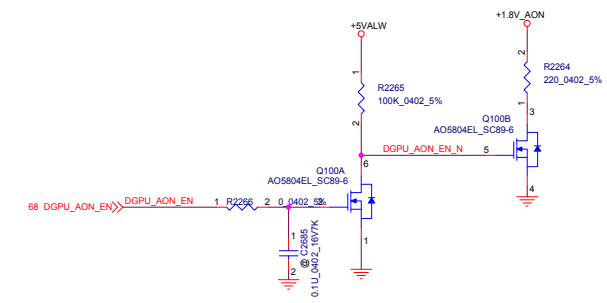
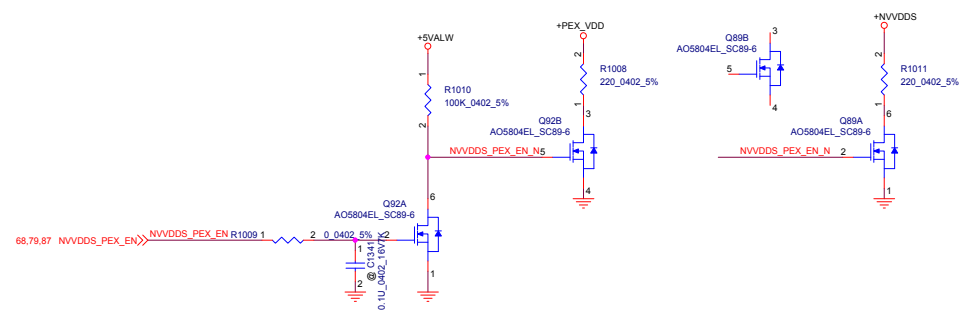
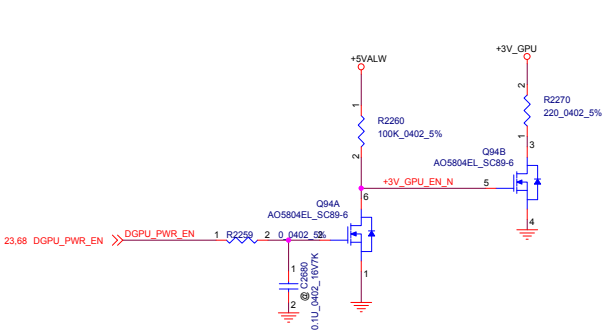








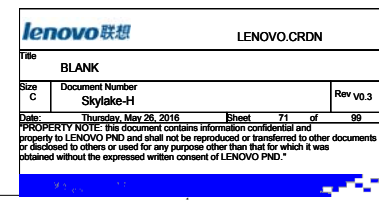







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C				C
B				B
A				A

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File			
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Size	Document Number		Rev
C	Skylake-H		V0.3
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A				A

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Skylake-H

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V0.3

Date

Thursday, May 26, 2016


Sheet

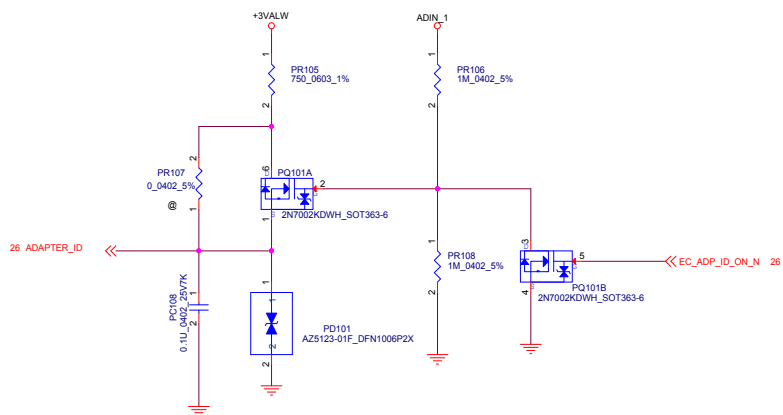
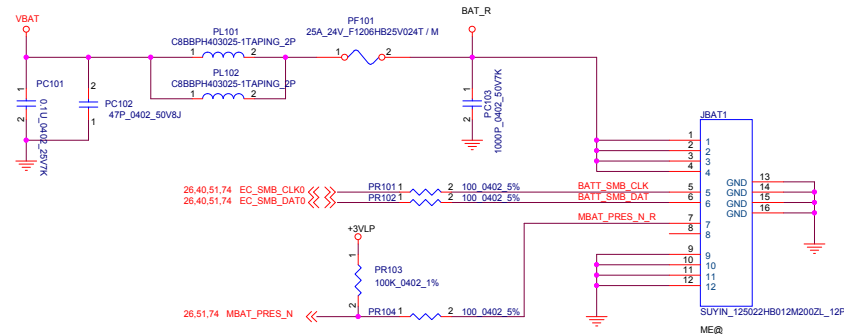
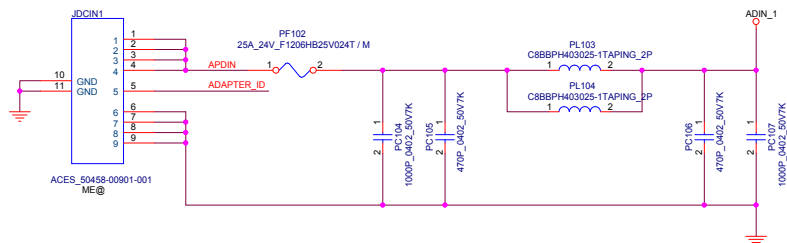
72

of

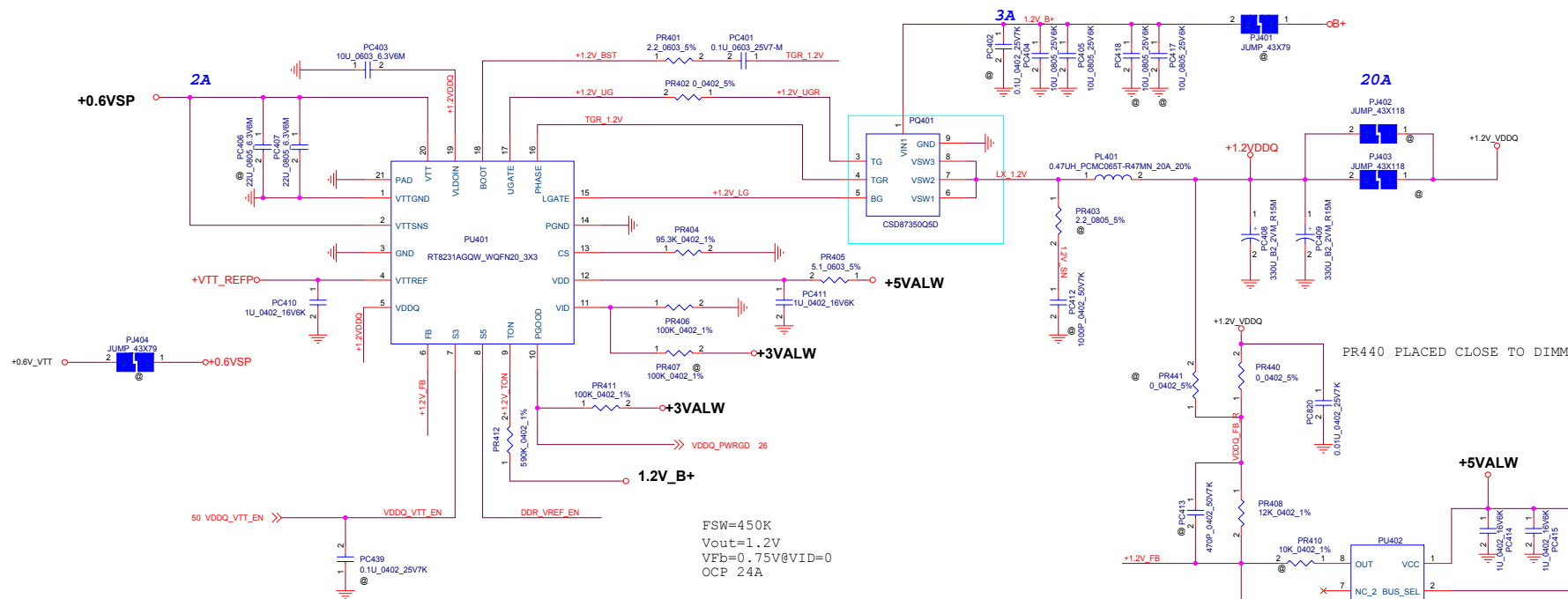
99

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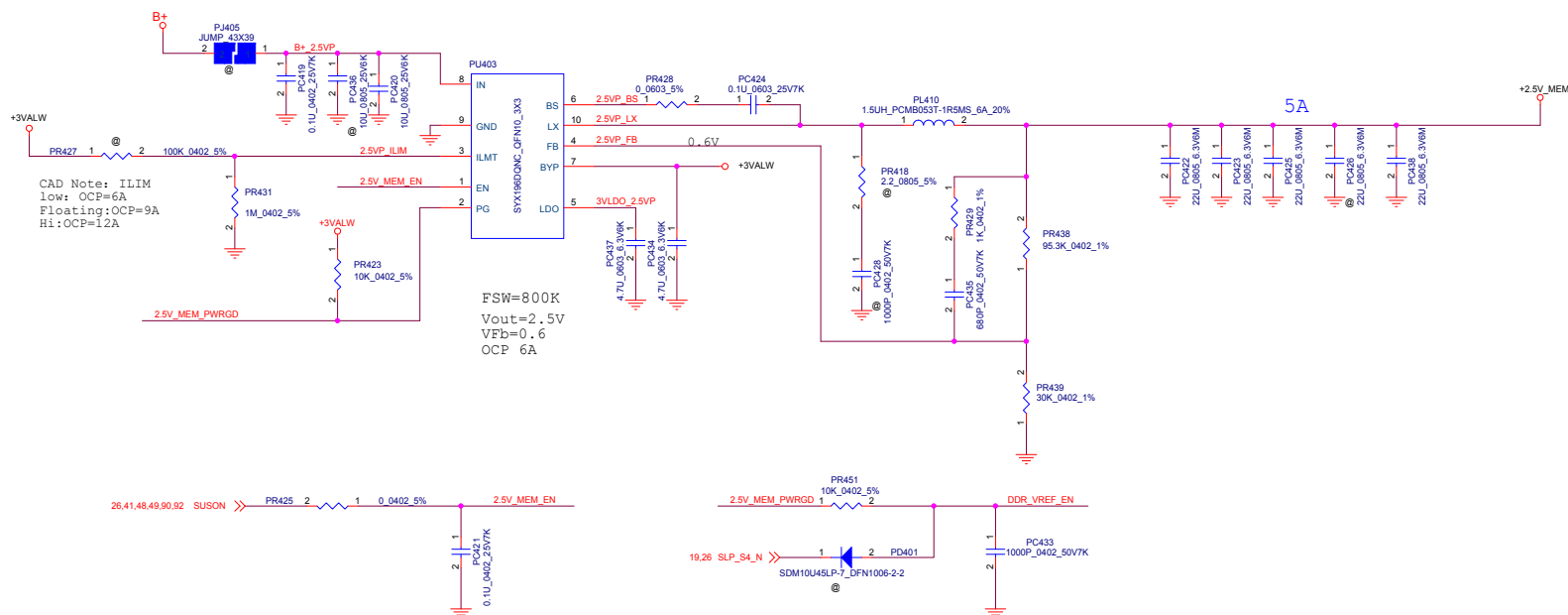
BATT CONN.



STATE	SUSON	MAINON	+1.2V_VDDQ	+0.6V_VTT
S0	HI	HI	ON	ON
S3	HI	LOW	ON	OFF(High-Z)
S5	LOW	LOW	OFF(Discharge)	OFF(Discharge)

Address	0X6A	0X68	0X66	0X64	0X62	0X60
TOP R (Kohm)	OPEN	3.9	3	2.3	1.3	10
BOT R (Kohm)	10	1.3	2.3	3	3.9	OPEN
Bus_sel Volt (% of VCC)	0%	25%	40%	60%	75%	100%

ADDR 0X62



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Title

PWR-1.2VDDQ/VTT/2.5V

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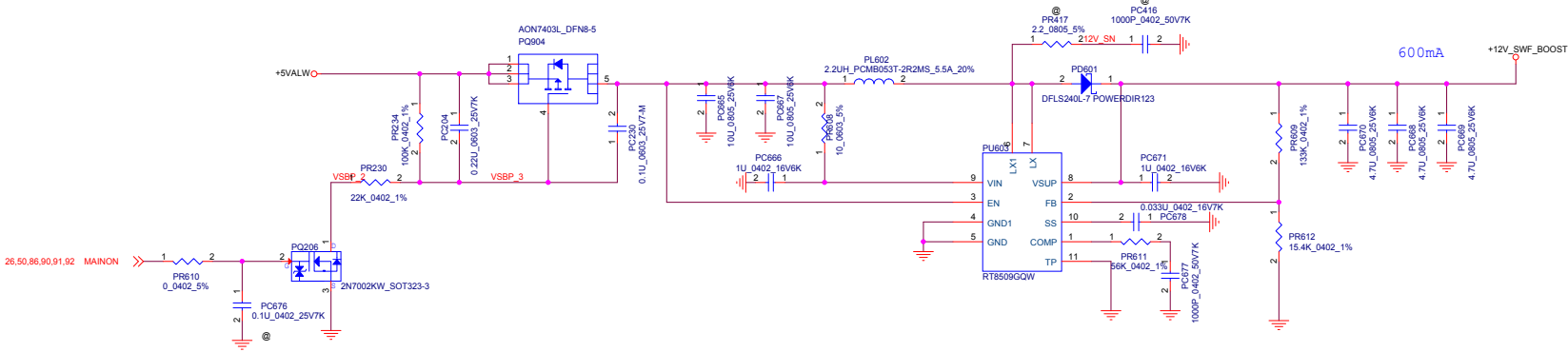
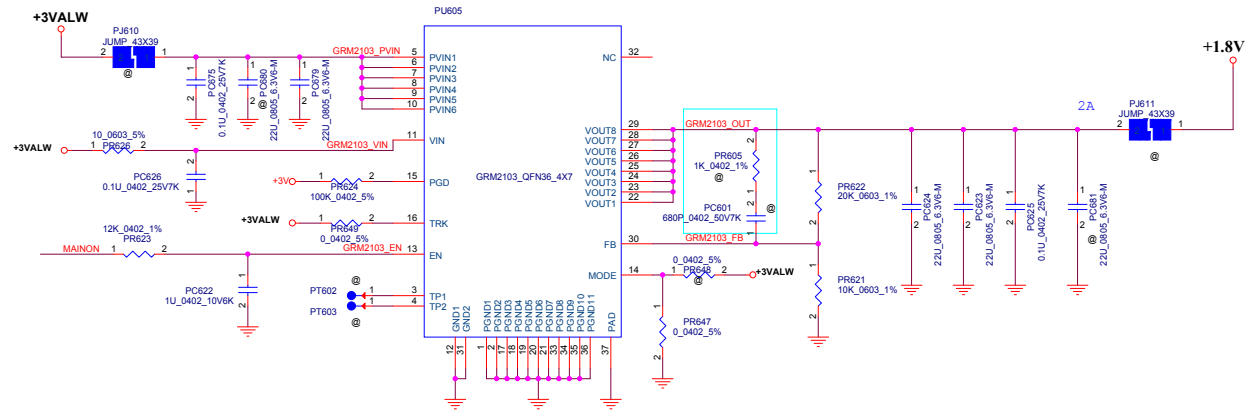
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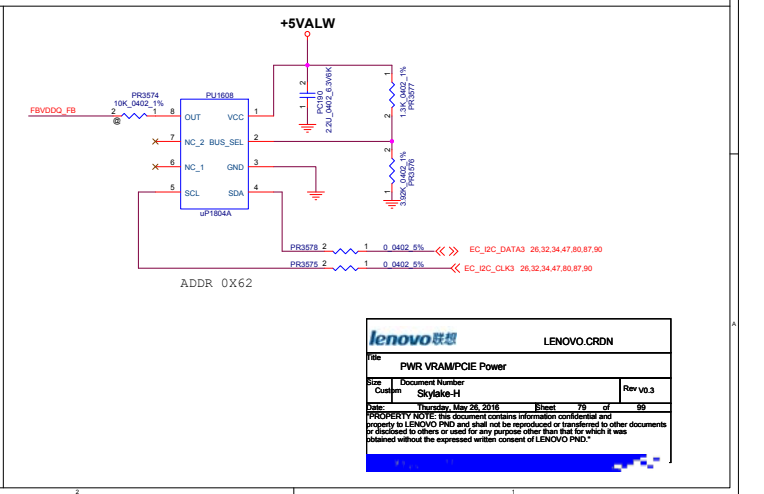
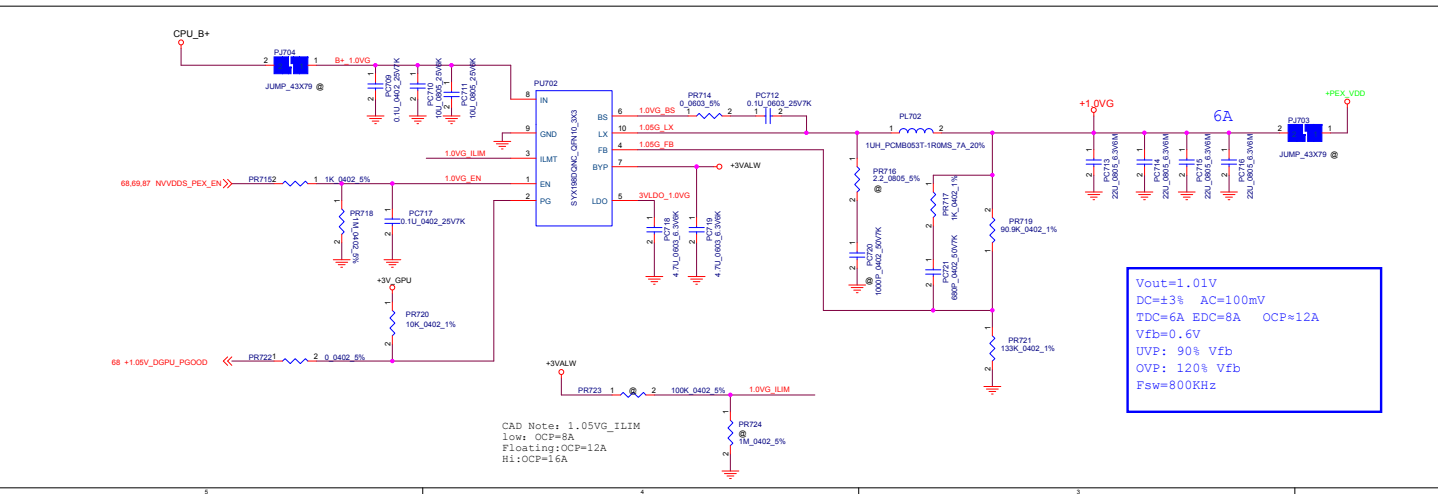
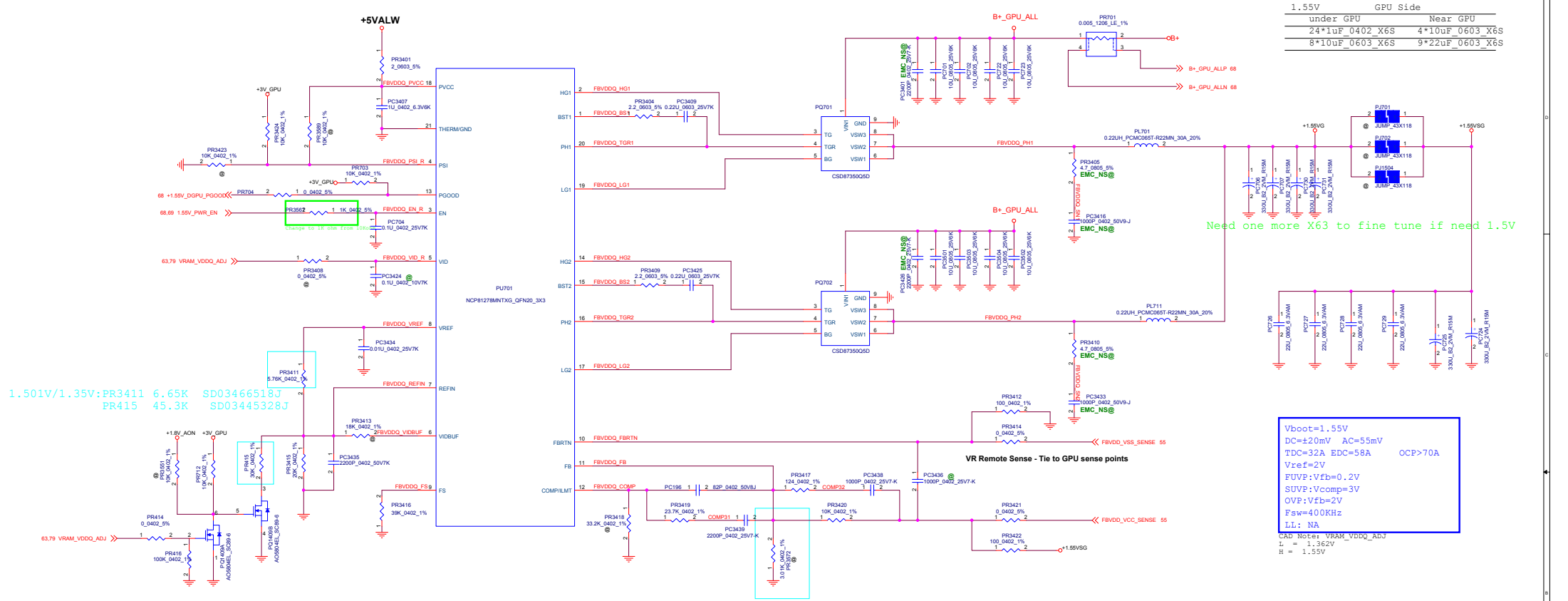
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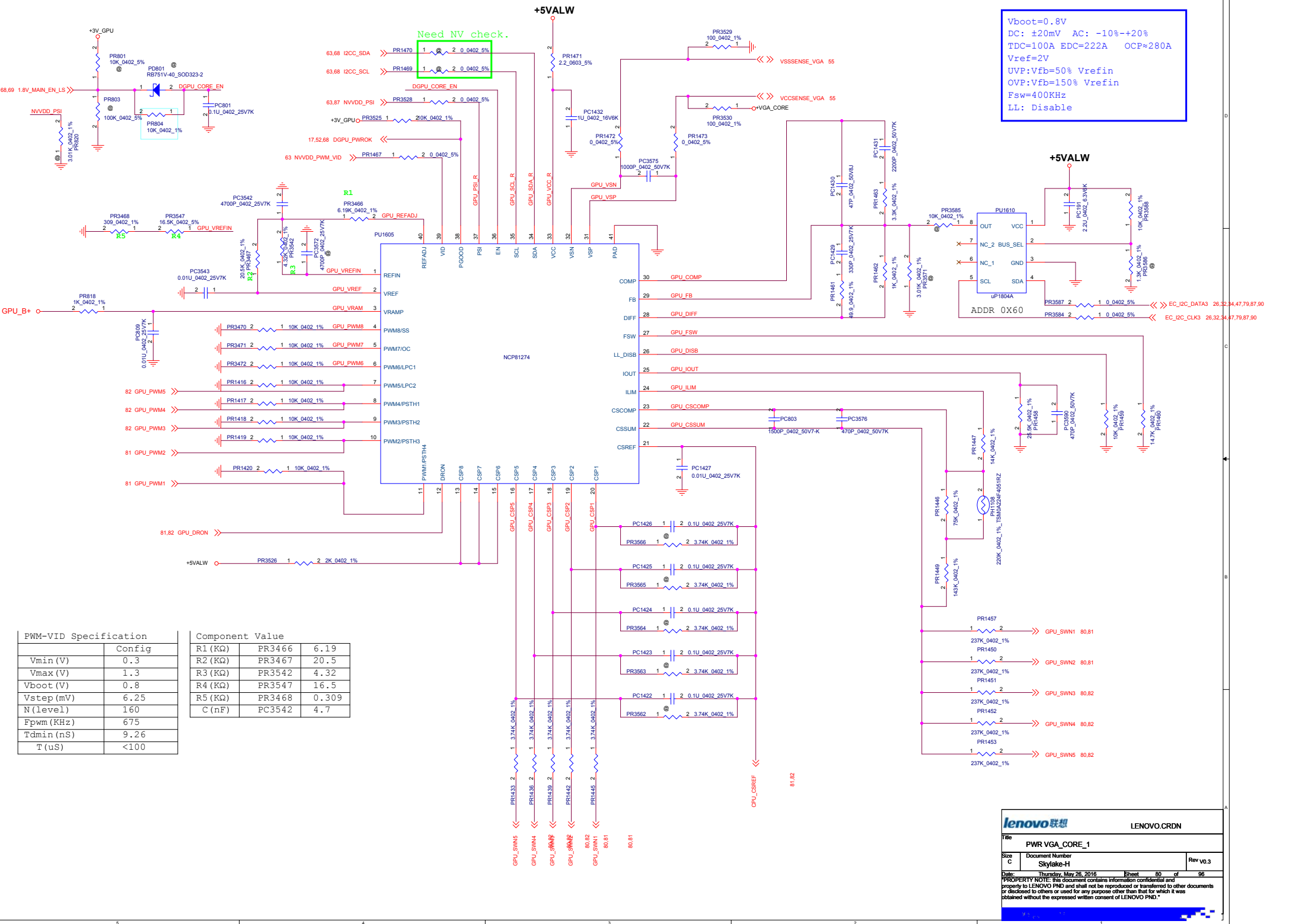
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PWM-VID Specification	
Config	
Vmin (V)	0.3
Vmax (V)	1.3
Vboot (V)	0.8
Vstep (mV)	6.25
N (level)	160
Fpwm (KHz)	675
Tdmin (nS)	9.26
T (uS)	<100

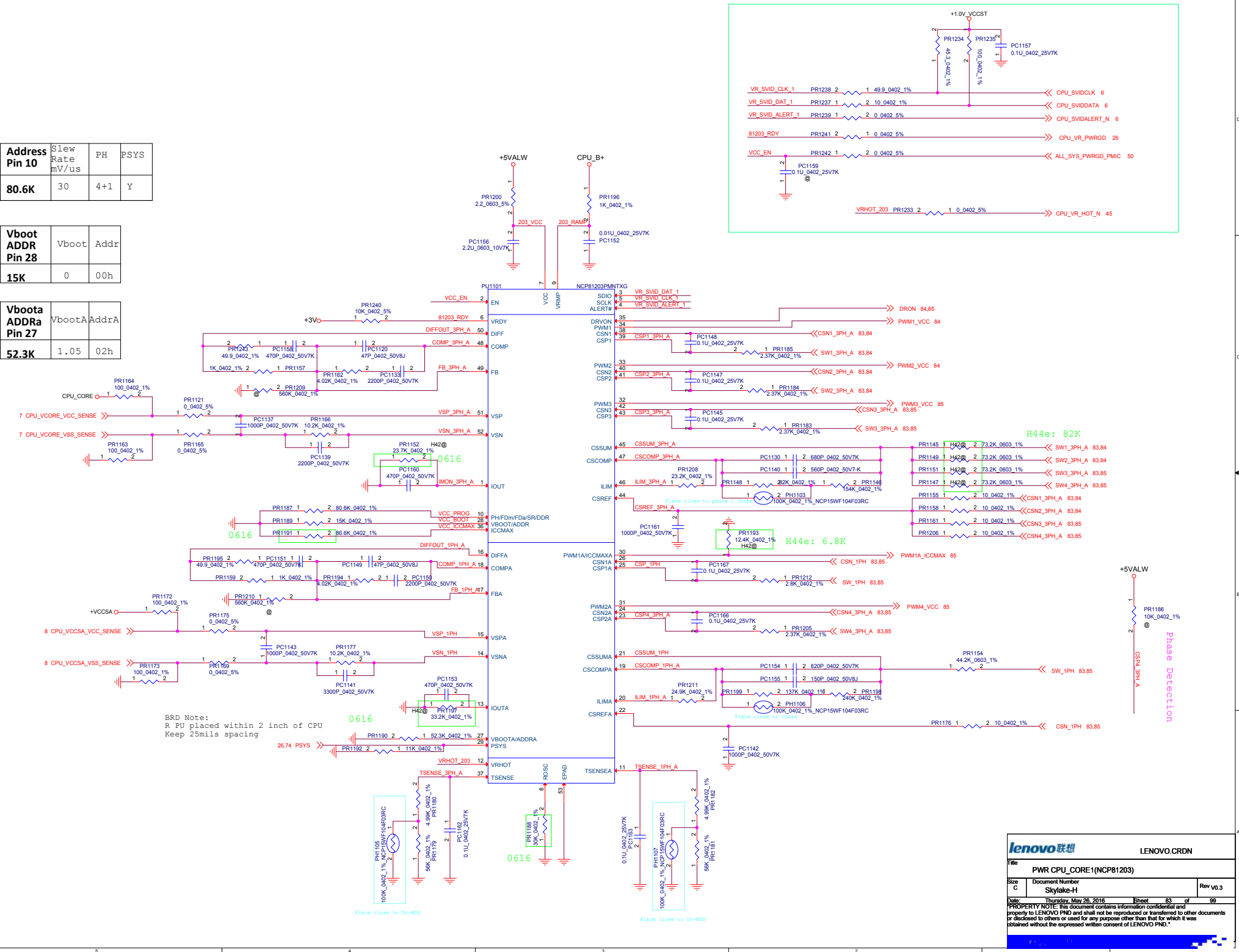
Component Value		
R1 (KΩ)	PR3466	6.19
R2 (KΩ)	PR3467	20.5
R3 (KΩ)	PR3542	4.32
R4 (KΩ)	PR3547	16.5
R5 (KΩ)	PR3468	0.309
C (nF)	PC3542	4.7

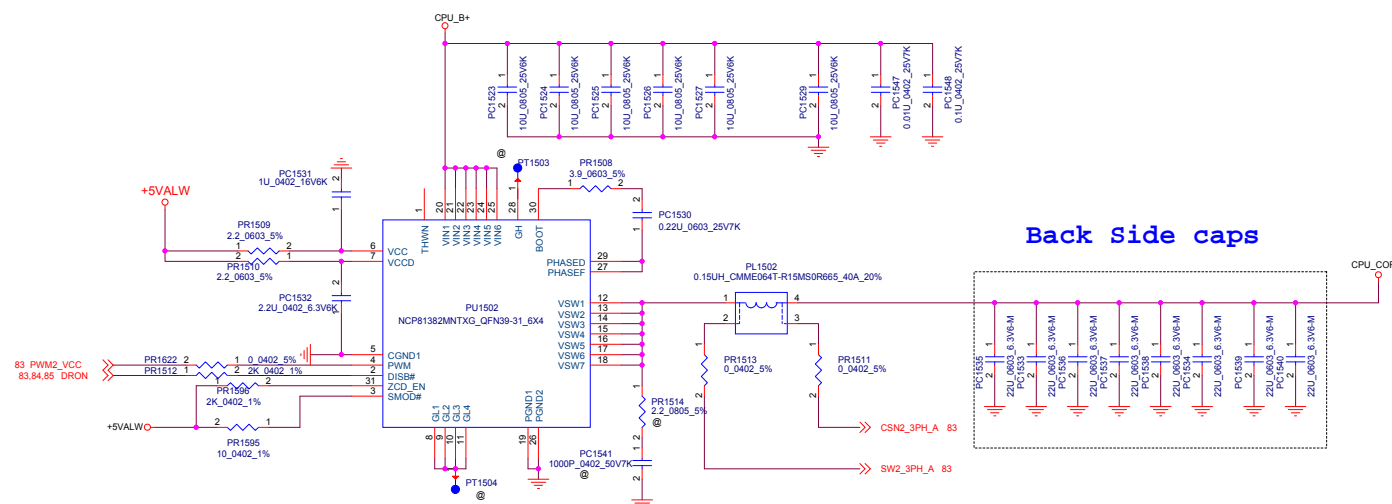
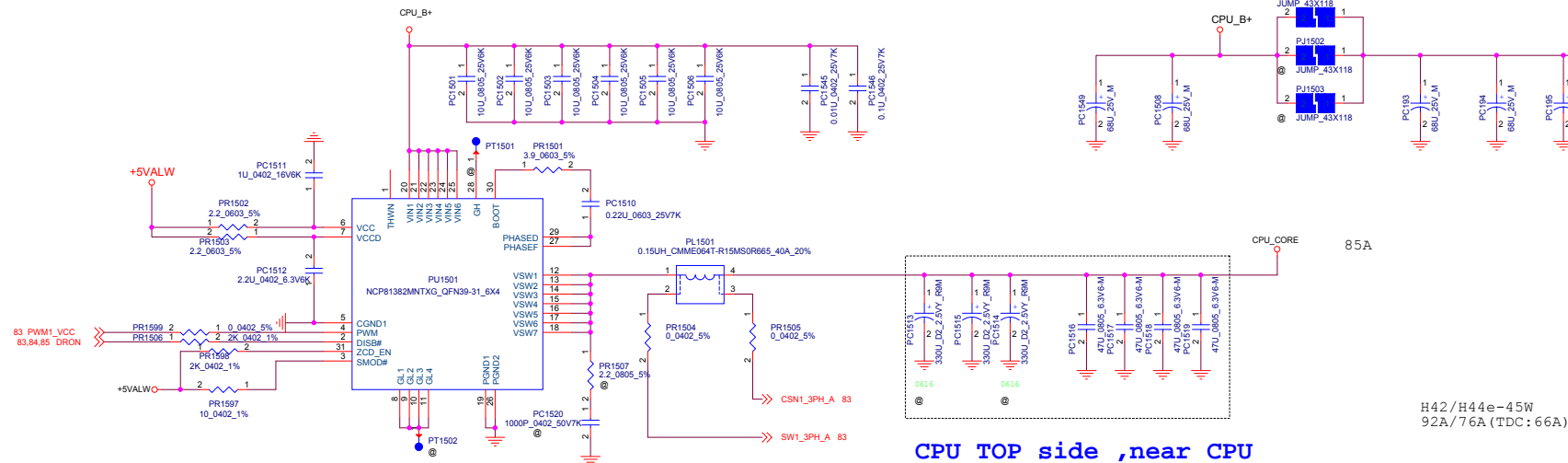
Vboot=0.8V
DC: ±20mV AC: -10%~+20%
TDC=100A EDC=222A OCP≈280A
Vref=2V
UVP:Vfb=50% Vrefin
OVP:Vfb=150% Vrefin
Fsw=400KHz
LL: Disable

Address Pin 10	Slew Rate mV/us	PH	PSYS
80.6K	30	4+1	Y

Vboot ADDR Pin 28	Vboot	Addr
15K	0	00h

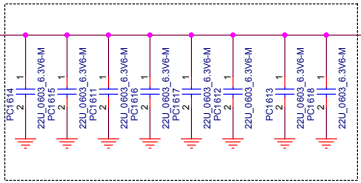
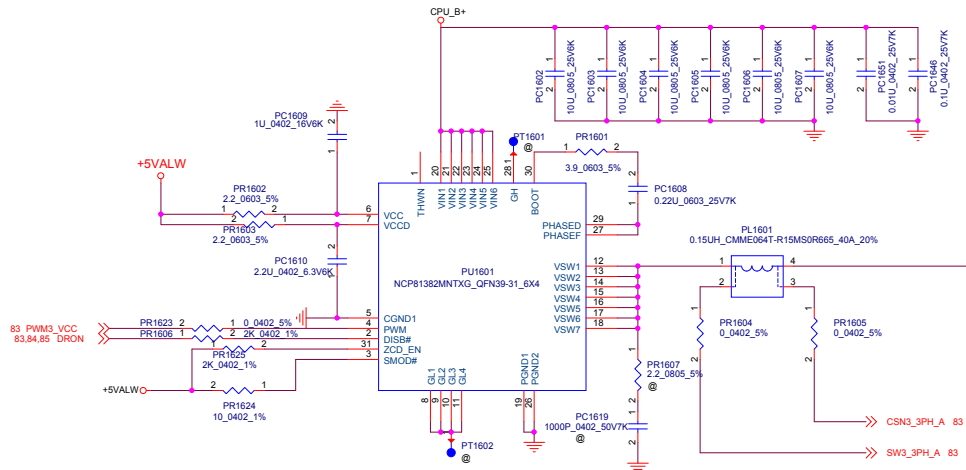
Vboota ADDRa Pin 27	VbootA	AddrA
52.3K	1.05	02h



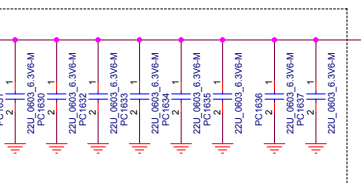
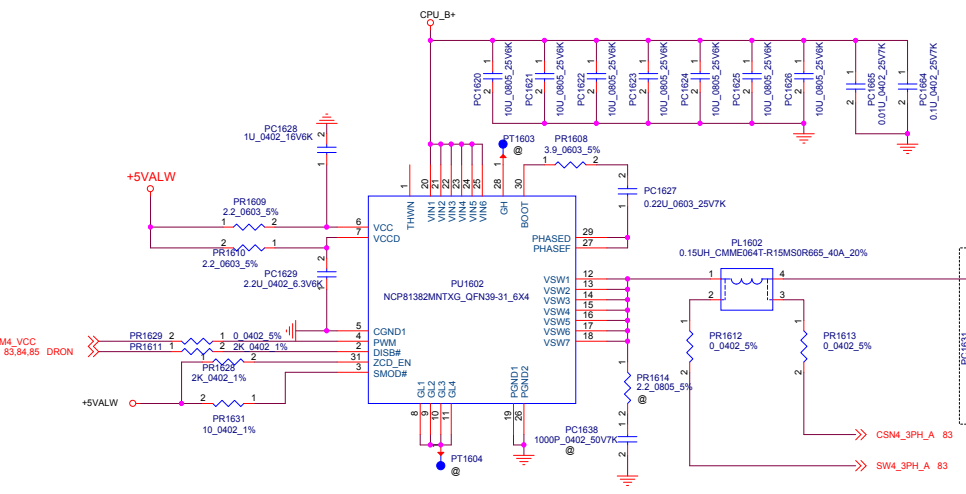


	CPU BACK				CPU TOP	
	220	22	10	1	220	47
CRB	2V	0603	0402	0201	2V	0805
pcs	3	8	28	63	2	4

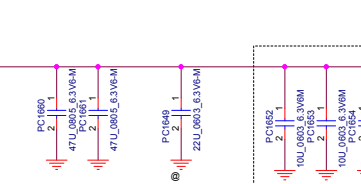
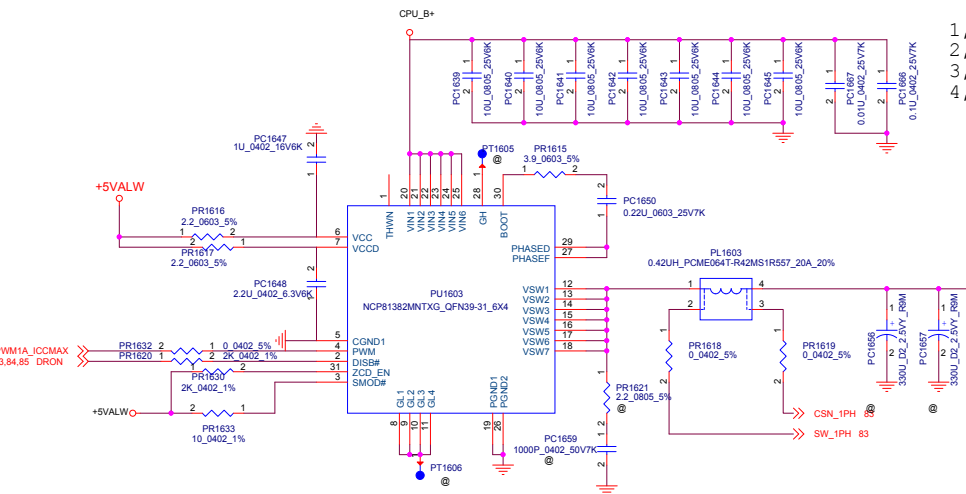
- 1,PDG 3*220uF TOP ,no Back; follow CRB/PDG;
- 2,47uF,22uF follow CRB;
- 3,Reserve 16pcs 22uF for OC;
- 4,10uF/1uF double check EE side
- 5,Total Cap double check with Vendor



Board edge caps



Board edge caps



- 1,PDG 1*220uF TOP ,47uF*2; follow CRB/PDG;
- 2,47uF,22uF follow CRB;
- 3,1uF double check EE side
- 4,Total Cap double check with Vendor

VCCSA	CPU BACK				CPU TOP	
CRB	220	47	10	1	220	22
	2V	0805	0402	0201	2V	0603
pcs	0	1	7	3	2	1

LENOVO.CRDN

Title: PWR_CPU_CORE3(NCP81382)

Size: Document Number

C: SkyLake-H

Date: Thursday, May 26, 2016

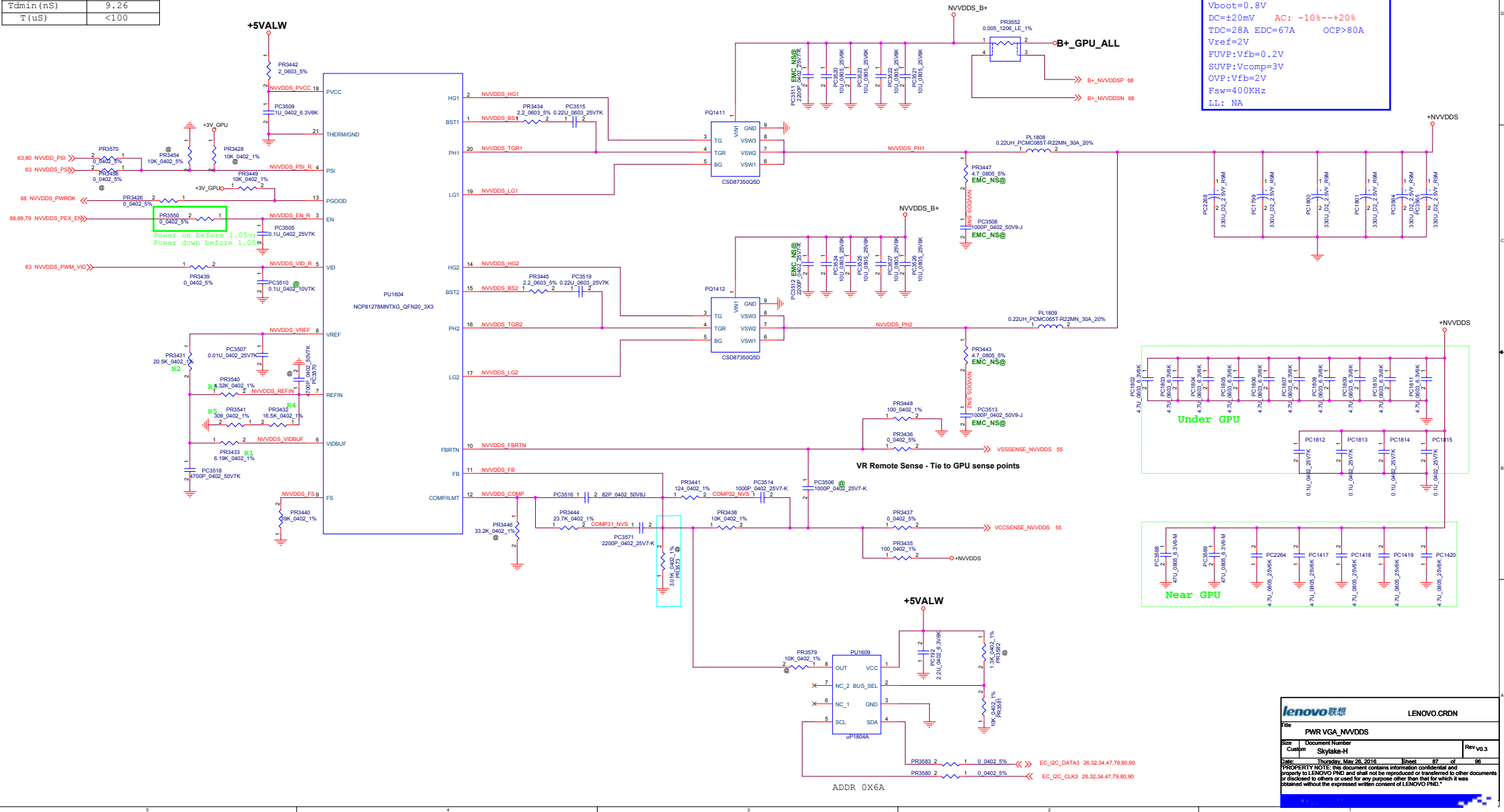
Sheet: 65 of 99

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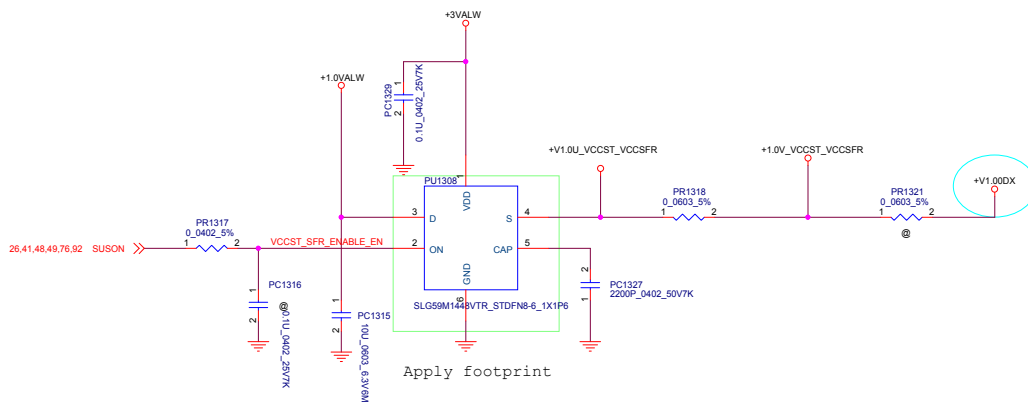
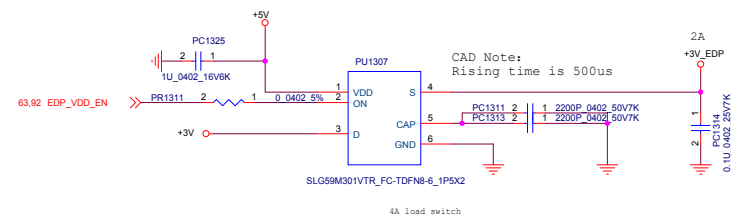
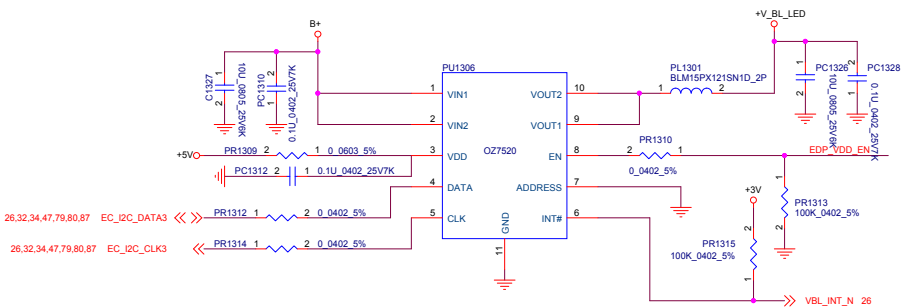
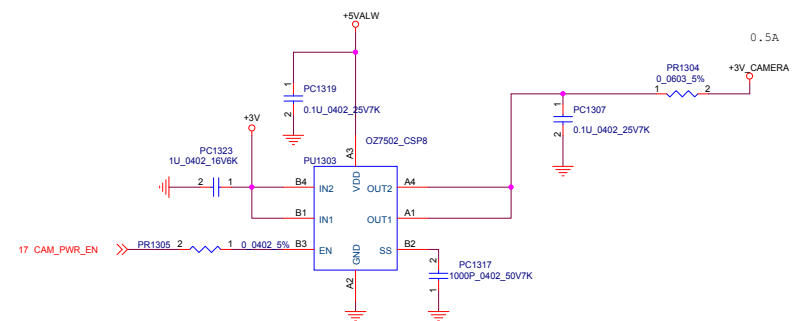
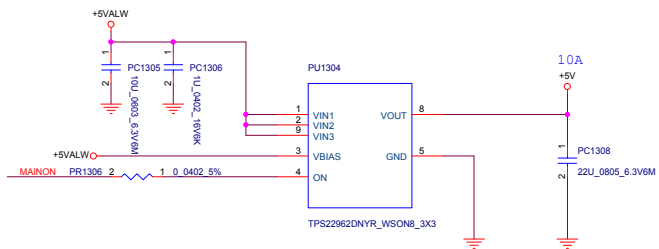
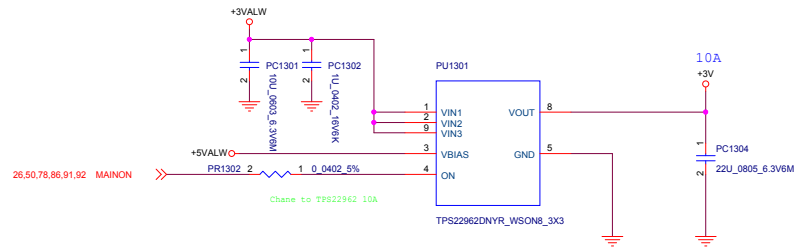
PWM-VID Specification	
	Config
Vmin(V)	0.3
Vmax(V)	1.3
Vboot(V)	0.8
Vstep(mV)	6.25
N(level)	160
Fpwm(KHz)	675
Tdmin(nS)	9.26
T(uS)	<100

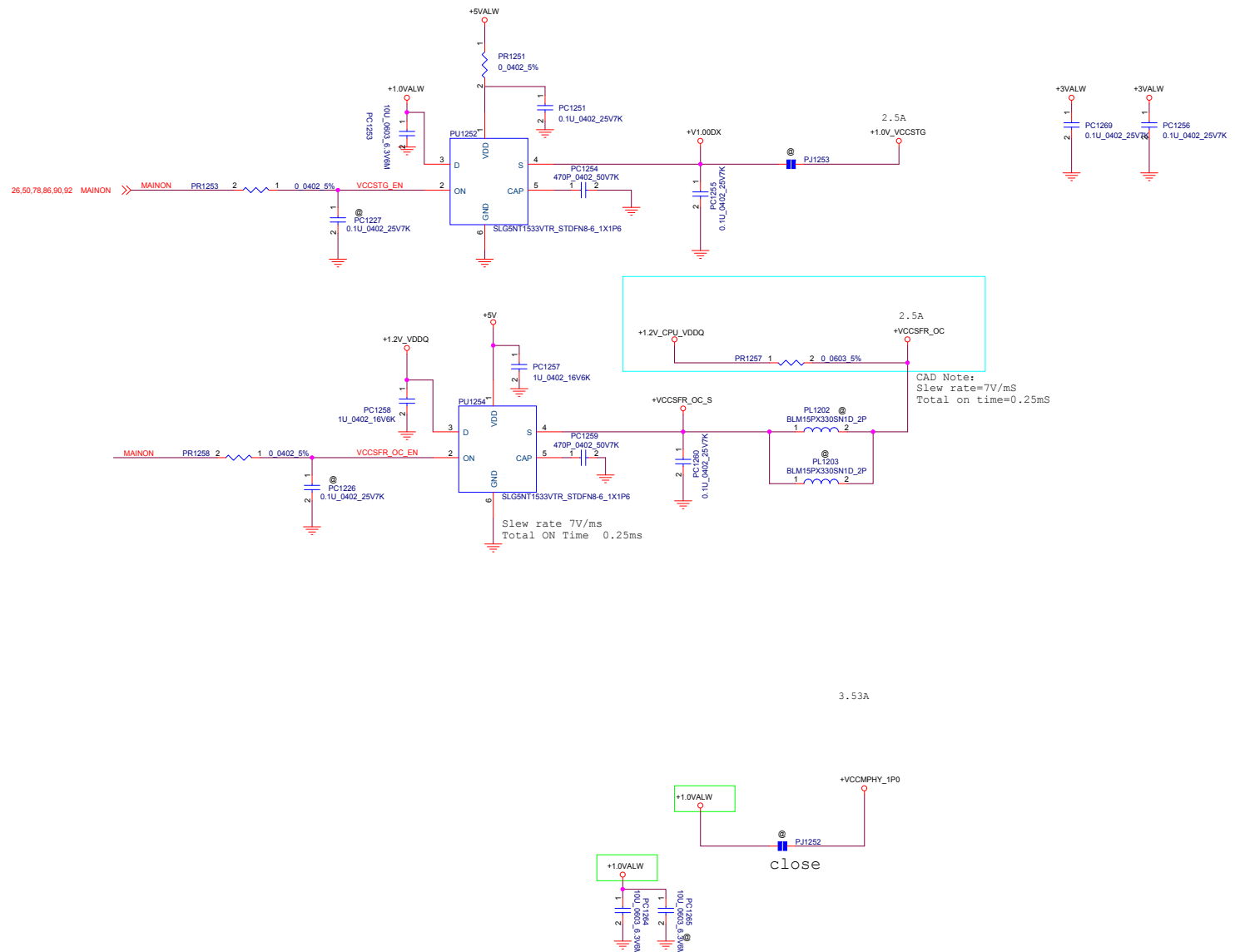
Component Value		
R1 (K Ω)	PR3433	6.19
R2 (K Ω)	PR3431	20.5
R3 (K Ω)	PR3540	4.32
R4 (K Ω)	PR3432	16.5
R5 (K Ω)	PR3541	0.309
C (nF)	PC1277	4.7

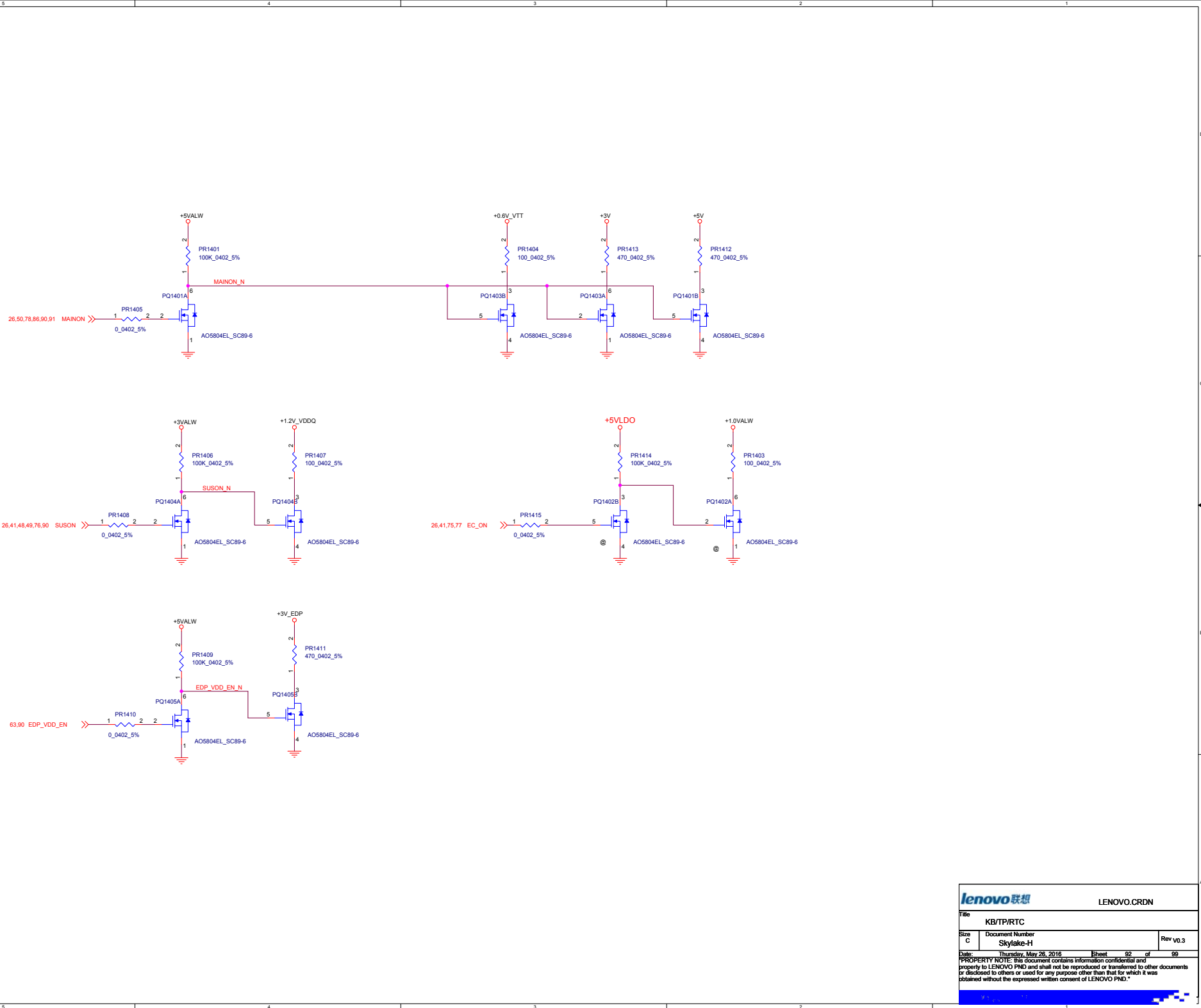


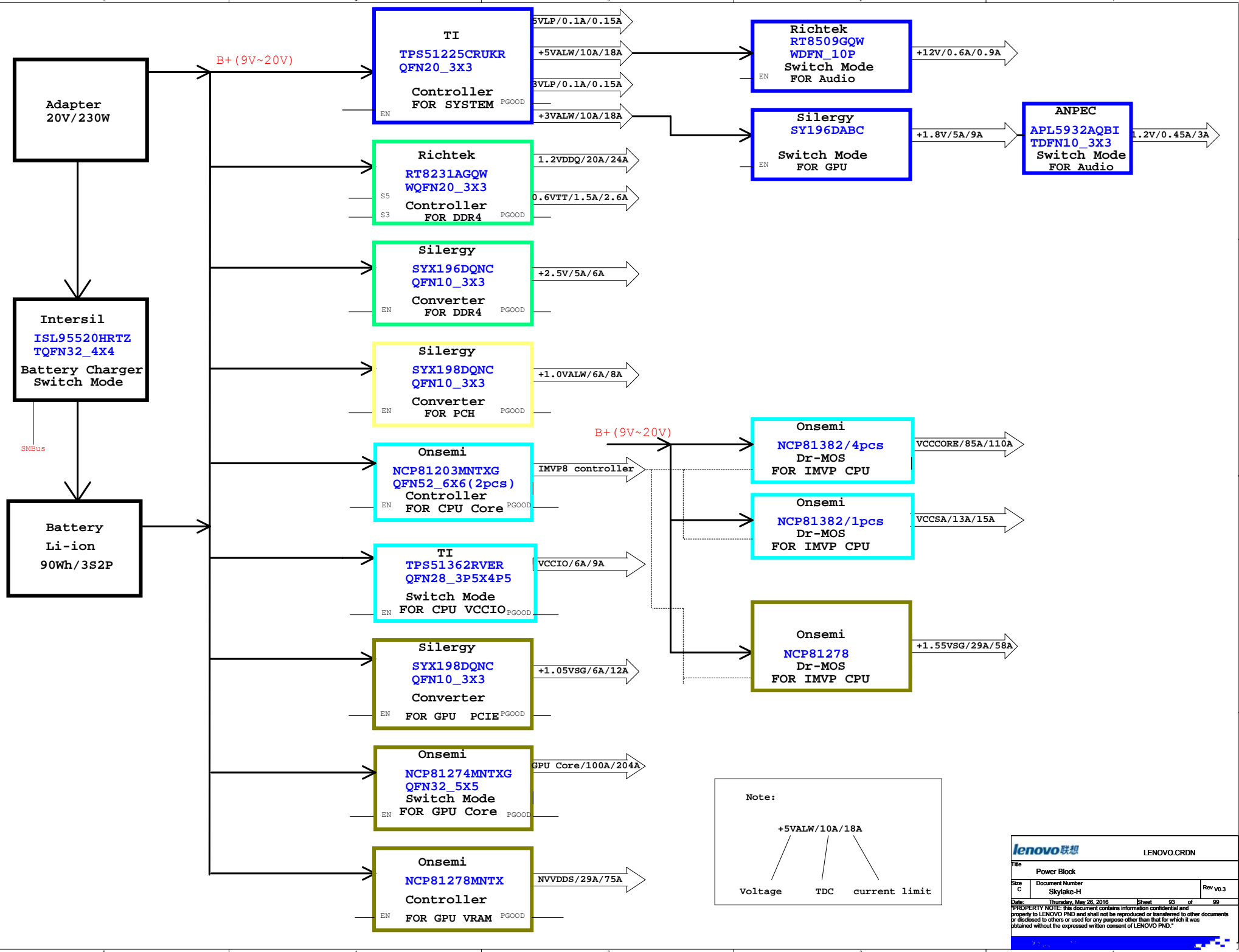
NVDDDS	GPU Side
under GPU	Near GPU
16*1uF_0402_X6S	2*10uF_4.7uF_X6S
4*10uF_0603_X6S	1*47uF_0805_X5R
	1*330uF

```
Vboot=0.8V
DC=±20mV      AC: -10%--+20%
TDC=28A  EDC=67A    OCP>80A
Vref=2V
FUVF:Vfb=0.2V
SUVP:Vcomp=3V
OVP:Vfb=2V
Fsw=400KHz
LL: NA
```









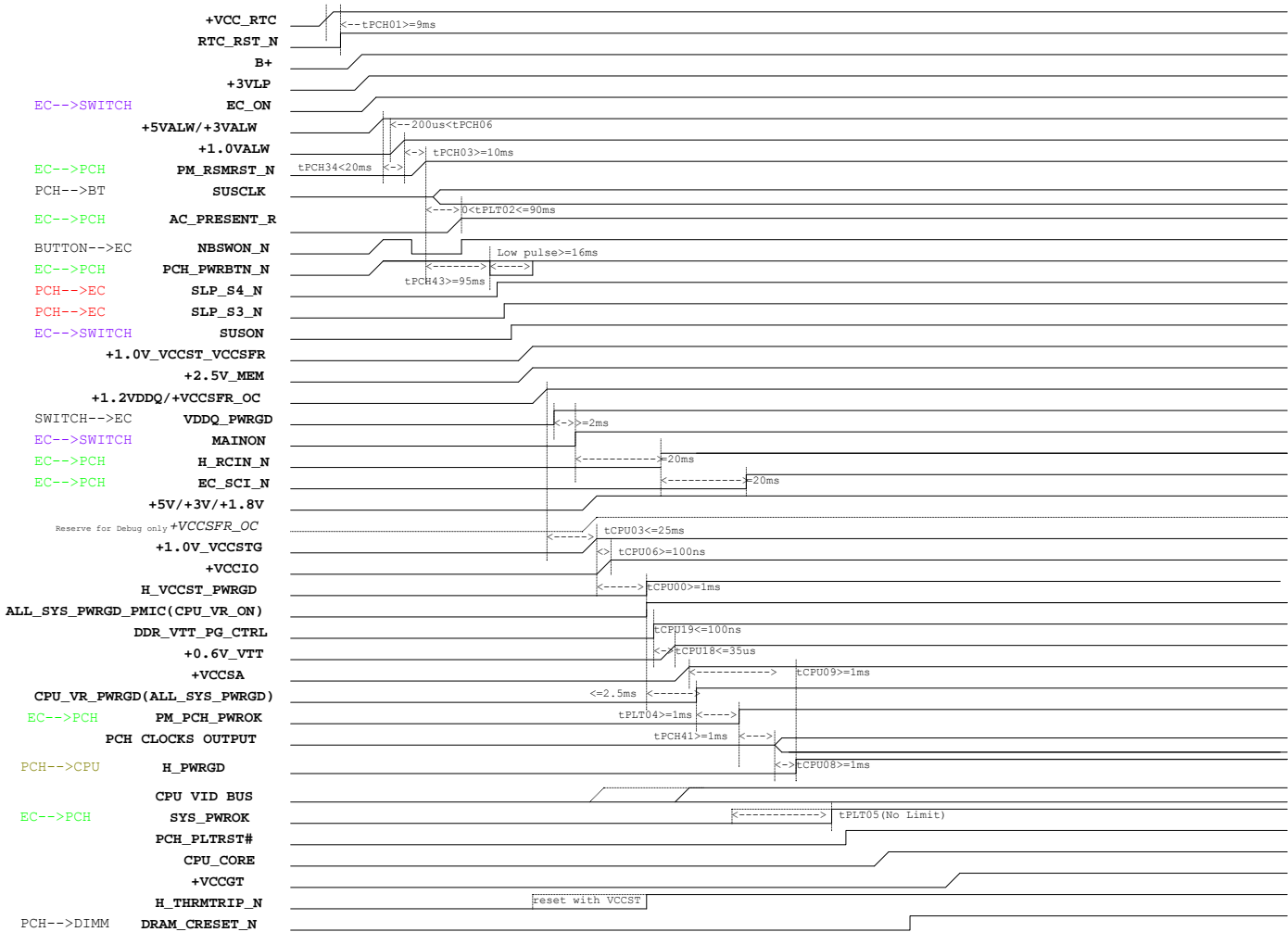


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B				B
A				A
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Power On Sequence

G3-->S5/S4-->S0 (Non-Deep Sx platform)



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Flexible I/O

HSIO PORTS	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	22	23	24	25	26
CONFIGUR	USB3.0 PORT1		USB3.0 PORT3		USB3.0 PORT6		PCIE PORT1(1X4)				PCIE PORT6		PCIE PORT7		PCIE PORT8		PCIE PORT9(1X4)			PCIE PORT13(1X4)			SATA PORT6			
DEVICE	JUSB3(IO)		JUSB2		JUSB4(IO)		U2005(Intel AR DP)				Card Reader		WLAN		LAN		PCIE SSD2			PCIE SSD1			HDD			

SMBus Table

Master EC	Slave Device					
EC_SMB_CLK0 EC_SMB_DATA0	PJ201 CHARGER 0x 0001 001x	JBAT1 BATTERY 0x 16	U2007 TPS65982 0x			
EC_SMB_CLK1 EC_SMB_DATA1	U2 PCH	U25 Thermal Sensor 0x 1001 101x	G2 dGPU 0x 9E	J9C0M1 MXM 0x 9C		
EC_I2C_CLK3 EC_I2C_DATA3	U19 LC	PJ1255 TPS22993 0x 1110 010x	PJ1256 TPS22993 0x 1110 000x	PJ1306 OZ7520 0x 2E	U2019 PI3HDX1204BZHE 0XC2	U2015 PI3DPX1203ZHE 0XF2
EC_I2C_CLK5 EC_I2C_DATA5	U23 IR sensor 0x 1000 000x	U24 IR sensor TMP006 0x 1000 001x	U27 IR sensor 0x 1000 100x	U5002(reserve) RGB sensor CS5032 0x 1C	U8 (reserve) AMP TAS5766 0x 1001 100x	

Master PCH	Slave Device						
PCH_SMB_CLK PCH_SMB_DAT	JDIMM1 SO-DIMM 0x 1010 000x	JDIMM2 SO-DIMM 0x 1010 001x	JDIMM3 SO-DIMM 0x 1010 010x	JDIMM4 SO-DIMM 0x 1010 011x	JTP1 Touch Pad 0x 2C	PJ402 uP1804A 0x 62	XDP
EC_SMB_CLK1 EC_SMB_DAT1	U5 EC						

I2C Table

Master PCH	Slave Device
PCH_I2C_CLK0 PCH_I2C_DATA0	U8 AMP TAS5766 0x 1001 100x
PCH_I2C_CLK1 PCH_I2C_DATA1	U19 LC
PCH_I2C_CLK1 PCH_I2C_DATA1	U5 EC

Flexible I/O Configuration				
I/O	High Speed Signals	Configuration	DEVICE	OCx #
Port 1	USB3 1 Capable of OTG	USB3.0	JUSB3(IO)	
Port 2	USB2 3 / SSIC 1	NC		
Port 3	USB3 3 / SSIC 2	USB3.0	JUSB2	USB_OC1_N
Port 4	USB3 4	NC		
Port 5	USB3 5	NC		
Port 6	USB3 6	USB3.0	JUSB4(IO)	

Flexible I/O Configuration				
I/O	High Speed Signals	Configuration	DEVICE	GEN
Port 7	USB3_7 / PCIE 1	AR (L0)		
Port 8	USB3_8 / PCIE 2	AR (L1)		
Port 9	USB3_9 / PCIE 3	AR (L2)	U2005 (Intel AR DP)	
Port 10	USB3_10 / PCIE 4	AR (L3)		
Port 11	PCIE 5	NC		
Port 12	PCIE 6	Card Reader	U3001	PCIE 1x Gen2
Port 13	PCIE 7	WLAN	JWLAN1	PCIE 1x Gen2
Port 14	PCIE 8	LAN	U6	PCIE1x Gen1


Flexible I/O Configuration				
I/O	High Speed Signals	Configuration	DEVICE	GEN
Port 15	SATA 0A / PCIE 9	M.2 SSD2 (L0) / SATA0		
Port 16	SATA 1A / PCIE 10	M.2 SSD2 (L1)		
Port 17	SATA 1A / PCIE 11	M.2 SSD2 (L2)	JSSD2	PCIE 4x Gen 3 /SATA Gen 3
Port 18	SATA 1A / PCIE 12	M.2 SSD2 (L3)		
Port 19	SATA 0B / PCIE 13	M.2 SSD12(L0)		
Port 20	SATA 1B / PCIE 14	M.2 SSD1 (L1)		
Port 21	SATA 2 / PCIE 15	M.2 SSD1 (L2)	JSSD1	PCIE 4 x Gen 3
Port 22	SATA 3 / PCIE 16	M.2 SSD1 (L3)		
Port 23	SATA 4 / PCIE 17	SATA HDD	U14	SATA Gen 3
Port 24	SATA 5 / PCIE 18	NC		
Port 25	SATA6 / PCIE 19	NC		
Port 26	SATA7 / PCIE 20	NC		

BOM Structure Table

BTO Item	BOM Structure
Unpop	@
CPU Option	H44e@, H42@
GPU Option	SLI@
Connector	ME@

BOARD ID Table

USB2.0 Configuration		
USB2 #	Assignment	OCx #
USB2 1	JUSB3(IO DB)	USB_OC0_N
USB2 2	JUSB2	USB_OC1_N
USB2 3	HD camera	
USB2 4	KB	
USB2 5	BT	
USB2 6	JUSB4(IO DB)	USB_OC3_N
USB2 7	NC	
USB2 8	NC	
USB2 9	Finger print	
USB2 10	NC	
USB2 11	NC	
USB2 12	NC	
USB2 13	NC	
USB2 14	NC	


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